

BURST MODE FLASH MEMORY

CMOS

128M (8M × 16) BIT

MBM29BS/FS12DH 15

DESCRIPTION

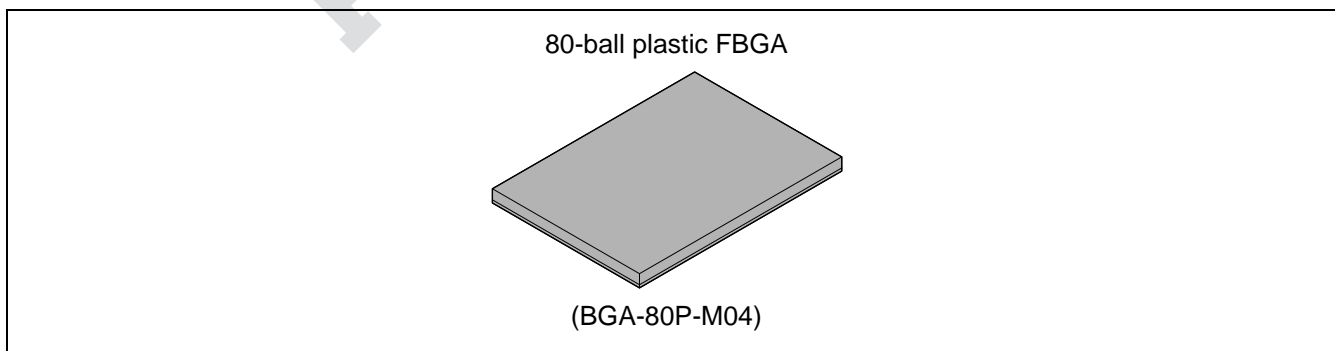
The MBM29BS/FS12DH is a 128 Mbit, 1.8 Volt-only, Burst mode and dual operation Flash memory organized as 8M words of 16 bits each. The device offered in a 80-ball FBGA package. This device is designed to be programmed in-system with the standard system 1.8 V V_{CC} supply. 12.0 V V_{PP} and 5.0 V V_{CC} are not required for write or erase operations. The device can also be programmed in standard EPROM programmers.

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PRODUCT LINE UP

Part No.		MBM29BS12DH	MBM29FS12DH
Handshaking On/Off		Non-Handshaking	Handshaking
Synchronous/Burst	Max Latency (even address in case of Handshaking) Time (ns)	71	56
	Max Burst Access Time (ns)	11	11
	Max \overline{OE} Access Time (ns)	11	11
Asynchronous	Max Address Access Time (ns)	50	50
	Max \overline{CE} Access Time (ns)	50	50
	Max \overline{OE} Access Time (ns)	11	11

PACKAGE



MBM29BS/FS12DH₁₅

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The device provides truly high performance non-volatile memory solution. The device offers fast burst access frequency of 66 MHz with initial access times of 56 ns at Handshaking mode, allowing operation of high-speed microprocessors without wait states. To eliminate bus connection the device has separate chip enable (\overline{CE}), write enable (\overline{WE}), address valid (\overline{AVD}) and output enable (\overline{OE}) controls. For burst operations, the device additionally requires Ready (RDY) at Handshaking mode, and Clock (CLK). This implementation allows easy interface with minimal glue logic to a wide range of microprocessors/ microcontrollers for high performance read operations.

The burst read mode feature gives system designers flexibility in the interface to the device. The user can preset the burst length and wrap through the same memory space. At 66 MHz, the device provides a burst access of 11 ns with a latency of 56 ns at 30 pF (Handshaking mode).

The dual operation function provides simultaneous operation by dividing the memory space into four banks. The device can improve overall system performance by allowing a host system to program or erase in one bank, then immediately and simultaneously read from another bank, with zero latency. This releases the system from waiting for the completion of program or erase operations.

The device is command set compatible with JEDEC standard E²PROMs. Commands are written to the command register using standard microprocessor write timing. Register contents serve as inputs to an internal state-machine which controls the erase and programming circuitry. Write cycles also internally latch addresses and data needed for the programming and erase operations. Reading data out of the device is similar to reading from 5.0 V and 12.0 V Flash or EPROM devices.

The device is programmed by executing the program command sequence. This will invoke the Embedded Program Algorithm which is an internal algorithm that automatically times the program pulse widths and verifies proper cell margins. Typically, each 32K words sector can be programmed and verified in about 0.3 second. Erase is accomplished by executing the erase command sequence. This will invoke the Embedded Erase Algorithm which is an internal algorithm that automatically preprograms the array if it is not already programmed before executing the erase operation. During erase, the device automatically times the erase pulse widths and verifies proper cell margins.

Any individual sector is typically erased and verified in 0.5 second. (If already preprogrammed.)

The device also features a sector erase architecture. The sector mode allows each sector to be erased and reprogrammed without affecting other sectors. The device is erased when shipped from the factory.

The Enhanced $V_{I/O}$ (V_{CCQ}) feature allows the output voltage generated on the device to be determined based on the $V_{I/O}$ level. This feature allows this device to operate in the 1.8 V I/O environment, driving and receiving signals to and from other 1.8 V devices on the same bus.

The device features single 1.8 V power supply operation for both read and write functions. Internally generated and regulated voltages are provided for the program and erase operations. The end of program or erase is detected by \overline{Data} Polling of DQ₇, by the Toggle Bit feature on DQ₆, output pin. Once the end of a program or erase cycle has been completed, the device internally resets to the read mode.

Fujitsu's Flash technology combines years of Flash memory manufacturing experience to produce the highest levels of quality, reliability and cost effectiveness. The device electrically erases all bits within a sector simultaneously via Fowler-Nordheim tunneling. The data is programmed using hot electron injection.

■ FEATURES

- **0.13 μm process technology**
- **Single 1.8 V read, program and erase (1.65 V to 1.95 V)**
- **Simultaneous Read/Write operation (Dual Bank)**
- **FlexBank™*1**
 Bank A: 16 Mbit (4 Kwords \times 8 and 32 Kwords \times 31)
 Bank B: 48 Mbit (32 Kwords \times 96)
 Bank C: 48 Mbit (32 Kwords \times 96)
 Bank D: 16 Mbit (4 Kwords \times 8 and 32 Kwords \times 31)
- **Enhanced V_{IO} ™*2 (V_{CCQ}) Feature**
 Input/ Output voltage generated on the device is determined based on the V_{IO} level
- **High Performance Burst frequency reach at 66 MHz**
 Burst access times of 11 ns @ 30 pF at industrial temperature range
 Asynchronous random access times of 50 ns (at 30 pF)
 Synchronous latency of 56 ns with 1.8 V V_{CCQ} for Handshaking mode
- **Programmable Burst Interface**
 Linear Burst: 8, 16, and 32 words with wrap-around
- **Compatible with JEDEC-standard commands**
 Uses same software commands as E²PROMs
- **Minimum 100,000 program/erase cycles**
- **Sector Erase Architecture**
 Eight 4 Kwords, two hundred fifty-four 32 Kwords sectors, eight 4 Kwords sectors.
 Any combination of sectors can be concurrently erased. Also supports full chip erase.
- **HiddenROM region**
 64 words for factory and 64 words for customer of HiddenROM, accessible through a new “HiddenROM Enable” command sequence
 Factory serialized and protected to provide a sector secure serial number (ESN)
- **Write Protect Pin (WP)**
 At V_{IL} , allows protection of “outermost” 4 \times 4 K words on low, high end or both ends of boot sectors, regardless of sector protection/unprotection status
- **Accelerate Pin (ACC)**
 At V_{ACC} , increases program performance. ; all sectors locked when $ACC = V_{IL}$
- **Embedded Erase™*2 Algorithms**
 Automatically preprograms and erases the chip or any sector
- **Embedded Program™*2 Algorithms**
 Automatically writes and verifies data at specified address
- **Data Polling and Toggle Bit feature for detection of program or erase cycle completion**
- **Ready Output (RDY)**
 In Synchronous Mode, indicates the status of the Burst read.
 In Asynchronous Mode, indicates the status of the internal program and erase function.
- **Automatic sleep mode**
 When address remain stable, the device automatically switches itself to low power mode
- **Erase Suspend/Resume**
 Suspends the erase operation to allow a read data and/or program in another sector within the same device
- **In accordance with CFI (Common Flash Interface)**
- **Hardware reset pin (\overline{RESET})**
 Hardware method to reset the device for reading array data

*1 : FlexBank™ is a trademark of Fujitsu Limited.

*2 : Embedded Erase™, Embedded Program™ and Enhanced V_{IO} ™ are trademarks of Advanced Micro Devices, Inc.

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MBM29BS/FS12DH₁₅

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- **Sector Protection**

- Persistent sector protection

- Password sector protection

- ACC protects all sectors

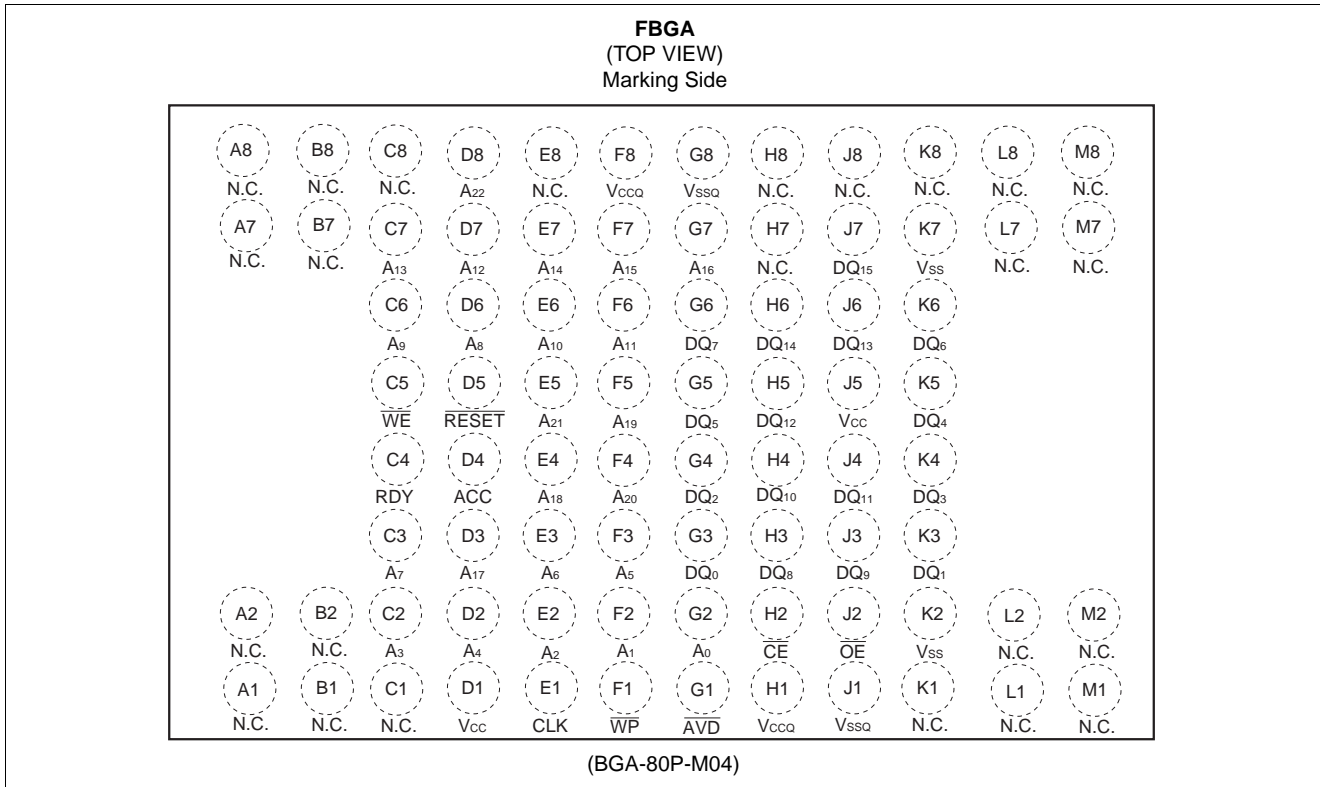
- \overline{WP} protects the outermost 4 x 4 K words on both ends of boot sectors, regardless of sector protection / unprotection status.

- **Handshaking feature available (MBM29FS12DH)**

- Provides host system with minimum possible latency by monitoring RDY

- **CMOS compatible inputs, CMOS compatible outputs**

■ PIN ASSIGNMENT



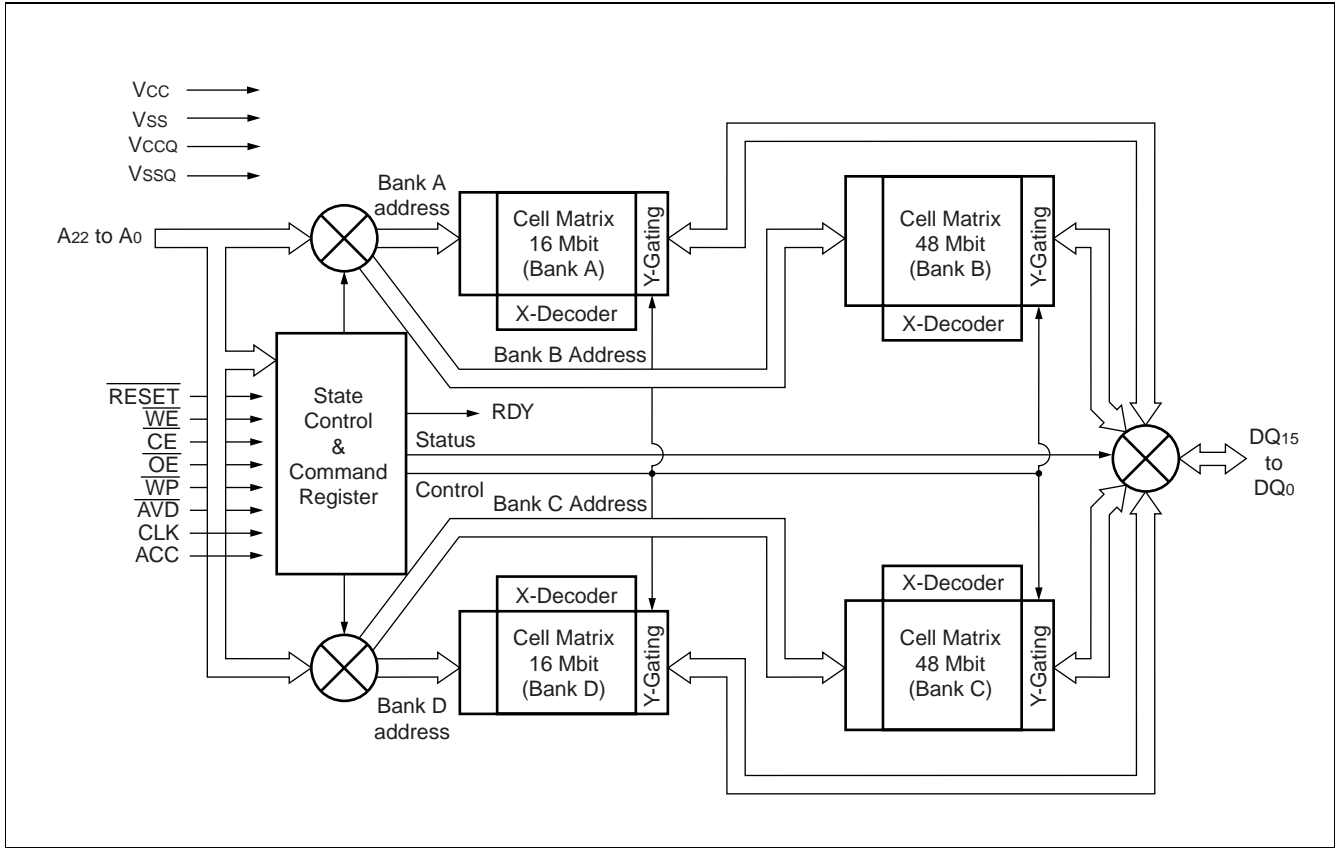
■ PIN DESCRIPTIONS

MBM29BS/FS12DH Pin Configuration Table

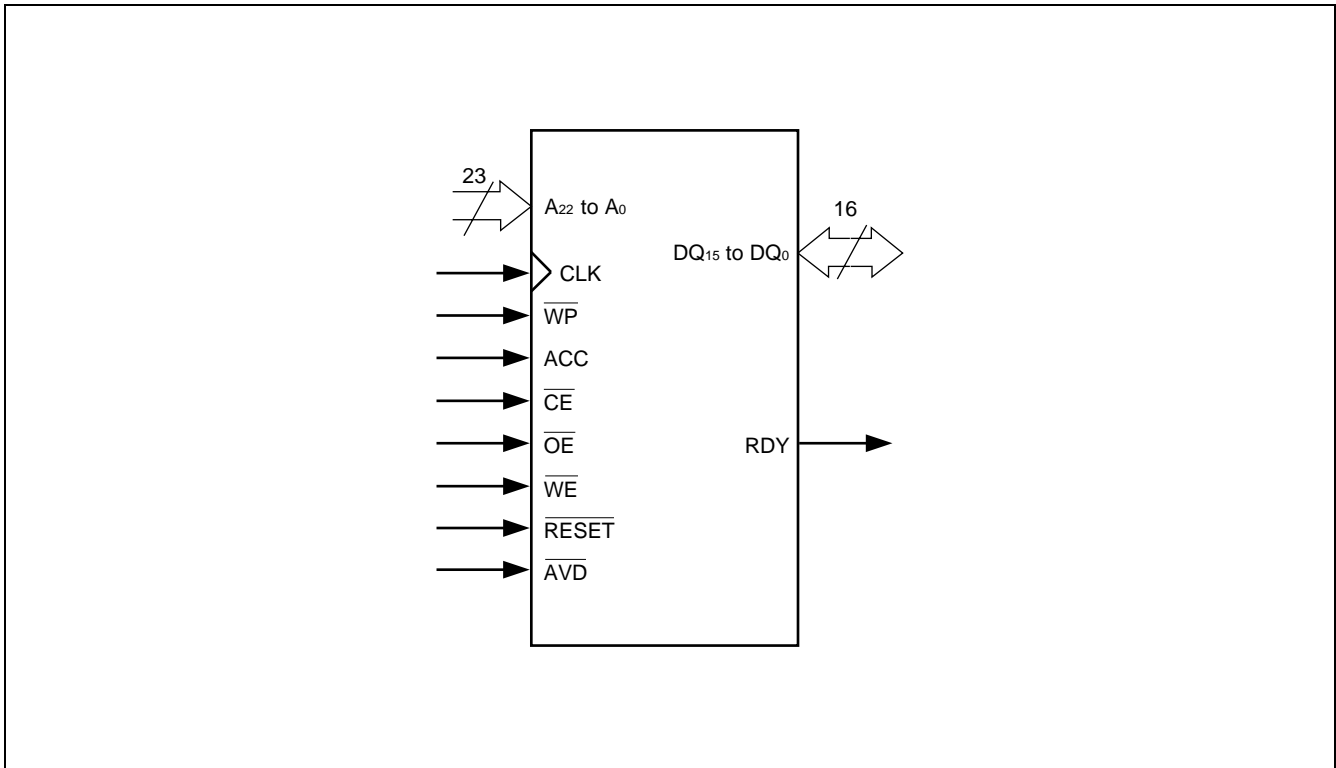
Pin name	Function
A ₂₂ to A ₀	Address Inputs
DQ ₁₅ to DQ ₀	Data Inputs/Outputs
CLK	CLK Input
\overline{CE}	Chip Enable
\overline{OE}	Output Enable
\overline{WE}	Write Enable
\overline{AVD}	Address Valid Input
RDY	Ready Output. (In asynchronous mode, RY/ \overline{BY} Output)
\overline{RESET}	Hardware Reset
\overline{WP}	Hardware Write Protection
ACC	Program Acceleration
N.C.	Pin Not Connected Internally
V _{SS}	Device Ground
V _{CC}	Device Power Supply
V _{SSQ}	Input & Output Buffer Ground
V _{CCQ}	Input & Output Buffer Power Supply

MBM29BS/FS12DH₁₅

■ BLOCK DIAGRAM

















■ LOGIC SYMBOL



■ DEVICE BUS OPERATION

MBM29BS/FS12DH User Bus Operations Table

Operation	\overline{CE}	\overline{OE}	\overline{WE}	\overline{WP}	ACC	A ₂₂ to A ₀	DQ ₁₅ to DQ ₀	CLK	\overline{AVD}	\overline{RESET}
Asynchronous Mode Operations (Default)										
Asynchronous Read Addresses Latched * ¹	L	L	H	X	X	Addr In	D _{OUT}	X	L	H
Standby	H	X	X	X	X	X	High-Z	X	X	H
Output Disable	L	H	H	X	X	X	High-Z	X	X	H
Write - \overline{WE} address latched * ³	L	H	L	X* ²	H* ²	Addr In	D _{IN}	X	L	H
Write - \overline{AVD} address latched * ³	L	H		X* ²	H* ²	Addr In	D _{IN}	X		H
Boot Block Sector Write Protection * ²	X	X	X	L	X	X	X	X	X	H
All Sector Write Protection * ²	X	X	X	X	L	X	X	X	X	H
RESET	X	X	X	X	X	X	High-Z	X	X	L
Synchronous Mode Operations (need to set the configuration register)										
Load Starting Burst Address (CLK latch) * ¹	L	X	H	X	X	Addr In	X			H
Advance Burst to next address with appropriate Data presented on the Data Bus * ¹	L	L	H	X	X	X	D _{OUT}		H	H
Terminate current Burst read cycle	H	X	H	X	X	X	High-Z		X	H
Terminate current Burst read via RESET	X	X	H	X	X	X	High-Z	X	X	L
Terminate current Burst read cycle and start new Burst read cycle	L	X	H	X	X	Addr In	D _{OUT}			H
Burst Suspend	L	H	H	X	X	X	High-Z	X	H	H
Standby	H	X	X	X	X	X	High-Z	X	X	H
Output Disable	L	H	H	X	X	X	High-Z	X	X	H
Write - \overline{WE} address latched * ⁴	L	H	L	X* ²	H* ²	Addr In	D _{IN}	H/L	L	H
Write - CLK address latched * ⁴	L	H		X* ²	H* ²	Addr In	D _{IN}			H
Write - \overline{AVD} address latched * ⁴	L	H		X* ²	H* ²	Addr In	D _{IN}	H/L		H
Boot Block Sector Write Protection * ²	X	X	X	L	X	X	X	X	X	H
All Sector Write Protection * ²	X	X	X	X	L	X	X	X	X	H
RESET	X	X	X	X	X	X	High-Z	X	X	L

Legend: L = V_{IL}, H = V_{IH}, X = V_{IL} or V_{IH},  = Pulse input. See “■DC CHARACTERISTICS” for voltage levels.

*¹ : \overline{WE} can be V_{IL} if \overline{OE} is V_{IL}, \overline{OE} at V_{IH} initiates the write operations.

*² : At \overline{WP} =V_{IL}, SA0-SA3 and SA266-SA269 are protected. At ACC=V_{IL}, all sectors are protected.

*³ : Write Operation: at asynchronous mode, addresses are latched on the last falling edge of \overline{WE} pulse while \overline{AVD} is held low or rising edge of \overline{AVD} pulse whichever comes first. Data is latched on the 1st rising edge of \overline{WE} .

*⁴ : Write Operation: at synchronous mode, addresses are latched on the falling edge of \overline{WE} while \overline{AVD} is held low or active edge of CLK while \overline{AVD} is held low whichever happens first. Data is latched on the 1st rising edge of \overline{WE} .

MBM29BS/FS12DH₁₅

MBM29BS/FS12DH Command Definitions Table

Command Sequence	Bus Write Cycles Req'd	First Bus Write Cycle		Second Write Cycle		Third Write Cycle		Fourth Write Cycle		Fifth Write Cycle		Sixth Write Cycle		Seventh Write Cycle	
		Addr.	Data	Addr.	Data	Addr.	Data	Addr.	Data	Addr.	Data	Addr.	Data	Addr.	Data
Read / Reset	1	XXXh	F0h	RA	RD	—	—	—	—	—	—	—	—	—	—
Read / Reset	3	555h	AAh	2AAh	55h	555h	F0h	RA	RD	—	—	—	—	—	—
Autoselect	3	555h	AAh	2AAh	55h	(BA) 555h	90h	—	—	—	—	—	—	—	—
Program	4	555h	AAh	2AAh	55h	555h	A0h	PA	PD	—	—	—	—	—	—
Chip Erase	6	555h	AAh	2AAh	55h	555h	80h	555h	AAh	2AAh	55h	555h	10h	—	—
Sector Erase	6	555h	AAh	2AAh	55h	555h	80h	555h	AAh	2AAh	55h	SA	30h	—	—
Erase Suspend	1	BA	B0h	—	—	—	—	—	—	—	—	—	—	—	—
Erase Resume	1	BA	30h	—	—	—	—	—	—	—	—	—	—	—	—
Set to Fast Mode	3	555h	AAh	2AAh	55h	555h	20h	—	—	—	—	—	—	—	—
Fast Program	2	XXXh	A0	PA	PD	—	—	—	—	—	—	—	—	—	—
Reset from Fast Mode *1	2	BA	90h	XXXh	F0h*3	—	—	—	—	—	—	—	—	—	—
Set Burst Mode Configuration Register	3	555h	AAh	2AAh	55h	(CR) 555h	C0h	—	—	—	—	—	—	—	—
Query	1	(BA) 55h	98h	—	—	—	—	—	—	—	—	—	—	—	—
HiddenROM Entry	3	555h	AAh	2AAh	55h	555h	88h	—	—	—	—	—	—	—	—
HiddenROM Program*2	4	555h	AAh	2AAh	55h	555h	A0h	(HRA) PA	PD	—	—	—	—	—	—
HiddenROM Exit *2	4	555h	AAh	2AAh	55h	(HRBA) 555h	90h	XXXh	00h	—	—	—	—	—	—
HiddenROM Protect *2	6	555h	AAh	2AAh	55h	555h	60h	OPBP	68h	OPBP	48h	XXXh	RD (0)	—	—
Password Program	4	555h	AAh	2AAh	55h	555h	38h	XX0h	PD0	—	—	—	—	—	—
		555h	AAh	2AAh	55h	555h	38h	XX1h	PD1	—	—	—	—	—	—
		555h	AAh	2AAh	55h	555h	38h	XX2h	PD2	—	—	—	—	—	—
		555h	AAh	2AAh	55h	555h	38h	XX3h	PD3	—	—	—	—	—	—
Password Unlock	7	555h	AAh	2AAh	55h	555h	28h	XX0h	PD0	XX1h	PD1	XX2h	PD2	XX3h	PD3

(Continued)

(Continued)

Command Sequence	Bus Write Cycles Req'd	First Bus Write Cycle		Second Write Cycle		Third Write Cycle		Fourth Write Cycle		Fifth Write Cycle		Sixth Write Cycle		Seventh Write Cycle	
		Addr.	Data	Addr.	Data	Addr.	Data	Addr.	Data	Addr.	Data	Addr.	Data	Addr.	Data
Password Verify	4	555h	AAh	2AAh	55h	555h	C8h	PWA	PWD	—	—	—	—	—	—
Password Mode Locking Bit Program	6	555h	AAh	2AAh	55h	555h	60h	PL	68h	PL	48h	XXh	RD (0)	—	—
Persistent Protection Mode Locking Bit Program	6	555h	AAh	2AAh	55h	555h	60h	SPML	68h	SPML	48h	XXh	RD (0)	—	—
PPB Program	6	555h	AAh	2AAh	55h	555h	60h	SGA+ WP	68h	SGA+ WP	48h	XXh	RD (0)	—	—
PPB Verify	4	555h	AAh	2AAh	55h	(BA) 555h	90h	SGA+ WP	RD (0)	—	—	—	—	—	—
All PPB Erase	6	555h	AAh	2AAh	55h	555h	60h	WPE	60h	WPE	40h	XXh	RD (0)	—	—
PPB Lock Bit Set	6	555h	AAh	2AAh	55h	555h	78h	—	—	—	—	—	—	—	—
PPB Lock Bit Verify	4	555h	AAh	2AAh	55h	555h	58h	SA	RD (1)	—	—	—	—	—	—
DPB Write	4	555h	AAh	2AAh	55h	555h	48h	SA	X1h	—	—	—	—	—	—
DPB Erase	4	555h	AAh	2AAh	55h	555h	48h	SA	X0h	—	—	—	—	—	—
DPB Verify	4	555h	AAh	2AAh	55h	555h	58h	SA	RD (0)	—	—	—	—	—	—

Legend:

- RA = Address of the memory location to be read.
- PA = Address of the memory location to be programmed. Addresses latch on the rising edge of the \overline{AVD} pulse or active edge of CLK while $\overline{AVD} = V_{IL}$ whichever comes first or falling edge of write pulse while $\overline{AVD} = V_{IL}$.
- SA = Address of the sector to be erased. The combination of A₂₂, A₂₁, A₂₀, A₁₉, A₁₈, A₁₇, A₁₆, A₁₅, A₁₄, A₁₃, and A₁₂ will uniquely select any sector.
- BA = Bank Address. Address settled by A₂₂, A₂₁, A₂₀ will select Bank A, Bank B, Bank C and Bank D.
- RD = Data read from location RA during read operation.
- PD = Data to be programmed at location PA. Data latches on the rising edge of write pulse.
- SGA = Sector group address to be protected.
- SD = Sector group protection verify data.
Output 01h at protected sector group addresses and output 00h at unprotected sector group addresses.
- HRA = Address of the HiddenROM area 000000h to 00007Fh
- HRBA = Bank Address of the HiddenROM area (A₂₂ = A₂₁ = A₂₀ = V_{IL})
- RD (0) = Read Data bit. If programmed, DQ₀ = 1, if erase, DQ₀ = 0
- RD (1) = Read Data bit. If programmed, DQ₁ = 1, if erase, DQ₁ = 0
- OPBP = (A₇, A₆, A₅, A₄, A₃, A₂, A₁, A₀) is (0, 0, 0, 1, 1, 0, 1, 0)
- PWA/PWD = Password Address/Password Data
- PL = (A₇, A₆, A₅, A₄, A₃, A₂, A₁, A₀) is (0, 0, 0, 0, 1, 0, 1, 0)
- SPML = (A₇, A₆, A₅, A₄, A₃, A₂, A₁, A₀) is (0, 0, 0, 1, 0, 0, 1, 0)
- WP = (A₇, A₆, A₅, A₄, A₃, A₂, A₁, A₀) is (0, 0, 0, 0, 0, 0, 1, 0)
- WPE = (A₇, A₆, A₅, A₄, A₃, A₂, A₁, A₀) is (0, 1, 0, 0, 0, 0, 1, 0)
- CR = Configuration Register address bits A₁₉ to A₁₂.

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MBM29BS/FS12DH₁₅

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*1: This command is valid during Fast Mode.

*2: This command is valid during HiddenROM mode.

*3: The data "00h" is also acceptable.

Notes : • Address bits A₂₂ to A₁₁ = X = "H" or "L" for all address commands except for PA, SA, BA, SGA, OPBP, PWA, PL, SPML, WP, WPE.

- Bus operations are defined in "MBM29BS/FS12DH User Bus Operations Table".
- Both Read/Reset commands are functionally equivalent, resetting the device to the read mode.
- Command Combinations not described in "MBM29BS/FS12DH Command Definitions Table" are illegal.

MBM29BS/FS12DH Sector Protection Verify Autoselect Codes Table

Type	A ₂₂ to A ₁₂	A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀	Code (HEX)
Manufacture's Code	BA	V _{IL}	V _{IL}	V _{IL}	V _{IL}	V _{IL}	V _{IL}	V _{IL}	V _{IL}	04h
Device Code	BA	V _{IL}	V _{IL}	V _{IL}	V _{IL}	V _{IL}	V _{IL}	V _{IL}	V _{IH}	227Eh
Extended Device Code*2	BA	V _{IL}	V _{IL}	V _{IL}	V _{IL}	V _{IH}	V _{IH}	V _{IH}	V _{IL}	2218h
	BA	V _{IL}	V _{IL}	V _{IL}	V _{IL}	V _{IH}	V _{IH}	V _{IH}	V _{IH}	2200h
Sector Group Protection	Sector Group Addresses	V _{IL}	V _{IL}	V _{IL}	V _{IL}	V _{IL}	V _{IL}	V _{IH}	V _{IL}	01h*1
Indicator Bits	BA	V _{IL}	V _{IL}	V _{IL}	V _{IL}	V _{IL}	V _{IL}	V _{IH}	V _{IH}	DQ ₇ - Factory Lock Bit 1 = Locked, 0 = Not Locked DQ ₆ - Customer Lock Bit 1 = Locked, 0 = Not Locked DQ ₅ - Handshake Bit 1 = Handshake (FS12), 0 = non-Handshake(BS12)

*1 : Outputs 01h at protected sector group addresses and outputs 00h at unprotected sector group addresses.

*2 : A read cycle at address (BA) 01h outputs device code. When 227Eh is output, it indicates that two additional codes, called Extended Device Codes, will be required. Therefore the system may continue reading out these Extended Device Codes at the address of (BA) 0Eh, as well as at (BA) 0Fh.

Extended Autoselect Code Table

Type	Code	DQ ₁₅	DQ ₁₄	DQ ₁₃	DQ ₁₂	DQ ₁₁	DQ ₁₀	DQ ₉	DQ ₈	DQ ₇	DQ ₆	DQ ₅	DQ ₄	DQ ₃	DQ ₂	DQ ₁	DQ ₀
Manufacture's Code	04h	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0
Device Code	227Eh	0	0	1	0	0	0	1	0	0	1	1	1	1	1	1	0
Extended Device Code	2218h	0	0	1	0	0	0	1	0	0	0	0	1	1	0	0	0
	2200h	0	0	1	0	0	0	1	0	0	0	0	0	0	0	0	0
Sector Group Protection	00h	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	01h	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1

■ FLEXIBLE SECTOR-ERASE ARCHITECTURE

Sector Address Table (Bank A)

Bank	Sector	Sector Address										Sector Size (Kwords)	(× 16) Address Range		
		Bank Address			A ₁₉	A ₁₈	A ₁₇	A ₁₆	A ₁₅	A ₁₄	A ₁₃			A ₁₂	
		A ₂₂	A ₂₁	A ₂₀											
Bank A	SA0	0	0	0	0	0	0	0	0	0	0	0	4	000000h to 000FFFh	
	SA1	0	0	0	0	0	0	0	0	0	0	1	4	001000h to 001FFFh	
	SA2	0	0	0	0	0	0	0	0	0	0	1	0	4	002000h to 002FFFh
	SA3	0	0	0	0	0	0	0	0	0	0	1	1	4	003000h to 003FFFh
	SA4	0	0	0	0	0	0	0	0	0	1	0	0	4	004000h to 004FFFh
	SA5	0	0	0	0	0	0	0	0	0	1	0	1	4	005000h to 005FFFh
	SA6	0	0	0	0	0	0	0	0	0	1	1	0	4	006000h to 006FFFh
	SA7	0	0	0	0	0	0	0	0	0	1	1	1	4	007000h to 007FFFh
	SA8	0	0	0	0	0	0	0	0	1	X	X	X	32	008000h to 00FFFFh
	SA9	0	0	0	0	0	0	0	1	0	X	X	X	32	010000h to 017FFFh
	SA10	0	0	0	0	0	0	0	1	1	X	X	X	32	018000h to 01FFFFh
	SA11	0	0	0	0	0	0	1	0	0	X	X	X	32	020000h to 027FFFh
	SA12	0	0	0	0	0	0	1	0	1	X	X	X	32	028000h to 02FFFFh
	SA13	0	0	0	0	0	0	1	1	0	X	X	X	32	030000h to 037FFFh
	SA14	0	0	0	0	0	0	1	1	1	X	X	X	32	038000h to 03FFFFh
	SA15	0	0	0	0	0	1	0	0	0	X	X	X	32	040000h to 047FFFh
	SA16	0	0	0	0	0	1	0	0	1	X	X	X	32	048000h to 04FFFFh
	SA17	0	0	0	0	0	1	0	1	0	X	X	X	32	050000h to 057FFFh
	SA18	0	0	0	0	0	1	0	1	1	X	X	X	32	058000h to 05FFFFh
	SA19	0	0	0	0	0	1	1	0	0	X	X	X	32	060000h to 06FFFFh
	SA20	0	0	0	0	0	1	1	0	1	X	X	X	32	068000h to 06FFFFh
	SA21	0	0	0	0	0	1	1	1	0	X	X	X	32	070000h to 077FFFh
	SA22	0	0	0	0	0	1	1	1	1	X	X	X	32	078000h to 07FFFFh
	SA23	0	0	0	0	1	0	0	0	0	X	X	X	32	080000h to 087FFFh
	SA24	0	0	0	0	1	0	0	0	1	X	X	X	32	088000h to 08FFFFh
	SA25	0	0	0	0	1	0	0	1	0	X	X	X	32	090000h to 097FFFh
	SA26	0	0	0	0	1	0	0	1	1	X	X	X	32	098000h to 09FFFFh
	SA27	0	0	0	0	1	0	1	0	0	X	X	X	32	0A0000h to 0A7FFFh
	SA28	0	0	0	0	1	0	1	0	1	X	X	X	32	0A8000h to 0AFFFFh
	SA29	0	0	0	0	1	0	1	1	0	X	X	X	32	0B0000h to 0B7FFFh
	SA30	0	0	0	0	1	0	1	1	1	X	X	X	32	0B8000h to 0BFFFFh
	SA31	0	0	0	0	1	1	0	0	0	X	X	X	32	0C0000h to 0C7FFFh
	SA32	0	0	0	0	1	1	0	0	1	X	X	X	32	0C8000h to 0CFFFFh
	SA33	0	0	0	0	1	1	0	1	0	X	X	X	32	0D0000h to 0D7FFFh
	SA34	0	0	0	0	1	1	0	1	1	X	X	X	32	0D8000h to 0DFFFFh
	SA35	0	0	0	0	1	1	1	0	0	X	X	X	32	0E0000h to 0E7FFFh
	SA36	0	0	0	0	1	1	1	0	1	X	X	X	32	0E8000h to 0EFFFFh
	SA37	0	0	0	0	1	1	1	1	0	X	X	X	32	0F0000h to 0F7FFFh
SA38	0	0	0	0	1	1	1	1	1	X	X	X	32	0F8000h to 0FFFFFh	

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Sector Address Table (Bank B)

Bank	Sector	Sector Address											Sector Size (Kwords)	(× 16) Address Range
		Bank Address			A ₁₉	A ₁₈	A ₁₇	A ₁₆	A ₁₅	A ₁₄	A ₁₃	A ₁₂		
		A ₂₂	A ₂₁	A ₂₀										
Bank B	SA39	0	0	1	0	0	0	0	0	X	X	X	32	100000h to 107FFFFh
	SA40	0	0	1	0	0	0	0	1	X	X	X	32	108000h to 10FFFFFFh
	SA41	0	0	1	0	0	0	1	0	X	X	X	32	110000h to 117FFFFh
	SA42	0	0	1	0	0	0	1	1	X	X	X	32	118000h to 11FFFFFFh
	SA43	0	0	1	0	0	1	0	0	X	X	X	32	120000h to 127FFFFh
	SA44	0	0	1	0	0	1	0	1	X	X	X	32	128000h to 12FFFFFFh
	SA45	0	0	1	0	0	1	1	0	X	X	X	32	130000h to 137FFFFh
	SA46	0	0	1	0	0	1	1	1	X	X	X	32	138000h to 13FFFFFFh
	SA47	0	0	1	0	1	0	0	0	X	X	X	32	140000h to 147FFFFh
	SA48	0	0	1	0	1	0	0	1	X	X	X	32	148000h to 14FFFFFFh
	SA49	0	0	1	0	1	0	1	0	X	X	X	32	150000h to 157FFFFh
	SA50	0	0	1	0	1	0	1	1	X	X	X	32	158000h to 15FFFFFFh
	SA51	0	0	1	0	1	1	0	0	X	X	X	32	160000h to 167FFFFh
	SA52	0	0	1	0	1	1	0	1	X	X	X	32	168000h to 16FFFFFFh
	SA53	0	0	1	0	1	1	1	0	X	X	X	32	170000h to 177FFFFh
	SA54	0	0	1	0	1	1	1	1	X	X	X	32	178000h to 17FFFFFFh
	SA55	0	0	1	1	0	0	0	0	X	X	X	32	180000h to 187FFFFh
	SA56	0	0	1	1	0	0	0	1	X	X	X	32	188000h to 18FFFFFFh
	SA57	0	0	1	1	0	0	1	0	X	X	X	32	190000h to 197FFFFh
	SA58	0	0	1	1	0	0	1	1	X	X	X	32	198000h to 19FFFFFFh
	SA59	0	0	1	1	0	1	0	0	X	X	X	32	1A0000h to 1A7FFFFh
	SA60	0	0	1	1	0	1	0	1	X	X	X	32	1A8000h to 1AFFFFFFh
	SA61	0	0	1	1	0	1	1	0	X	X	X	32	1B0000h to 1B7FFFFh
	SA62	0	0	1	1	0	1	1	1	X	X	X	32	1B8000h to 1BFFFFFFh
	SA63	0	0	1	1	1	0	0	0	X	X	X	32	1C0000h to 1C7FFFFh
	SA64	0	0	1	1	1	0	0	1	X	X	X	32	1C8000h to 1CFFFFFFh
	SA65	0	0	1	1	1	0	1	0	X	X	X	32	1D0000h to 1D7FFFFh
	SA66	0	0	1	1	1	0	1	1	X	X	X	32	1D8000h to 1DFFFFFFh
	SA67	0	0	1	1	1	1	0	0	X	X	X	32	1E0000h to 1E7FFFFh
	SA68	0	0	1	1	1	1	0	1	X	X	X	32	1E8000h to 1EFFFFFFh
SA69	0	0	1	1	1	1	1	0	X	X	X	32	1F0000h to 1F7FFFFh	
SA70	0	0	1	1	1	1	1	1	X	X	X	32	1F8000h to 1FFFFFFh	
SA71	0	1	0	0	0	0	0	0	X	X	X	32	200000h to 207FFFFh	
SA72	0	1	0	0	0	0	0	1	X	X	X	32	208000h to 20FFFFFFh	
SA73	0	1	0	0	0	0	1	0	X	X	X	32	210000h to 217FFFFh	
SA74	0	1	0	0	0	0	1	1	X	X	X	32	218000h to 21FFFFFFh	
SA75	0	1	0	0	0	1	0	0	X	X	X	32	220000h to 227FFFFh	
SA76	0	1	0	0	0	1	0	1	X	X	X	32	228000h to 22FFFFFFh	
SA77	0	1	0	0	0	1	1	0	X	X	X	32	230000h to 237FFFFh	

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Bank	Sector	Sector Address											Sector Size (Kwords)	(× 16) Address Range
		Bank Address			A ₁₉	A ₁₈	A ₁₇	A ₁₆	A ₁₅	A ₁₄	A ₁₃	A ₁₂		
		A ₂₂	A ₂₁	A ₂₀										
Bank B	SA78	0	1	0	0	0	1	1	1	X	X	X	32	238000h to 23FFFFh
	SA79	0	1	0	0	1	0	0	0	X	X	X	32	240000h to 247FFFh
	SA80	0	1	0	0	1	0	0	1	X	X	X	32	248000h to 24FFFFh
	SA81	0	1	0	0	1	0	1	0	X	X	X	32	250000h to 257FFFh
	SA82	0	1	0	0	1	0	1	1	X	X	X	32	258000h to 25FFFFh
	SA83	0	1	0	0	1	1	0	0	X	X	X	32	260000h to 267FFFh
	SA84	0	1	0	0	1	1	0	1	X	X	X	32	268000h to 26FFFFh
	SA85	0	1	0	0	1	1	1	0	X	X	X	32	270000h to 277FFFh
	SA86	0	1	0	0	1	1	1	1	X	X	X	32	278000h to 27FFFFh
	SA87	0	1	0	1	0	0	0	0	X	X	X	32	280000h to 287FFFh
	SA88	0	1	0	1	0	0	0	1	X	X	X	32	288000h to 28FFFFh
	SA89	0	1	0	1	0	0	1	0	X	X	X	32	290000h to 297FFFh
	SA90	0	1	0	1	0	0	1	1	X	X	X	32	298000h to 29FFFFh
	SA91	0	1	0	1	0	1	0	0	X	X	X	32	2A0000h to 2A7FFFh
	SA92	0	1	0	1	0	1	0	1	X	X	X	32	2A8000h to 2AFFFFh
	SA93	0	1	0	1	0	1	1	0	X	X	X	32	2B0000h to 2B7FFFh
	SA94	0	1	0	1	0	1	1	1	X	X	X	32	2B8000h to 2BFFFFh
	SA95	0	1	0	1	1	0	0	0	X	X	X	32	2C0000h to 2C7FFFh
	SA96	0	1	0	1	1	0	0	1	X	X	X	32	2C8000h to 2CFFFFh
	SA97	0	1	0	1	1	0	1	0	X	X	X	32	2D0000h to 2D7FFFh
	SA98	0	1	0	1	1	0	1	1	X	X	X	32	2D8000h to 2DFFFFh
	SA99	0	1	0	1	1	1	0	0	X	X	X	32	2E0000h to 2E7FFFh
	SA100	0	1	0	1	1	1	0	1	X	X	X	32	2E8000h to 2EFFFFh
	SA101	0	1	0	1	1	1	1	0	X	X	X	32	2F0000h to 2F7FFFh
	SA102	0	1	0	1	1	1	1	1	X	X	X	32	2F8000h to 2FFFFh
	SA103	0	1	1	0	0	0	0	0	X	X	X	32	300000h to 307FFFh
	SA104	0	1	1	0	0	0	0	1	X	X	X	32	308000h to 30FFFFh
	SA105	0	1	1	0	0	0	1	0	X	X	X	32	310000h to 317FFFh
	SA106	0	1	1	0	0	0	1	1	X	X	X	32	318000h to 31FFFFh
	SA107	0	1	1	0	0	1	0	0	X	X	X	32	320000h to 327FFFh
	SA108	0	1	1	0	0	1	0	1	X	X	X	32	328000h to 32FFFFh
	SA109	0	1	1	0	0	1	1	0	X	X	X	32	330000h to 337FFFh
SA110	0	1	1	0	0	1	1	1	X	X	X	32	338000h to 33FFFFh	
SA111	0	1	1	0	1	0	0	0	X	X	X	32	340000h to 347FFFh	
SA112	0	1	1	0	1	0	0	1	X	X	X	32	348000h to 34FFFFh	
SA113	0	1	1	0	1	0	1	0	X	X	X	32	350000h to 357FFFh	
SA114	0	1	1	0	1	0	1	1	X	X	X	32	358000h to 35FFFFh	
SA115	0	1	1	0	1	1	0	0	X	X	X	32	360000h to 367FFFh	
SA116	0	1	1	0	1	1	0	1	X	X	X	32	368000h to 36FFFFh	

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Bank	Sector	Sector Address											Sector Size (Kwords)	(× 16) Address Range
		Bank Address			A ₁₉	A ₁₈	A ₁₇	A ₁₆	A ₁₅	A ₁₄	A ₁₃	A ₁₂		
		A ₂₂	A ₂₁	A ₂₀										
Bank B	SA117	0	1	1	0	1	1	1	0	X	X	X	32	370000h to 377FFFh
	SA118	0	1	1	0	1	1	1	1	X	X	X	32	378000h to 37FFFFh
	SA119	0	1	1	1	0	0	0	0	X	X	X	32	380000h to 387FFFh
	SA120	0	1	1	1	0	0	0	1	X	X	X	32	388000h to 38FFFFh
	SA121	0	1	1	1	0	0	1	0	X	X	X	32	390000h to 397FFFh
	SA122	0	1	1	1	0	0	1	1	X	X	X	32	398000h to 39FFFFh
	SA123	0	1	1	1	0	1	0	0	X	X	X	32	3A0000h to 3A7FFFh
	SA124	0	1	1	1	0	1	0	1	X	X	X	32	3A8000h to 3AFFFFh
	SA125	0	1	1	1	0	1	1	0	X	X	X	32	3B0000h to 3B7FFFh
	SA126	0	1	1	1	0	1	1	1	X	X	X	32	3B8000h to 3BFFFFh
	SA127	0	1	1	1	1	0	0	0	X	X	X	32	3C0000h to 3C7FFFh
	SA128	0	1	1	1	1	0	0	1	X	X	X	32	3C8000h to 3CFFFFh
	SA129	0	1	1	1	1	0	1	0	X	X	X	32	3D0000h to 3D7FFFh
	SA130	0	1	1	1	1	0	1	1	X	X	X	32	3D8000h to 3DFFFFh
	SA131	0	1	1	1	1	1	0	0	X	X	X	32	3E0000h to 3E7FFFh
	SA132	0	1	1	1	1	1	0	1	X	X	X	32	3E8000h to 3EFFFFh
	SA133	0	1	1	1	1	1	1	0	X	X	X	32	3F0000h to 3F7FFFh
SA134	0	1	1	1	1	1	1	1	X	X	X	32	3F8000h to 3FFFFFh	

Sector Address Table (Bank C)

Bank	Sector	Sector Address										Sector Size (Kwords)	(× 16) Address Range	
		Bank Address			A ₁₉	A ₁₈	A ₁₇	A ₁₆	A ₁₅	A ₁₄	A ₁₃			A ₁₂
		A ₂₂	A ₂₁	A ₂₀										
Bank C	SA135	1	0	0	0	0	0	0	0	X	X	X	32	400000h to 407FFFh
	SA136	1	0	0	0	0	0	0	1	X	X	X	32	408000h to 40FFFFh
	SA137	1	0	0	0	0	0	1	0	X	X	X	32	410000h to 417FFFh
	SA138	1	0	0	0	0	0	1	1	X	X	X	32	418000h to 41FFFFh
	SA139	1	0	0	0	0	1	0	0	X	X	X	32	420000h to 427FFFh
	SA140	1	0	0	0	0	1	0	1	X	X	X	32	428000h to 42FFFFh
	SA141	1	0	0	0	0	1	1	0	X	X	X	32	430000h to 437FFFh
	SA142	1	0	0	0	0	1	1	1	X	X	X	32	438000h to 43FFFFh
	SA143	1	0	0	0	1	0	0	0	X	X	X	32	440000h to 447FFFh
	SA144	1	0	0	0	1	0	0	1	X	X	X	32	448000h to 44FFFFh
	SA145	1	0	0	0	1	0	1	0	X	X	X	32	450000h to 457FFFh
	SA146	1	0	0	0	1	0	1	1	X	X	X	32	458000h to 45FFFFh
	SA147	1	0	0	0	1	1	0	0	X	X	X	32	460000h to 467FFFh
	SA148	1	0	0	0	1	1	0	1	X	X	X	32	468000h to 46FFFFh
	SA149	1	0	0	0	1	1	1	0	X	X	X	32	470000h to 477FFFh
	SA150	1	0	0	0	1	1	1	1	X	X	X	32	478000h to 47FFFFh
	SA151	1	0	0	1	0	0	0	0	X	X	X	32	480000h to 487FFFh
	SA152	1	0	0	1	0	0	0	1	X	X	X	32	488000h to 48FFFFh
	SA153	1	0	0	1	0	0	1	0	X	X	X	32	490000h to 497FFFh
	SA154	1	0	0	1	0	0	1	1	X	X	X	32	498000h to 49FFFFh
	SA155	1	0	0	1	0	1	0	0	X	X	X	32	4A0000h to 4A7FFFh
	SA156	1	0	0	1	0	1	0	1	X	X	X	32	4A8000h to 4AFFFFh
	SA157	1	0	0	1	0	1	1	0	X	X	X	32	4B0000h to 4B7FFFh
	SA158	1	0	0	1	0	1	1	1	X	X	X	32	4B8000h to 4BFFFFh
	SA159	1	0	0	1	1	0	0	0	X	X	X	32	4C0000h to 4C7FFFh
	SA160	1	0	0	1	1	0	0	1	X	X	X	32	4C8000h to 4CFFFFh
	SA161	1	0	0	1	1	0	1	0	X	X	X	32	4D0000h to 4D7FFFh
	SA162	1	0	0	1	1	0	1	1	X	X	X	32	4D8000h to 4DFFFFh
	SA163	1	0	0	1	1	1	0	0	X	X	X	32	4E0000h to 4E7FFFh
	SA164	1	0	0	1	1	1	0	1	X	X	X	32	4E8000h to 4EFFFFh
SA165	1	0	0	1	1	1	1	0	X	X	X	32	4F0000h to 4F7FFFh	
SA166	1	0	0	1	1	1	1	1	X	X	X	32	4F8000h to 4FFFFh	
SA167	1	0	1	0	0	0	0	0	X	X	X	32	500000h to 507FFFh	
SA168	1	0	1	0	0	0	0	1	X	X	X	32	508000h to 50FFFFh	
SA169	1	0	1	0	0	0	1	0	X	X	X	32	510000h to 517FFFh	
SA170	1	0	1	0	0	0	1	1	X	X	X	32	518000h to 51FFFFh	
SA171	1	0	1	0	0	1	0	0	X	X	X	32	520000h to 527FFFh	
SA172	1	0	1	0	0	1	0	1	X	X	X	32	528000h to 52FFFFh	
SA173	1	0	1	0	0	1	1	0	X	X	X	32	530000h to 537FFFh	

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Bank	Sector	Sector Address											Sector Size (Kwords)	(× 16) Address Range
		Bank Address			A ₁₉	A ₁₈	A ₁₇	A ₁₆	A ₁₅	A ₁₄	A ₁₃	A ₁₂		
		A ₂₂	A ₂₁	A ₂₀										
Bank C	SA174	1	0	1	0	0	1	1	1	X	X	X	32	538000h to 53FFFFh
	SA175	1	0	1	0	1	0	0	0	X	X	X	32	540000h to 547FFFh
	SA176	1	0	1	0	1	0	0	1	X	X	X	32	548000h to 54FFFFh
	SA177	1	0	1	0	1	0	1	0	X	X	X	32	550000h to 557FFFh
	SA178	1	0	1	0	1	0	1	1	X	X	X	32	558000h to 55FFFFh
	SA179	1	0	1	0	1	1	0	0	X	X	X	32	560000h to 567FFFh
	SA180	1	0	1	0	1	1	0	1	X	X	X	32	568000h to 56FFFFh
	SA181	1	0	1	0	1	1	1	0	X	X	X	32	570000h to 577FFFh
	SA182	1	0	1	0	1	1	1	1	X	X	X	32	578000h to 57FFFFh
	SA183	1	0	1	1	0	0	0	0	X	X	X	32	580000h to 587FFFh
	SA184	1	0	1	1	0	0	0	1	X	X	X	32	588000h to 58FFFFh
	SA185	1	0	1	1	0	0	1	0	X	X	X	32	590000h to 597FFFh
	SA186	1	0	1	1	0	0	1	1	X	X	X	32	598000h to 59FFFFh
	SA187	1	0	1	1	0	1	0	0	X	X	X	32	5A0000h to 5A7FFFh
	SA188	1	0	1	1	0	1	0	1	X	X	X	32	5A8000h to 5AFFFFh
	SA189	1	0	1	1	0	1	1	0	X	X	X	32	5B0000h to 5B7FFFh
	SA190	1	0	1	1	0	1	1	1	X	X	X	32	5B8000h to 5BFFFFh
	SA191	1	0	1	1	1	0	0	0	X	X	X	32	5C0000h to 5C7FFFh
	SA192	1	0	1	1	1	0	0	1	X	X	X	32	5C8000h to 5CFFFFh
	SA193	1	0	1	1	1	0	1	0	X	X	X	32	6D0000h to 6D7FFFh
	SA194	1	0	1	1	1	0	1	1	X	X	X	32	6D8000h to 6DFFFFh
	SA195	1	0	1	1	1	1	0	0	X	X	X	32	5E0000h to 5E7FFFh
	SA196	1	0	1	1	1	1	0	1	X	X	X	32	5E8000h to 5EFFFFh
	SA197	1	0	1	1	1	1	1	0	X	X	X	32	5F0000h to 5F7FFFh
SA198	1	0	1	1	1	1	1	1	X	X	X	32	5F8000h to 5FFFFh	
SA199	1	1	0	0	0	0	0	0	X	X	X	32	600000h to 607FFFh	
SA200	1	1	0	0	0	0	0	1	X	X	X	32	608000h to 60FFFFh	
SA201	1	1	0	0	0	0	1	0	X	X	X	32	610000h to 617FFFh	
SA202	1	1	0	0	0	0	1	1	X	X	X	32	618000h to 61FFFFh	
SA203	1	1	0	0	0	1	0	0	X	X	X	32	620000h to 627FFFh	
SA204	1	1	0	0	0	1	0	1	X	X	X	32	628000h to 62FFFFh	
SA205	1	1	0	0	0	1	1	0	X	X	X	32	630000h to 637FFFh	
SA206	1	1	0	0	0	1	1	1	X	X	X	32	638000h to 63FFFFh	
SA207	1	1	0	0	1	0	0	0	X	X	X	32	640000h to 647FFFh	
SA208	1	1	0	0	1	0	0	1	X	X	X	32	648000h to 64FFFFh	
SA209	1	1	0	0	1	0	1	0	X	X	X	32	650000h to 657FFFh	
SA210	1	1	0	0	1	0	1	1	X	X	X	32	658000h to 65FFFFh	
SA211	1	1	0	0	1	1	0	0	X	X	X	32	660000h to 667FFFh	
SA212	1	1	0	0	1	1	0	1	X	X	X	32	668000h to 66FFFFh	

(Continued)

(Continued)

Bank	Sector	Sector Address											Sector Size (Kwords)	(× 16) Address Range
		Bank Address			A ₁₉	A ₁₈	A ₁₇	A ₁₆	A ₁₅	A ₁₄	A ₁₃	A ₁₂		
		A ₂₂	A ₂₁	A ₂₀										
Bank C	SA213	1	1	0	0	1	1	1	0	X	X	X	32	670000h to 677FFFh
	SA214	1	1	0	0	1	1	1	1	X	X	X	32	678000h to 67FFFFh
	SA215	1	1	0	1	0	0	0	0	X	X	X	32	680000h to 687FFFh
	SA216	1	1	0	1	0	0	0	1	X	X	X	32	688000h to 68FFFFh
	SA217	1	1	0	1	0	0	1	0	X	X	X	32	690000h to 697FFFh
	SA218	1	1	0	1	0	0	1	1	X	X	X	32	698000h to 69FFFFh
	SA219	1	1	0	1	0	1	0	0	X	X	X	32	6A0000h to 6A7FFFh
	SA220	1	1	0	1	0	1	0	1	X	X	X	32	6A8000h to 6AFFFFh
	SA221	1	1	0	1	0	1	1	0	X	X	X	32	6B0000h to 6B7FFFh
	SA222	1	1	0	1	0	1	1	1	X	X	X	32	8B8000h to 6BFFFFh
	SA223	1	1	0	1	1	0	0	0	X	X	X	32	6C0000h to 6C7FFFh
	SA224	1	1	0	1	1	0	0	1	X	X	X	32	6C8000h to 6CFFFFh
	SA225	1	1	0	1	1	0	1	0	X	X	X	32	6D0000h to 6D7FFFh
	SA226	1	1	0	1	1	0	1	1	X	X	X	32	6D8000h to 6DFFFFh
	SA227	1	1	0	1	1	1	0	0	X	X	X	32	6E0000h to 6E7FFFh
	SA228	1	1	0	1	1	1	0	1	X	X	X	32	6E8000h to 6EFFFFh
	SA229	1	1	0	1	1	1	1	0	X	X	X	32	6F0000h to 6F7FFFh
SA230	1	1	0	1	1	1	1	1	X	X	X	32	6F8000h to 6FFFFFh	

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Sector Address Table (Bank D)

Bank	Sector	Sector Address											Sector Size (Kwords)	(× 16) Address Range
		Bank Address			A ₁₉	A ₁₈	A ₁₇	A ₁₆	A ₁₅	A ₁₄	A ₁₃	A ₁₂		
		A ₂₂	A ₂₁	A ₂₀										
Bank D	SA231	1	1	1	0	0	0	0	0	X	X	X	32	700000h to 707FFFh
	SA232	1	1	1	0	0	0	0	1	X	X	X	32	708000h to 70FFFFh
	SA233	1	1	1	0	0	0	1	0	X	X	X	32	710000h to 717FFFh
	SA234	1	1	1	0	0	0	1	1	X	X	X	32	718000h to 71FFFFh
	SA235	1	1	1	0	0	1	0	0	X	X	X	32	720000h to 727FFFh
	SA236	1	1	1	0	0	1	0	1	X	X	X	32	728000h to 72FFFFh
	SA237	1	1	1	0	0	1	1	0	X	X	X	32	730000h to 737FFFh
	SA238	1	1	1	0	0	1	1	1	X	X	X	32	738000h to 73FFFFh
	SA239	1	1	1	0	1	0	0	0	X	X	X	32	740000h to 747FFFh
	SA240	1	1	1	0	1	0	0	1	X	X	X	32	748000h to 74FFFFh
	SA241	1	1	1	0	1	0	1	0	X	X	X	32	750000h to 757FFFh
	SA242	1	1	1	0	1	0	1	1	X	X	X	32	758000h to 75FFFFh
	SA243	1	1	1	0	1	1	0	0	X	X	X	32	760000h to 767FFFh
	SA244	1	1	1	0	1	1	0	1	X	X	X	32	768000h to 76FFFFh
	SA245	1	1	1	0	1	1	1	0	X	X	X	32	770000h to 777FFFh
	SA246	1	1	1	0	1	1	1	1	X	X	X	32	778000h to 77FFFFh
	SA247	1	1	1	1	0	0	0	0	X	X	X	32	780000h to 787FFFh
	SA248	1	1	1	1	0	0	0	1	X	X	X	32	788000h to 78FFFFh
	SA249	1	1	1	1	0	0	1	0	X	X	X	32	790000h to 797FFFh
	SA250	1	1	1	1	0	0	1	1	X	X	X	32	798000h to 79FFFFh
	SA251	1	1	1	1	0	1	0	0	X	X	X	32	7A0000h to 7A7FFFh
	SA252	1	1	1	1	0	1	0	1	X	X	X	32	7A8000h to 7AFFFFh
	SA253	1	1	1	1	0	1	1	0	X	X	X	32	7B0000h to 7B7FFFh
	SA254	1	1	1	1	0	1	1	1	X	X	X	32	7B8000h to 7BFFFFh
	SA255	1	1	1	1	1	0	0	0	X	X	X	32	7C0000h to 7C7FFFh
	SA256	1	1	1	1	1	0	0	1	X	X	X	32	7C8000h to 7CFFFFh
	SA257	1	1	1	1	1	0	1	0	X	X	X	32	7D0000h to 7D7FFFh
	SA258	1	1	1	1	1	0	1	1	X	X	X	32	7D8000h to 7DFFFFh
	SA259	1	1	1	1	1	1	0	0	X	X	X	32	7E0000h to 7E7FFFh
SA260	1	1	1	1	1	1	0	1	X	X	X	32	7E8000h to 7EFFFFh	
SA261	1	1	1	1	1	1	1	0	X	X	X	32	7F0000h to 7F7FFFh	
SA262	1	1	1	1	1	1	1	1	0	0	0	4	7F8000h to 7F8FFFh	
SA263	1	1	1	1	1	1	1	1	0	0	1	4	7F9000h to 7F9FFFh	
SA264	1	1	1	1	1	1	1	1	0	1	0	4	7FA000h to 7FAFFFh	
SA265	1	1	1	1	1	1	1	1	0	1	1	4	7FB000h to 7FBFFFh	
SA266	1	1	1	1	1	1	1	1	1	0	0	4	7FC000h to 7FCFFFh	
SA267	1	1	1	1	1	1	1	1	1	0	1	4	7FD000h to 7FDFFFh	
SA268	1	1	1	1	1	1	1	1	1	1	0	4	7FE000h to 7FEFFFh	
SA269	1	1	1	1	1	1	1	1	1	1	1	4	7FF000h to 7FFFFFh	

Sector Group Address Table

Sector Group	A ₂₂	A ₂₁	A ₂₀	A ₁₉	A ₁₈	A ₁₇	A ₁₆	A ₁₅	A ₁₄	A ₁₃	A ₁₂	Sectors
SGA0	0	0	0	0	0	0	0	0	0	0	0	SA0
SGA1	0	0	0	0	0	0	0	0	0	0	1	SA1
SGA2	0	0	0	0	0	0	0	0	0	1	0	SA2
SGA3	0	0	0	0	0	0	0	0	0	1	1	SA3
SGA4	0	0	0	0	0	0	0	0	1	0	0	SA4
SGA5	0	0	0	0	0	0	0	0	1	0	1	SA5
SGA6	0	0	0	0	0	0	0	0	1	1	0	SA6
SGA7	0	0	0	0	0	0	0	0	1	1	1	SA7
SGA8	0	0	0	0	0	0	0	1	X	X	X	SA8
SGA9	0	0	0	0	0	0	1	0	X	X	X	SA9
SGA10	0	0	0	0	0	0	1	1	X	X	X	SA10
SGA11	0	0	0	0	0	1	X	X	X	X	X	SA11 to SA14
SGA12	0	0	0	0	1	0	X	X	X	X	X	SA15 to SA18
SGA13	0	0	0	0	1	1	X	X	X	X	X	SA19 to SA22
SGA14	0	0	0	1	0	0	X	X	X	X	X	SA23 to SA26
SGA15	0	0	0	1	0	1	X	X	X	X	X	SA27 to SA30
SGA16	0	0	0	1	1	0	X	X	X	X	X	SA31 to SA34
SGA17	0	0	0	1	1	1	X	X	X	X	X	SA35 to SA38
SGA18	0	0	1	0	0	0	X	X	X	X	X	SA39 to SA42
SGA19	0	0	1	0	0	1	X	X	X	X	X	SA43 to SA46
SGA20	0	0	1	0	1	0	X	X	X	X	X	SA47 to SA50
SGA21	0	0	1	0	1	1	X	X	X	X	X	SA51 to SA54
SGA22	0	0	1	1	0	0	X	X	X	X	X	SA55 to SA58
SGA23	0	0	1	1	0	1	X	X	X	X	X	SA59 to SA62
SGA24	0	0	1	1	1	0	X	X	X	X	X	SA63 to SA66
SGA25	0	0	1	1	1	1	X	X	X	X	X	SA67 to SA70
SGA26	0	1	0	0	0	0	X	X	X	X	X	SA71 to SA74
SGA27	0	1	0	0	0	1	X	X	X	X	X	SA75 to SA78

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Sector Group	A ₂₂	A ₂₁	A ₂₀	A ₁₉	A ₁₈	A ₁₇	A ₁₆	A ₁₅	A ₁₄	A ₁₃	A ₁₂	Sectors
SGA28	0	1	0	0	1	0	X	X	X	X	X	SA79 to SA82
SGA29	0	1	0	0	1	1	X	X	X	X	X	SA83 to SA86
SGA30	0	1	0	1	0	0	X	X	X	X	X	SA87 to SA90
SGA31	0	1	0	1	0	1	X	X	X	X	X	SA91 to SA94
SGA32	0	1	0	1	1	0	X	X	X	X	X	SA95 to SA98
SGA33	0	1	0	1	1	1	X	X	X	X	X	SA99 to SA102
SGA34	0	1	1	0	0	0	X	X	X	X	X	SA103 to SA106
SGA35	0	1	1	0	0	1	X	X	X	X	X	SA107 to SA110
SGA36	0	1	1	0	1	0	X	X	X	X	X	SA111 to SA114
SGA37	0	1	1	0	1	1	X	X	X	X	X	SA115 to SA118
SGA38	0	1	1	1	0	0	X	X	X	X	X	SA119 to SA122
SGA39	0	1	1	1	0	1	X	X	X	X	X	SA123 to SA126
SGA40	0	1	1	1	1	0	X	X	X	X	X	SA127 to SA130
SGA41	0	1	1	1	1	1	X	X	X	X	X	SA131 to SA134
SGA42	1	0	0	0	0	0	X	X	X	X	X	SA135 to SA138
SGA43	1	0	0	0	0	1	X	X	X	X	X	SA139 to SA142
SGA44	1	0	0	0	1	0	X	X	X	X	X	SA143 to SA146
SGA45	1	0	0	0	1	1	X	X	X	X	X	SA147 to SA150
SGA46	1	0	0	1	0	0	X	X	X	X	X	SA151 to SA154
SGA47	1	0	0	1	0	1	X	X	X	X	X	SA155 to SA158
SGA48	1	0	0	1	1	0	X	X	X	X	X	SA159 to SA162
SGA49	1	0	0	1	1	1	X	X	X	X	X	SA163 to SA166
SGA50	1	0	1	0	0	0	X	X	X	X	X	SA167 to SA170
SGA51	1	0	1	0	0	1	X	X	X	X	X	SA171 to SA174

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(Continued)

Sector Group	A ₂₂	A ₂₁	A ₂₀	A ₁₉	A ₁₈	A ₁₇	A ₁₆	A ₁₅	A ₁₄	A ₁₃	A ₁₂	Sectors
SGA52	1	0	1	0	1	0	X	X	X	X	X	SA175 to SA178
SGA53	1	0	1	0	1	1	X	X	X	X	X	SA179 to SA182
SGA54	1	0	1	1	0	0	X	X	X	X	X	SA183 to SA186
SGA55	1	0	1	1	0	1	X	X	X	X	X	SA187 to SA190
SGA56	1	0	1	1	1	0	X	X	X	X	X	SA191 to SA194
SGA57	1	0	1	1	1	1	X	X	X	X	X	SA195 to SA198
SGA58	1	1	0	0	0	0	X	X	X	X	X	SA199 to SA202
SGA59	1	1	0	0	0	1	X	X	X	X	X	SA203 to SA206
SGA60	1	1	0	0	1	0	X	X	X	X	X	SA207 to SA210
SGA61	1	1	0	0	1	1	X	X	X	X	X	SA211 to SA214
SGA62	1	1	0	1	0	0	X	X	X	X	X	SA215 to SA218
SGA63	1	1	0	1	0	1	X	X	X	X	X	SA219 to SA222
SGA64	1	1	0	1	1	0	X	X	X	X	X	SA223 to SA226
SGA65	1	1	0	1	1	1	X	X	X	X	X	SA227 to SA230
SGA66	1	1	1	0	0	0	X	X	X	X	X	SA231 to SA234
SGA67	1	1	1	0	0	1	X	X	X	X	X	SA235 to SA238
SGA68	1	1	1	0	1	0	X	X	X	X	X	SA239 to SA242
SGA69	1	1	1	0	1	1	X	X	X	X	X	SA243 to SA246
SGA70	1	1	1	1	0	0	X	X	X	X	X	SA247 to SA250
SGA71	1	1	1	1	0	1	X	X	X	X	X	SA251 to SA254
SGA72	1	1	1	1	1	0	X	X	X	X	X	SA255 to SA258
SGA73	1	1	1	1	1	1	0	0	X	X	X	SA259
SGA74	1	1	1	1	1	1	0	1	X	X	X	SA260
SGA75	1	1	1	1	1	1	1	0	X	X	X	SA261
SGA76	1	1	1	1	1	1	1	1	0	0	0	SA262
SGA77	1	1	1	1	1	1	1	1	0	0	1	SA263
SGA78	1	1	1	1	1	1	1	1	0	1	0	SA264
SGA79	1	1	1	1	1	1	1	1	0	1	1	SA265
SGA80	1	1	1	1	1	1	1	1	1	0	0	SA266
SGA81	1	1	1	1	1	1	1	1	1	0	1	SA267
SGA82	1	1	1	1	1	1	1	1	1	1	0	SA268
SGA83	1	1	1	1	1	1	1	1	1	1	1	SA269

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Common Flash Memory Interface Code Table

Description	A ₆ to A ₀	DQ ₁₅ to DQ ₀	Description	A ₆ to A ₀	DQ ₁₅ to DQ ₀
Query-unique ASCII string "QRY"	10h 11h 12h	0051h 0052h 0059h	Erase Block Region 4 Information	39h 3Ah 3Bh 3Ch	0000h 0000h 0000h 0000h
Primary OEM Command Set 2h: AMD/FJ standard type	13h 14h	0002h 0000h		40h 41h 42h	0050h 0052h 0049h
Address for Primary Extended Table	15h 16h	0040h 0000h		Major version number, ASCII	43h
Alternate OEM Command Set (00h = not applicable)	17h 18h	0000h 0000h	Minor version number, ASCII	44h	0033h
Address for Alternate OEM Extended Table	19h 1Ah	0000h 0000h	Address Sensitive Unlock 0h = Required 1h = Not Required	45h	000Ch
V _{CC} Min (write/erase) DQ ₇ to DQ ₄ : 1 V, DQ ₃ to DQ ₀ : 100 mV	1Bh	0017h	Erase Suspend 0h = Not Supported 1h = To Read Only 2h = To Read & Write	46h	0002h
V _{CC} Max (write/erase) DQ ₇ to DQ ₄ : 1 V, DQ ₃ to DQ ₀ : 100 mV	1Ch	0019h	Sector Protection 0h = Not Supported X = Number of sectors in per group	47h	0001h
V _{PP} Min voltage	1Dh	0000h	Sector Temporary Unprotection 00h = Not Supported 01h = Supported	48h	0000h
V _{PP} Max voltage	1Eh	0000h	Sector Protection Algorithm	49h	0007h
Typical timeout per single byte/ word write 2 ^N μs	1Fh	0004h	Simultaneous Operation 00h = Not Supported, X = Total number of sectors in all Banks except Bank A	4Ah	00E7h
Typical timeout for Min size buff- er write 2 ^N μs	20h	0000h	Burst Mode Type 00h = Not Supported	4Bh	0001h
Typical timeout per individual block erase 2 ^N ms	21h	0009h	Page Mode Type 00h = Not Supported	4Ch	0000h
Typical timeout for full chip erase 2 ^N ms	22h	0000h	ACC (Acceleration) Supply Minimum 00h = Not Supported, DQ ₇ to DQ ₄ : 1 V, DQ ₃ to DQ ₀ : 100 mV	4Dh	00B5h
Max timeout for byte/word write 2 ^N times typical	23h	0004h	ACC (Acceleration) Supply Maximum 00h = Not Supported, DQ ₇ to DQ ₄ : 1 V, DQ ₃ to DQ ₀ : 100 mV	4Eh	00C5h
Max timeout for buffer write 2 ^N times typical	24h	0000h	Boot Type	4Fh	0001h
Max timeout per individual block erase 2 ^N times typical	25h	0004h	Program Suspend 00h = Not Supported, 01h = Supported	50h	0000h
Max timeout for full chip erase 2 ^N times typical	26h	0000h	Bank Organization	57h	0004h
Device Size = 2 ^N byte	27h	0018h	Bank A Region Information	58h	0027h
Flash Device Interface description	28h 29h	0001h 0000h	Bank B Region Information	59h	0060h
Max number of byte in multi-byte write = 2 ^N	2Ah 2Bh	0000h 0000h	Bank C Region Information	5Ah	0060h
Number of Erase Block Regions within device	2Ch	0003h	Bank D Region Information	5Bh	0027h
Erase Block Region 1 Information	2Dh 2Eh 2Fh 30h	0007h 0000h 0020h 0000h			
	31h 32h 33h 34h	00FDh 0000h 0000h 0001h			
	35h 36h 37h 38h	0007h 0000h 0020h 0000h			

■ FUNCTIONAL DESCRIPTION

Asynchronous Read Operation (Non-Burst) Mode

When the device first powers up, it is enabled for asynchronous read operation. CLK is ignored in this operation.

To read data from the memory array, the system must first assert a valid address on A₂₂ to A₀, while driving \overline{AVD} and \overline{CE} to V_{IL}. \overline{WE} should remain at V_{IH}. The addresses are latched on the falling edge of \overline{CE} while \overline{AVD} is held low or the address transition while \overline{AVD} is held low. The data will appear on DQ₁₅ to DQ₀. Since the memory array is divided into four banks, each bank remains enabled for read access until the command register contents are altered.

Address access time (t_{ACC}) is equal to the delay from stable addresses to valid output data. The chip enable access time (t_{CE}) is the delay from the stable addresses and stable \overline{CE} to valid data at the outputs. The output enable access time (t_{OE}) is the delay from the falling edge of \overline{OE} to valid data at the output.

The internal state machine is set for reading array data in asynchronous mode upon device power-up, or after a hardware reset. During power transition \overline{RESET} must be held low. (Refer to "Power On/Off Timing Diagram") This ensures that no spurious alteration of the memory content occurs during the power transition.

Synchronous (Burst) Read Operation Mode

The device is capable of linear burst operation of a preset length.

Prior to entering burst mode, the system should determine how many wait states are desired for the initial word (t_{iACC}) of each burst access, what mode of burst operation is desired, which edge of the clock will be the active clock edge, and how the RDY signal will transition with valid data. The system would then write the configuration register set command sequence. See "Configuration Register Set Command" and "Command Definitions" for further details.

Once the system has written the "Configuration Register Set" command sequence, the device Read mode is enabled for synchronous reads only.

The initial word is output t_{iACC} after the active edge of the first CLK cycle. Subsequent words are output t_{BACC} after the active edge of each successive clock cycle, which automatically increments the internal address counter.

8-, 16-, and 32-Word Linear Burst with Wrap Around

The device provides Linear burst mode, in which a fixed number of words are read from consecutive addresses. In each of these modes, the burst addresses read are determined by the group within which the starting address falls. The groups are sized according to the number of words read in a single burst sequence for a given mode.

As an example: if the starting address in the 8-word with wrap-around mode is 39h, the address range to be read would be 38-3Fh, and the burst sequence would be 39-3A-3B-3C-3D-3E-3F-38h-etc. The burst sequence begins with the starting address written to the device, but wraps back to the first address in the selected group. In a similar fashion, the 16-word and 32-word Linear Wrap modes begin their burst sequence on the starting address written to the device, and then wrap back to the first address in the selected address group.

The RDY pin indicates when data is valid on the bus in synchronous read mode. The devices can wrap through a maximum of 128 words of data (8 words up to 16 times, 16 words up to 8 times, or 32 words up to 4 times) before requiring a new synchronous access (latching of a new address).

Burst Address Groups Table

Mode	Group Size	Group Address Ranges
8-word with wrap-around	8 words	0h-7h, 8h-Fh, 10h-17h, ...
16-word with wrap-around	16 words	0h-Fh, 10h-1Fh, 20h-2Fh, ...
32-word with wrap-around	32 words	00h-1Fh, 20h-3Fh, 40h-5Fh, ...

Configuration Register

The device uses a configuration register to set the various burst parameters: number of wait states, burst read mode, active clock edge, RDY configuration, and synchronous mode active.

Burst Suspend / Resume

The Burst Suspend / Resume feature allows the system temporarily suspend a synchronous burst operation during the initial access (before data is available) or after the device is outputting data. When the burst operation is suspended, any previously latched internal data and the current state are retained.

At Handshaking mode, when the Burst Suspend is enabled the device will enter power down mode, in which the current consumption is reduced to typically 1mA. At Non-Handshaking mode, the device does not go to power down mode. Burst plus Burst Suspend should not last longer than t_{RCC} without relatching an address or crossing address boundary.

Burst Suspend requires \overline{CE} to be asserted, \overline{WE} deasserted, and the initial address latched by the CLK edge. Burst Suspend occurs when \overline{OE} is deasserted. To resume the burst access, \overline{OE} must be re-asserted. The next active CLK edge will resume the burst sequence where it had been suspended.

The RDY pin is only controlled by \overline{CE} . RDY will remain active and is not placed into a high-impedance state when \overline{OE} is de-asserted. When using Burst Suspend feature, the host system should set the configuration register to "RDY active with data ($A_{18}=1$)". Refer to "Configuration Register Set Command".

Handshaking Option

The device is equipped with a handshaking feature that brings out the fastest initial latency of this burst mode flash memory by simply monitoring the RDY signal from the device to determine when the initial word of burst data is ready to be read. In this handshaking mode, the microprocessor does not need to set its register the number of initial wait clocks. The device will indicate when the initial word of burst data is valid by the rising edge of RDY after \overline{OE} goes low. The presence of the handshaking feature may be verified by writing the autoselect command sequence to the device. See "Autoselect Command Sequence" for details. For optimal burst mode performance on devices with the handshaking option, the host system must set the appropriate number of wait states in the flash device depending on clock frequency. See "Configuration Register Set Command" section for more information.

Non-Handshaking Option

In Non-Handshaking option, the device does not require the host system monitoring RDY signal. The microprocessor will know the number of initial wait count to be required by setting its own register. The device always provides initial data with same initial clock latency that is set by Configuration Register. See "Configuration Register Set Command" section for more information.

Simultaneous Operation

The device features functions that enable reading of data from one memory bank while a program or erase operation is in progress in the other memory bank (simultaneous operation), in addition to conventional features (read, program, erase, erase-suspend read, and erase-suspend program). The bank can be selected by bank address (A_{22} , A_{21} , A_{20}) with zero latency. The device consists of the following four banks:

Bank A : 8 X 4 Kword and 31 X 32 Kword; Bank B : 96 X 32 Kword; Bank C : 96 X 32 Kword; Bank D : 8 X 4 Kword and 31 X 32 Kword. The device can execute simultaneous operations between Bank 1, a bank chosen from among the four banks, and Bank 2, a bank consisting of the three remaining banks. (See "Burst Address Groups Table".) This is what we call a "FlexBank", for example, the rest of banks B, C and D to let the system read while Bank A is in the process of program (or erase) operation. However, the different types of operations for the three banks are impossible, e.g. Bank A writing, Bank B erasing, and Bank C reading out. With this "FlexBank", as described in "FlexBank™ Architecture Table", the system gets to select from four combinations of data volume for Bank 1 and Bank 2, which works well to meet the system requirement. The simultaneous operation cannot execute multi-function mode in the same bank. "Simultaneous Operation Table" shows the possible combinations for simultaneous operation. (Refer to "Bank-to-Bank Read/Write Timing Diagram" in "TIMING DIAGRAM".)

FlexBank™ Architecture Table

Bank Splits	Bank 1		Bank 2	
	Volume	Combination	Volume	Combination
1	16 Mbit	Bank A	112 Mbit	Remember (Bank B, C, D)
2	48 Mbit	Bank B	96 Mbit	Remember (Bank A, C, D)
3	48 Mbit	Bank C	96 Mbit	Remember (Bank A, B, D)
4	16 Mbit	Bank D	112 Mbit	Remember (Bank A, B, C)

Example of Virtual Banks Combination Table

Bank Splits	Bank 1			Bank 2		
	Megabits	Combination of Memory Bank	Sector Sizes	Megabits	Combination of Memory Bank	Sector Sizes
1	16 Mbit	Bank A	Eight 4K word, thirty-one 32K word	112 Mbit	Bank B + Bank C + Bank D	Eight 4K word, two hundred twenty-three 32K word
2	32 Mbit	Bank A + Bank D	Sixteen 4K word, sixty-two 32K word	96 Mbit	Bank B + Bank C	One hundred ninety-two 32K word
3	48 Mbit	Bank B	Ninety-six 32K word	80 Mbit	Bank A + Bank C + Bank D	Sixteen 4K word, one hundred fifty-eight 32K word
4	64 Mbit	Bank A + Bank B	Eight 4K word, one hundred twenty-seven 32K word	64 Mbit	Bank C + Bank D	Eight 4K word, one hundred twenty-seven 32K word

Note : When multiple sector erase over several banks is operated, the system cannot read out of the bank to which a sector being erased belongs. For example, suppose that erasing is taking place at both Bank A and Bank B, neither Bank A nor Bank B is read out (they would output the sequence flag once they were selected.) Meanwhile the system would get to read from either Bank C or Bank D.

Simultaneous Operation Table

Case	Bank 1 Status	Bank 2 Status
1	Read mode	Read mode
2	Read mode	Autoselect mode
3	Read mode	Program mode
4	Read mode	Erase mode
5	Autoselect mode	Read mode
6	Program mode	Read mode
7	Erase mode	Read mode

Note : Bank 1 and Bank 2 are divided for the sake of convenience at Simultaneous Operation. Actually, the Bank consists of 4 banks, Bank A, Bank B, BankC and Bank D. Bank Address (BA) meant to specify each of the Banks.

Standby Mode

There are two ways to implement the standby mode on the device, one using both the \overline{CE} and \overline{RESET} pins, and the other via the \overline{RESET} pin only.

When using both pins, a CMOS standby mode is achieved with \overline{CE} and \overline{RESET} input held at $V_{CC} \pm 0.2$ V. Under this condition the current consumed is less than 10 μ A Max. During Embedded Algorithm operation, V_{CC} active current (I_{CC2}) is required even if $\overline{CE} = "H"$. The device can be read with standard access time (t_{CE}) from either of these standby modes.

When using the \overline{RESET} pin only, a CMOS standby mode is achieved with \overline{RESET} input held at $V_{SS} \pm 0.3$ V ($\overline{CE} = "H"$ or $"L"$). Under this condition the current consumed is less than 5 μ A Max. Once the \overline{RESET} pin is set high, the device requires t_{RH} as a wake-up time for output to be valid for read access.

During standby mode, the output is in the high impedance state, regardless of \overline{OE} input.

I_{CC3} in the DC Characteristics table represents the standby current specification.

Automatic Sleep Mode

Automatic sleep mode works to restrain power consumption during read-out of the device data. This mode can be useful in the application such as a handy terminal which requires low power consumption.

While in asynchronous mode, the device automatically enables this mode when addresses remain stable for $t_{ACC} + 60$ ns. The automatic sleep mode is independent of the \overline{CE} , \overline{WE} , and \overline{OE} control signals. Standard address access timings provide new data when addresses are changed. While in sleep mode, output data is latched and always available to the system. Under the mode, the current consumed is typically 0.2 μ A (CMOS Level). Since the data are latched during this mode, the data are continuously read out. When the addresses are changed, the mode is automatically canceled and the device reads the data for changed addresses.

While in synchronous mode, the device automatically enables this mode when the first active CLK level (if rising edge is active, the first period of $CLK = V_{IH}$) is greater than t_{ACC} . During this mode on Handshaking devices, initial latency will be same between even and odd address. The device always outputs data with the same latency to even address. In case of Non-Handshaking devices, initial latency is fixed same as normal operation. When the device is in the Automatic sleep mode, the device outputs burst data with the CLK. Please note that if CLK runs faster (active CLK level is shorter than t_{ACC}) during burst access in the Automatic sleep mode, the device will output incorrect data. In this case, a new burst operations (addresses must be re-latched) is required to provide correct data. Under the mode, the current consumed is typically TBD μ A (CMOS Level).

During simultaneous operation, V_{CC} active current (I_{CC2}) is required.

Output Disable

When the \overline{OE} input is at V_{IH} , output from the device is disabled. The outputs are placed in the high impedance state.

Write

Device erasure and programming are accomplished via the command register. The contents of the register serve as input to the internal state machine. The state machine output dictates the function of the device. The command register itself does not occupy any addressable memory location. The register is a latch used to store the commands, along with the address and data information needed to execute the command. The programming operation is dependent of the Set Device Read Mode bit in the Configuration Register.

- At Asynchronous Mode

Clock is ignored when the Configuration Register is set to Asynchronous mode, the device has the capability of performing two types of programming operation.

\overline{WE} latch - The system must drive \overline{CE} , \overline{WE} , and \overline{AVD} to V_{IL} and \overline{OE} to V_{IH} when providing an address and data. Addresses are latched on the falling edge of \overline{WE} while data is latched on the rising edge of \overline{WE} . (Refer to "Program Operation Timing at Asynchronous Mode (\overline{WE} latch)").

\overline{AVD} latch - The system must drive \overline{CE} and \overline{AVD} to V_{IL} , and \overline{OE} to V_{IH} when providing an address to the device, and drive \overline{WE} and \overline{CE} to V_{IL} , and \overline{OE} to V_{IH} when wiring data. Addresses are latched on the rising edge of \overline{AVD} and data is latched on the rising edge of \overline{WE} . (Refer to "Program Operation Timing at Asynchronous Mode (\overline{AVD} latch)").

- At Synchronous Mode

When the Configuration Register is set to Synchronous mode, the device has the capability of performing two types of programming operation.

\overline{WE} latch - The system must drive \overline{CE} , \overline{WE} , and \overline{AVD} to V_{IL} and \overline{OE} to V_{IH} when providing an address and data. Addresses are latched on the falling edge of \overline{WE} while \overline{AVD} is held V_{IL} and data is latched on the rising edge of \overline{WE} . (Refer to "Program Operation Timing at Synchronous Mode (\overline{WE} latch)"). Refer to AC Write Characteristics and the Erase/Program Waveforms for specific timing parameters.

Note : Addresses are latched on the first of either the falling edge of \overline{WE} or active edge of CLK.

CLK latch - The system must drive \overline{CE} and \overline{AVD} to V_{IL} , and \overline{OE} to V_{IH} when providing an address to the device, and drive \overline{WE} and \overline{CE} to V_{IL} , and \overline{OE} to V_{IH} when wiring data. Addresses are latched on the active edge of clock while \overline{AVD} is held V_{IL} and data is latched on the rising edge of \overline{WE} . (Refer to "Program Operation Timing at Synchronous Mode (CLK latch)").

RESET

Hardware Reset

The device may be reset by driving the \overline{RESET} pin to V_{IL} . The \overline{RESET} pin has a pulse requirement and has to be kept low (V_{IL}) for at least " t_{RP} " in order to properly reset the internal state machine. Any operation in the process of being executed will be terminated and the internal state machine will be reset to the read mode " t_{READY} " after the \overline{RESET} pin is driven low. Furthermore, once the \overline{RESET} pin goes high the device requires an additional " t_{RH} " before it will allow read access. When the \overline{RESET} pin is low, the device will be in the standby mode for the duration of the pulse and all the data output pins will be tri-stated. If a hardware reset occurs during a program or erase operation, the data at that particular location will be corrupted.

Accelerated Program Operation

The device offers accelerated program operation which enables the programming in high speed. If the system asserts V_{ACC} to the ACC pin, the device automatically enters the acceleration mode and the time required for program operation will reduce to about 60%. This function is primarily intended to allow high speed program, so caution is needed as the sector group will temporarily be unprotected.

When at V_{IL} , ACC locks all sectors. Should be at V_{IH} for all other conditions.

The system would use a fast program command sequence when programming during acceleration mode. Set command to fast mode and reset command from fast mode are not necessary. When the device enters the acceleration mode, the device automatically set to fast mode. Therefore, the present sequence could be used for programming and detection of completion during acceleration mode.

Removing V_{ACC} from the ACC pin returns the device to normal operation. Do not remove V_{ACC} from ACC pin while programming. See "Accelerated Fast mode Programming Timing" in "■ TIMING DIAGRAM".

HiddenROM Region

The HiddenROM feature provides a Flash memory region that the system may access through a new command sequence. This is primarily intended for customers who wish to use an Electronic Serial Number (ESN) in the device with the ESN protected against modification. Once the HiddenROM region is protected, any further modification of that region becomes impossible. This ensures the security of the ESN once the product is shipped to the field. ONLY Program is possible in this area until it is protected. Once it is protected, it is impossible to unprotect, so please use this with caution.

HiddenROM area is 128 words (64 words for factory and 64 words for customer) in length and is stored at the same address of the "outermost" 4 Kwords boot sector. The device occupies the address of the 000000h - 00007Fh. After the system has written the Enter HiddenROM command sequence, the system may read the HiddenROM region by using the addresses normally occupied by the boot sector (particular area of SA0). That is, the device sends all commands that would normally be sent to the boot sector to the HiddenROM region. This mode of operation continues until the system issues the Exit HiddenROM command sequence, or until power is removed from the device. On power-up, or following a hardware reset, the device reverts to sending commands to the boot sector.

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HiddenROM area is divided into two regions, which are Factory Locked area and Customer Locked area. The Factory Locked area is 64 words (address: 000000h - 00003Fh) that is programmed and locked at Fujitsu. The Customer Locked area is also 64 words (address: 000040h - 00007Fh) that is programmed and locked at user. The Factory indicator Bit (DQ7) is used to indicate whether or not the Factory Locked area is locked when shipped from the factory. The Customer Indicator Bit (DQ6) is used to indicate whether or not the Customer Locked area is locked. The Factory Locked area can be programmed and protected at Fujitsu ONLY and is always protected when shipped from the factory regardless of the condition whether or not this area is programmed. Therefore this area has the Factory Indicator Bit (DQ7) permanently set to a "1". The Factory Locked area cannot be modified in any way. The Customer Locked area is shipped unprotected, allowing users to utilize that area in any manner they choose. The Customer Indicator Bit set to "0". Once the Customer Locked area is protected, the Customer Indicator Bit will be permanently set to "1".

<Protection>

The MBM29BS/FS12DH features several levels of sector protection, which can disable both the program and erase operations

(1) Write Protect (\overline{WP})[Hardware Protection]

The device features a hardware protection option using a write protect pin that prevents programming or erasing, regardless of the state of the sector's Persistent or Dynamic Protection Bits. The \overline{WP} pin is associated with the "outermost" 4 × 4K words on both ends of boot sectors (SA0-SA3 and SA266-SA269). The \overline{WP} pin has no effect on any other sector. When \overline{WP} is taken to V_{IL} , programming and erase operations of the "outermost" 4 × 4K words sectors on both ends are disabled. By taking \overline{WP} back to V_{IH} , the "outermost" 4 × 4K words sectors are enabled for program and erase operations, depending upon the status of the individual sector Persistent or Dynamic Protection Bits. If either of the four outermost sectors Persistent or Dynamic Protection Bits are programmed, program or erase operations are inhibited. If the sector Persistent or Dynamic Protection Bits are both erased, the four outermost sectors are available for programming or erasing as long as \overline{WP} remains at V_{IH} .

(2) ACC Protect (ACC)[Hardware Protection2]

The device has also hardware protect feature by ACC pin. When ACC is V_{IL} , all sectors are locked. Should be at V_{IH} for all other condition.

(3) New Sector Protection [Software Protection]

A command sector protection method that replaces the old V_{ID} controlled protection method.

a) Persistent Protection Bit (PPB)

A single Persistent (non-volatile) Protection Bit is assigned to a maximum four sectors (see the "sector group address table" in "■ FLEXIBLE SECTOR-ERASE ARCHITECTURE" for specific sector protection groupings). All 4 K words boot-block sectors have individual sector Persistent Protection Bits (PPBs) for greater flexibility. Each PPB is individually modifiable through the PPB Write Command.

Note : If a PPB requires erasure, all of the sector PPBs must first be preprogrammed prior to PPB erasing. All PPBs erase in parallel, unlike programming where individual PPBs are programmable. It is the responsibility of the user to perform the preprogramming operation. Otherwise, an already erased sector PPBs has the potential of being over-erased. There is no hardware mechanism to prevent sector PPBs over-erasure.

b) Dynamic Protection Bit (DPB)

A volatile protection bit is assigned for each sector. After power-up or hardware reset, the contents of all DPBs is "0". Each DPB is individually modifiable through the DPB Write Command.

When the parts are first shipped, the PPBs are cleared, the DPBs are cleared, and PPB Lock is defaulted to power up in the cleared state - meaning the PPBs are changeable.

When the device is first powered on the DPBs power up cleared (sectors not protected). The Protection State for each sector is determined by the logical OR of the PPB and the DPB related to that sector. For the sectors that have the PPBs cleared, the DPBs control whether or not the sector is protected or unprotected. By issuing the DPB Write/Erase command sequences, the DPBs will be set or cleared, thus placing each sector in the protected or unprotected state. These are the so-called Dynamic Locked or Unlocked states. They are called

dynamic states because it is very easy to switch back and forth between the protected and unprotected conditions. This allows software to easily protect sectors against inadvertent changes yet does not prevent the easy removal of protection when changes are needed. The DPBs may be set or cleared as often as needed.

PPB vs DPB

The PPBs allow for a more static, and difficult to change, level of protection. The PPBs retain their state across power cycles because they are Non-Volatile. Individual PPBs are set with a command but must all be cleared as a group through a complex sequence of program and erasing commands. The PPBs are also limited to 100 erase cycles.

The PPB Lock bit adds an additional level of protection. Once all PPBs are programmed to the desired settings, the PPB Lock may be set to “1”. Setting the PPB Lock disables all program and erase commands to the Non-Volatile PPBs. In effect, the PPB Lock Bit locks the PPBs into their current state. The only way to clear the PPB Lock is to go through a power cycle. System boot code can determine if any changes to the PPB are needed e.g. to allow new system code to be downloaded. If no changes are needed then the boot code can set the PPB Lock to disable any further changes to the PPBs during system operation.

It is possible to have sectors that have been persistently locked, and sectors that are left in the dynamic state. The sectors in the dynamic state are all unprotected. If there is a need to protect some of them, a simple DPB Write command sequence is all that is necessary. The DPB write/erase command for the dynamic sectors switch the DPBs to signify protected and unprotected, respectively. If there is a need to change the status of the persistently locked sectors, a few more steps are required. First, the PPB Lock bit must be disabled by either putting the device through a power-cycle, or hardware reset. The PPBs can then be changed to reflect the desired settings. Setting the PPB lock bit once again will lock the PPBs, and the device operates normally again.

Note : to achieve the best protection, it's recommended to execute the PPB lock bit set command early in the boot code, and protect the boot code by holding $\overline{WP} = V_{IL}$.

DPB	PPB	PPB Lock	Sector State
0	0	0	Unprotected—PPB and DPB are changeable
1	0	0	Protected—PPB and DPB are changeable
0	1	0	Protected—PPB and DPB are changeable
1	1	0	Protected—PPB and DPB are changeable
0	0	1	Unprotected—PPB not changeable, DPB is changeable
1	0	1	Protected—PPB not changeable, DPB is changeable
0	1	1	Protected—PPB not changeable, DPB is changeable
1	1	1	Protected—PPB not changeable, DPB is changeable

The above table contains all possible combinations of the DPB, PPB, and PPB lock relating to the status of the sector.

In summary, if the PPB is set, and the PPB lock is set, the sector is protected and the protection can not be removed until the next power cycle clears the PPB lock. If the PPB is cleared, the sector can be dynamically locked or unlocked. The DPB then controls whether or not the sector is protected or unprotected.

If the user attempts to program or erase a protected sector, the device ignores the command and returns to read mode. A program command to a protected sector enables status polling for approximately 1 μ s before the device returns to read mode without having modified the contents of the protected sector. An erase command to a protected sector enables status polling for approximately 50 μ s after which the device returns to read mode without having erased the protected sector.

The programming of the DPB, PPB, and PPB lock for a given sector can be verified by writing a DPB/PPB lock verify command to the device.

–DPB Status

The programming of the DPB for a given sector can be verified by writing a DPB status verify command to the device.

–PPB Status

The programming of the PPB for a given sector can be verified by writing a PPB status verify command to the device.

–PPB Lock Bit Status

The programming of the PPB Lock Bit for a given sector can be verified by writing a PPB Lock Bit status verify command to the device.

c) Persistent Protection Bit Lock (PPB Lock)

- **PPB Locked**
- **PPB Locked with Password**

A highly sophisticated protection method that requires a password before changes to certain sectors or sector groups are permitted.

All parts default to operate in the Persistent Sector Protection mode. The customer must then choose if the Persistent or Password Protection method is most desirable. There are two one-time programmable non-volatile bits that define which sector protection method will be used. If the customer decides to continue using the Persistent Sector Protection method, they must set the Persistent Sector Protection Mode Locking Bit. This will permanently set the part to operate only using Persistent Sector Protection. If the customer decides to use the password method, they must set the Password Mode Locking Bit. This will permanently set the part to operate only using password sector protection.

It is important to remember that setting either the Persistent Sector Protection Mode Locking Bit or the Password Mode Locking Bit permanently selects the protection mode. It is not possible to switch between the two methods once a locking bit has been set. It is important that one mode is explicitly selected when the device is first programmed, rather than relying on the default mode alone. This is so that it is not possible for a system program or virus to later set the Password Mode Locking Bit, which would cause an unexpected shift from the default Persistent Sector Protection Mode into the Password Protection Mode.

The \overline{WP} and ACC Hardware Protection feature is always available, independent of the software managed protection method chosen.

PPB lock bit is a global volatile bit. When set to “1”, the PPBs cannot be changed. When cleared (“0”), the PPBs are changeable. There is only one PPB Lock bit per device. The PPB Lock is cleared after power-up or hardware reset. There is no command sequence to unlock the PPB Lock.

The Persistent Protection Bit (PPB) Lock is a volatile bit that reflects the state of the Password Mode Locking Bit after power-up reset. If the Password Mode Locking Bit is set, which indicates the device is in Password Protection Mode, the PPB Lock Bit is also set after a hardware reset (\overline{RESET} asserted) or a power-up reset. The ONLY means for clearing the PPB Lock Bit in Password Protection Mode is to issue the Password Unlock command. Successful execution of the Password Unlock command clears the PPB Lock Bit, allowing for sector PPBs modifications. Asserting \overline{RESET} , taking the device through a power-on reset, or issuing the PPB Lock Bit Set command sets the PPB Lock Bit back to a “1”.

If the Password Mode Locking Bit is not set, indicating Persistent Sector Protection Mode, the PPB Lock Bit is cleared after power-up or hardware reset. The PPB Lock Bit is set by issuing the PPB Lock Bit Set command. Once set the only means for clearing the PPB Lock Bit is by issuing a hardware or power-up reset. The Password Unlock command is ignored in Persistent Sector Protection Mode.

-Password and Password Mode Locking Bit

In order to select the Password sector protection scheme, the customer must first program the password. Fujitsu recommends that the password be somehow correlated to the unique Electronic Serial Number (ESN) of the particular flash device. Each ESN is different for every flash device; therefore each password should be different for every flash device. While programming in the password region, the customer may perform Password Verify operations.

Once the desired password is programmed in, the customer must then set the Password Mode Locking Bit. This operation achieves two objectives:

- (1) It permanently sets the device to operate using the Password Protection Mode. It is not possible to reverse this function.
- (2) It also disables all further commands to the password region. All program, and read operations are ignored.

Both of these objectives are important, and if not carefully considered, may lead to unrecoverable errors. The user must be sure that the Password Protection method is desired when setting the Password Mode Locking Bit. More importantly, the user must be sure that the password is correct when the Password Mode Locking Bit is set. Due to the fact that read operations are disabled, there is no means to verify what the password is afterwards. If the password is lost after setting the Password Mode Locking Bit, there will be no way to clear the PPB Lock bit.

The Password Mode Locking Bit, once set, prevents reading the 64-bit password on the DQ bus and further password programming. The Password Mode Locking Bit is not erasable. Once Password Mode Locking Bit is programmed, the Persistent Sector Protection Locking Bit is disabled from programming, guaranteeing that no changes to the protection scheme are allowed.

64-bit Password

The 64-bit Password is located in its own memory space and is accessible through the use of the Password Program and Verify commands (see "Password Verify Command"). The password function works in conjunction with the Password Mode Locking Bit, which when set, prevents the Password Verify command from reading the contents of the password on the pins of the device.

-Persistent Sector Protection Mode Locking Bit

Like the password mode locking bit, a Persistent Sector Protection mode locking bit exists to guarantee that the device remain in software sector protection. Once set, the Persistent Sector Protection locking bit prevents programming of the password protection mode locking bit. This guarantees that a hacker could not place the device in password protection mode.

■ COMMAND DEFINITIONS

Device operations are selected by writing specific address and data sequences into the command register. Some commands require Bank Address (BA) input. When command sequences are input into a bank reading, the commands have priority over the reading. “MBM29BS/FS12DH Command Definitions Table” shows the valid register command sequences. Note that the Erase Suspend (B0h) and Erase Resume (30h) commands are valid only while the Sector Erase operation is in progress. Moreover, Read/Reset commands are functionally equivalent, resetting the device to the read mode. Please note that commands are always written at DQ₇ to DQ₀ and DQ₁₅ to DQ₈ bits are ignored.

Read/Reset Command

In order to return from Autoselect mode or Exceeded Timing Limits (DQ₅ = 1) to Read/Reset mode, verify mode of sector protect commands the Reset operation is initiated by writing the Reset command sequence into the command register. Microprocessor read cycles retrieve array data from the memory. The device remains enabled for reads until the command register contents are altered.

The device will automatically power-up in the Asynchronous Read/Reset state. In this case, a command sequence is not required to read data. Standard microprocessor read cycles will retrieve array data. Refer to the AC Read Characteristics and Waveforms for specific timing parameters.

Configuration Register Set Command

The device uses a configuration register to set the various burst parameters: number of wait states, burst read mode (burst length), active clock edge, RDY configuration, and synchronous mode active. The configuration register must be set before the device will enter burst mode.

The configuration register is loaded with a three-cycle command sequence. The first two cycles are standard unlock sequences. On the third cycle, the data should be C0h, address bits A₁₁ to A₀ should be 555h, address bits A₁₉ to A₁₂ set the code to be latched. The device will power up or after a hardware reset with the default setting, which is in asynchronous mode. The register must be set before the device can enter synchronous mode. The configuration register can not be changed during device operations (program, erase, or New Sector Protection).

Read Mode Setting

On power-up or hardware reset, the device is set to be in asynchronous read mode. This setting allows the system to enable or disable burst mode during system operations. Address A₁₉ determines this setting: "1" for asynchronous mode, "0" for synchronous mode.

Programmable Wait State Configuration Setting

The programmable wait state feature informs the device of the number of clock cycles that must elapse after \overline{AVD} is driven active before data will be available. This value is determined by the input frequency of the device. Address bits A₁₄ to A₁₂ determine the setting (see “Third Cycle Address/Data Table”). The wait state command sequence instructs the device to set a particular number of clock cycles for the initial access in burst mode. The number of wait states that should be programmed into the device is directly related to the clock frequency.

Third Cycle Address/Data Table

A ₁₄	A ₁₃	A ₁₂	Total Initial Access Cycles
0	0	0	2
0	0	1	3
0	1	0	4
0	1	1	5
1	0	0	6
1	0	1	7
1	1	0	Reserved
1	1	1	Reserved

- Handshaking Option

If the device is equipped with the handshaking option, the host system should set address bits (A_{14}, A_{13}, A_{12}) = (0, 1, 0) for a clock frequency of 54/66 MHz for the system/device to execute at maximum speed. The device will automatically delay RDY by one additional clock cycle when the starting address is odd.

“Third Cycle Address/Data Table” describes the typical number of clock cycles (wait states) for various conditions.

Wait States for Handshaking Table

Conditions at Address	Typical No. of Clock Cycles after \overline{AVD} Low
	66/54 MHz
Initial address is even	4
Initial address is odd	5

The autoselect function allows the host system to determine whether the flash device is enabled for handshaking. See the "Autoselect Command" section for more information.

- Non-Handshaking Option

For optimal burst mode performance on devices without the handshaking option, the host system must set the appropriate number of wait states in the flash device depending on the clock frequency.

Wait States for Non-Handshaking Table

Conditions at Address	Typical No. of Clock Cycles after \overline{AVD} Low
	66/54 MHz
Initial address is even	5
Initial address is odd	5

Burst Read Mode Configuration Setting(Burst Length)

The device supports three different burst read modes: 8, 16, and 32 word linear wrap around modes. A continuous sequence begins at the starting address and advances the address pointer until the burst operation is complete.

For example, an eight-word linear burst with wrap around begins on the starting burst address written to the device and then advances to the next 8-word boundary. The address pointer then returns to the 1st word after the previous eight-word boundary, wrapping through the starting location. The sixteen- and thirty-two linear wrap around modes operate in a fashion similar to the eight-word mode.

“Wait States for Handshaking Table” shows the address bits and settings for the three burst read modes.

Burst Read Mode Settings Table

Burst Modes	Address Bits	
	A_{16}	A_{15}
8-word linear wrap around	0	1
16-word linear wrap around	1	0
32-word linear wrap around	1	1

Active Clock Edge Configuration Setting

The device can be set so that either the rising clock edge or falling clock edge is active for all synchronous access. Address bit A_{17} determines this setting; "1" for rising active, "0" for falling active.

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RDY Configuration Setting

The device can be set so that RDY goes active either with valid data or one data cycle before active data. Address bit A₁₈ determines this setting; "1" for RDY active with data, "0" for RDY active one clock cycle before valid data. "Configuration Register Table" shows the address bits that determine the configuration register settings for various device functions.

Configuration Register Table

Address Bit	Function	Settings (Binary)
A ₁₉	Set Device Read Mode	0 = Synchronous Read (Burst Mode) Enabled 1 = Asynchronous Mode (Default)
A ₁₈	RDY	0 = RDY active one clock cycle before data 1 = RDY active with data
A ₁₇	Clock	0 = Burst starts and data is output on the falling edge of CLK 1 = Burst starts and data is output on the rising edge of CLK
A ₁₆	Burst Read Mode	00 = Reserved
A ₁₅		01 = 8-word linear with wrap around 10 = 16-word linear with wrap around 11 = 32-word linear with wrap around
A ₁₄	Programmable Wait State	000 = Data is valid on the 2th active CLK edge after \overline{AVD} transition to V _{IH}
A ₁₃		001 = Data is valid on the 3th active CLK edge after \overline{AVD} transition to V _{IH}
A ₁₂		010 = Data is valid on the 4th active CLK edge after \overline{AVD} transition to V _{IH}
		011 = Data is valid on the 5th active CLK edge after \overline{AVD} transition to V _{IH}
		100 = Data is valid on the 6th active CLK edge after \overline{AVD} transition to V _{IH}
		101 = Data is valid on the 7th active CLK edge after \overline{AVD} transition to V _{IH}
		110 = Reserved
		111 = Reserved

Autoselect Command

Flash memories are intended for use in applications where the local CPU alters memory contents. Therefore, manufacture and device codes must be accessible while the device resides in the target system. PROM programmers typically access the signature codes by raising A₉ to a higher voltage. However, multiplexing high voltage onto the address lines is not generally desired system design practice.

The device contains an Autoselect command operation to supplement traditional PROM programming methodology. The operation is initiated by writing the Autoselect command sequence into the command register.

The Autoselect command sequence is initiated first by writing two unlock cycles. This is followed by a third write cycle that contains the bank address (BA) and the Autoselect command. Then the manufacture and device codes can be read from the bank, and actual data from the memory cell can be read from another bank. The higher order address (A₂₂, A₂₁, A₂₀) required for reading out the manufacture and device codes demands the bank address (BA) set at the third write cycle.

Following the command write, a read cycle from address (BA)00h returns the manufacturer's code (Fujitsu= 04h). And a read cycle at address (BA)01h outputs device code. When 227Eh was output, this indicates that two additional codes, called Extended Device Codes will be required. Therefore the system may continue reading out these Extended Device Codes at the address of (BA) 0Eh, as well as at (BA) 0Fh. (Refer to "MBM29BS/FS12DH Sector Protection Verify Autoselect Codes Table" and "Extended Autoselect Code Table" in "■ DEVICE BUS OPERATION".)

The sector state (PPB protection or PPB unprotection) will be informed by address (BA) XX02h. Scanning the sector group addresses (A₂₂, A₂₁, A₂₀, A₁₉, A₁₈, A₁₇, A₁₆, A₁₅, A₁₄, A₁₃, and A₁₂) while (A₇, A₆, A₅, A₄, A₃, A₂, A₁, A₀) = (0, 0, 0, 0, 0, 0, 1, 0) will produce a logical "1" at device output DQ₀ for a protected sector group. The programming

verification should be performed by verifying sector group protection on the protected sector. (See “MBM29BS/FS12DH User Bus Operations Table” in “■ DEVICE BUS OPERATION”.)

The manufacture and device codes can be read from the selected bank. To read the manufacture and device codes and sector protection status from a non-selected bank, it is necessary to write the Read/Reset command sequence into the register. Autoselect command should then be written into the bank to be read.

If the software (program code) for Autoselect command is stored in the Flash memory, the device and manufacture codes should be read from the other bank, which does not contain the software. No subsequent data will be made available if the autoselect data is read in synchronous mode.

To terminate the operation, it is necessary to write the Read/Reset command sequence into the register. To execute the Autoselect command during the operation, Read/Reset command sequence must be written before the Autoselect command.

Word Programming Command

The device is programmed on word-by-word basis. Programming is a four bus cycle operation. There are two “unlock” write cycles. These are followed by the program set-up command and data write cycles. Upon executing the Embedded Program Algorithm command sequence, the system is not required to provide further controls or timings. The device will automatically provide adequate internally generated program pulses and verify the programmed cell margin.

The system can determine the status of the program operation by using $\overline{DQ_7}$ (Data Polling), DQ_6 (Toggle Bit). The Data Polling and Toggle Bit must be performed at the memory location which is being programmed.

The automatic programming operation is completed when the data on DQ_7 is equivalent to data written to this bit at which time the device returns to the read mode and addresses are no longer latched (see “Hardware Sequence Flags Table”). Therefore, the device requires that a valid address to the device be supplied by the system in this particular instance. Hence, Data Polling must be performed at the memory location which is being programmed. If hardware reset occurs during the programming operation, the data being written is not guaranteed.

Programming is allowed in any sequence and across sector boundaries. Beware that a data “0” cannot be programmed back to a “1”. Attempting to do so may either hang up the device or result in an apparent success according to the data polling algorithm but a read from Read/Reset mode will show that the data is still “0”. Only erase operations can convert from “0”s to “1”s.

“Embedded Program™ Algorithm” in “■ FLOW CHART” illustrates the Embedded Program™ Algorithm using typical command strings and bus operations.

Chip Erase Command

Chip erase is a six-bus cycle operation. There are two “unlock” write cycles. These are followed by writing the “set-up” command. Two more “unlock” write cycles are then followed by the chip erase command.

Chip erase does not require the user to program the device prior to erase. Upon executing the Embedded Erase Algorithm command sequence the device will automatically program and verify the entire memory for an all zero data pattern prior to electrical erase. (Preprogram Function). The system is not required to provide any controls or timings during these operations.

The system can determine the status of the erase operation by using $\overline{DQ_7}$ (Data Polling), or DQ_6 (Toggle Bit). The chip erase begins on the rising edge of the last \overline{WE} , whichever happens first in the command sequence and terminates when the data on DQ_7 is “1” (See Write Operation Status section.) at which time the device returns to read the mode.

Chip Erase Time; Sector Erase Time × All sectors + Chip Program Time (Preprogramming)

“Embedded Erase™ Algorithm” in “■ FLOW CHART” illustrates the Embedded Erase™ Algorithm using typical command strings and bus operations.

Sector Erase Command

Sector erase is a six bus cycle operation. There are two “unlock” write cycles. These are followed by writing the “set-up” command. Two more “unlock” write cycles are then followed by the Sector Erase command. After time-out of “t_{row}” from the rising edge of the last sector erase command, the sector erase operation will begin.

Multiple sectors may be erased concurrently by writing the six bus cycle operations on “MBM29BS/FS12DH Command Definitions Table” in “■ DEVICE BUS OPERATION”. This sequence is followed with writes of the Sector Erase command to addresses in other sectors desired to be concurrently erased. The time between writes must be less than “t_{row}” otherwise that command will not be accepted and erasure will not start. It is recommended that processor interrupts be disabled during this time to guarantee this condition. The interrupts can be re-enabled after the last Sector Erase command is written. A time-out of “t_{row}” from the rising edge of last \overline{WE} will initiate the execution of the Sector Erase command(s). If another falling edge of \overline{CE} or \overline{WE} , whichever happens first occurs within the “t_{row}” time-out window the timer is reset. (Monitor DQ₃ to determine if the sector erase timer window is still open, see section DQ₃, Sector Erase Timer.) Any command other than Sector Erase or Erase Suspend during this time-out period will reset the device to the read mode, ignoring the previous command string. Resetting the device once execution has begun will corrupt the data in the sector. In that case, restart the erase on those sectors and allow them to complete. (Refer to Write Operation Status section for Sector Erase Timer operation.) Loading the sector erase buffer may be done in any sequence and with any number of sectors.

Sector erase does not require the user to program the device prior to erase. The device automatically programs all memory locations in the sector(s) to be erased prior to electrical erase (Preprogram function). When erasing a sector or sectors the remaining unselected sectors are not affected. The system is not required to provide any controls or timings during these operations.

The system can determine the status of the erase operation by using DQ₇ ($\overline{\text{Data Polling}}$), or DQ₆ (Toggle Bit).

The sector erase begins after the “t_{row}” time out from the rising edge of \overline{WE} for the last sector erase command pulse and terminates when the data on DQ₇ is “1” (See Write Operation Status section.) at which time the device returns to the read mode. Data polling and Toggle Bit must be performed at an address within any of the sectors being erased.

Multiple Sector Erase Time; [Sector Erase Time + Sector Program Time (Preprogramming)] × Number of Sector Erase.

In case of multiple sector erase across bank boundaries, a read from the bank (read-while-erase) to which sectors being erased belong cannot be performed.

“Embedded Erase™ Algorithm” in “■ FLOW CHART” illustrates the Embedded Erase™ Algorithm using typical command strings and bus operations.

Erase Suspend/Resume Command

The Erase Suspend command allows the user to interrupt a Sector Erase operation and then perform data reads from or programs to a sector not being erased. This command is applicable ONLY during the Sector Erase operation which includes the time-out period for sector erase. The Erase Suspend command will be ignored if written during the Chip Erase operation or Embedded Program Algorithm. Writing the Erase Suspend command (B0h) during the Sector Erase time-out results in immediate termination of the time-out period and suspension of the erase operation.

Writing the Erase Resume command (30h) resumes the erase operation. The addresses are “DON’T CARES” when writing the Erase Suspend or Erase Resume command. When the Erase Suspend command is written during the Sector Erase operation, the device will take a maximum of “t_{SPD}” to suspend the erase operation. When the device has entered the erase-suspended mode, the DQ₇ bit will be at logic “1”, and DQ₆ will stop toggling. The user must use the address of the erasing sector for reading DQ₆ and DQ₇ to determine if the erase operation has been suspended. Further writes of the Erase Suspend command are ignored.

When the erase operation has been suspended, the device defaults to the erase-suspend-read mode. Reading data in this mode is the same as reading from the standard read mode except that the data must be read from

sectors that have not been erase-suspended. Successively reading from the erase-suspended sector while the device is in the erase-suspend-read mode will cause DQ₂ to toggle. (See the section on DQ₂.)

After entering the erase-suspend-read mode, the user can program the device by writing the appropriate command sequence for Program. This program mode is known as the erase-suspend-program mode. Again, programming in this mode is the same as programming in the regular Program mode except that the data must be programmed to sectors that are not erase-suspended. Successively reading from the erase-suspended sector while the device is in the erase-suspend-program mode will cause DQ₂ to toggle. The end of the erase-suspended Program operation is detected by the $\overline{\text{Data}}$ polling of DQ₇ or by the Toggle Bit I (DQ₆) which is the same as the regular Program operation. Note that DQ₇ must be read from the Program address while DQ₆ can be read from any address within Bank being programmed (erase-suspend program).

To resume the operation of Sector Erase, the Resume command (30h) should be written. Any further writes of the Resume command at this point will be ignored. Another Erase Suspend command can be written after the chip has resumed erasing.

Extended Command

(1) Fast Mode

The device has Fast Mode function. This mode dispenses with the initial two unlock cycles required in the standard program command sequence writing Fast Mode command into the command register. In this mode, the required bus cycle for programming is two cycles instead of four bus cycles in standard program command. Do not write any other commands, except Fast Program Command and Reset from Fast Program Command. The read operation is also executed after exiting this mode. To exit this mode, it is necessary to write Fast Mode Reset command into the command register. (Refer to “Embedded Programming Algorithm for Fast Mode” in “■ FLOW CHART”.) The V_{CC} active current is required even $\overline{\text{CE}} = V_{\text{IH}}$ during Fast Mode.

(2) Fast Programming

During Fast Mode, the programming can be executed with two bus cycles operation. The Embedded Program Algorithm is executed by writing program set-up command (A0h) and data write cycles (PA/PD). (Refer to “Embedded Programming Algorithm for Fast Mode” in “■ FLOW CHART”.)

(3) CFI (Common Flash Memory Interface)

The CFI (Common Flash Memory Interface) specification outlines device and host system software interrogation handshake which allows specific vendor-specified software algorithms to be used for entire families of device. This allows device-independent, JEDEC ID-independent, and forward-and backward-compatible software support for the specified flash device families. Refer to CFI specification in detail.

The operation is initiated by writing the query command (98h) into the command register. Following the command write, a read cycle from specific address retrieves device information. Please note that output data of upper byte (DQ₁₅ to DQ₈) is “0” in word mode (16 bit) read. Refer to the CFI code table. To terminate operation, it is necessary to write the Read/Reset command sequence into the register.

HiddenROM Entry Command

The device has a HiddenROM area with One Time Protect function. This area is to enter the security code and to enable the change of the code once set. Program/erase is possible in this area until it is protected. However, once it is protected, it is impossible to unprotect, so please use this with caution.

The HiddenROM area is 128 words (64 words for factory and 64 words for customer). This area is normally the “outermost” 4 Kwords boot block area in Bank A. Therefore, write the HiddenROM entry command sequence to enter the HiddenROM area. It is called HiddenROM mode when the HiddenROM area appears.

The following commands are not allowed when the HiddenROM is enabled.

1. CFI
2. Set to Fast Mode
3. Fast Program
4. Reset from Fast Mode
5. Sector Erase Suspend
6. Sector Erase Resume
7. Chip Erase Command

HiddenROM Program Command

To program the data to the HiddenROM area, write the HiddenROM program command sequence during HiddenROM mode. This command is the same as the program command in usual except to write the command during HiddenROM mode. Therefore the detection of completion method is the same as in the past, using the DQ₇ data polling, and DQ₆ toggle bit. Need to pay attention to the address to be programmed. If the address other than the HiddenROM area is selected to program, data of the address will be changed.

HiddenROM Protect Command

To protect the HiddenROM area, write the HiddenROM Protect command sequence during HiddenROM mode. After issuing "OPBP/48h" at 4th bus cycle, the device requires approximately 150us time out period for protecting HiddenROM area. Then by writing "OPBP/48h" at 5th bus cycle, the device outputs verify data at DQ0. If DQ0=1 then HiddenROM area is protected. If not, then the user needs to repeat this program sequence from the 4th cycle of "OPBP/48h".

Password Program Command

The Password Program Command permits programming the password that is used as part of the hardware protection scheme. The actual password is 64-bits long. 4 Password Program commands are required to program the password. The user must enter the unlock cycle, password program command (38h) and the program address/data for each portion of the password when programming. There are no provisions for entering the 2-cycle unlock cycle, the password program command, and all the password data. There is no special addressing order required for programming the password. Also, when the password is undergoing programming, Simultaneous Operation is disabled. Read operations to any memory location will return the programming status. Once the Password is written and verified, the Password Mode Locking Bit must be set in order to prevent verification. The Password Program Command is only capable of programming "0"s. Programming a "1" after a cell is programmed as a "0" results in a time-out by the Embedded Program Algorithm with the cell remaining as a "0". The password is all F's when shipped from the factory. All 64-bit password combinations are valid as a password. Writing the HiddenROM Exit command returns the device back to normal operation.

Password Verify Command

The Password Verify Command is used to verify the Password. The Password is verifiable only when the Password Mode Locking Bit is not programmed. If the Password Mode Locking Bit is programmed and the user attempts to verify the Password, the device will always drive all F's onto the DQ data bus.

Also, the device will not operate in Simultaneous Operation when the Password Verify command is executed. Only the password is returned regardless of the bank address. The lower two address bits (A₁:A₀) are valid during the Password Verify. Writing the HiddenROM Exit command returns the device back to normal operation.

Password Protection Mode Locking Bit Program Command

The Password Protection Mode Locking Bit Program Command programs the Password Protection Mode Locking Bit, which prevents further verifies or updates to the Password. Once programmed, the Password Protection Mode Locking Bit cannot be erased and the Persistent Sector Protection Locking Bit program circuitry is disabled, thereby forcing the device to remain in the Password Protection mode. After issuing "PL/68h" at 4th bus cycle, the device requires approximately 150μs time out period for programming the Password Protection Mode Locking Bit. Then by writing "PL/48h" at 5th bus cycle, the device outputs verify data at DQ0. If DQ0=1 then Password Protection Mode Locking Bit is programmed. If not, then the user needs to repeat this program sequence from the 4th cycle of "PL/68h". Exiting the Password Protection Mode Locking Bit Program command is accomplished by writing the HiddenROM Exit command.

Persistent Sector Protection Mode Locking Bit Program Command

The Persistent Sector Protection Mode Locking Bit Program Command programs the Persistent Sector Protection Mode Locking Bit, which prevents the Password Mode Locking Bit from ever being programmed. By disabling the program circuitry of the Password Mode Locking Bit, the device is forced to remain in the Persistent Sector Protection mode of operation, once this bit is set. After issuing "SPML/68h" at 4th bus cycle, the device requires approximately 150 μs time out period for programming the Persistent Protection Mode Locking Bit. Then by writing "SPML/48h" at 5th bus cycle, the device outputs verify data at DQ0. If DQ0=1 then Persistent Protection

Mode Locking Bit is programmed. If not, then the user needs to repeat this program sequence from the 4th cycle of "SPML/68h". Exiting the Persistent Protection Mode Locking Bit Program command is accomplished by writing the HiddenROM Exit command.

PPB Lock Bit Set Command

The PPB Lock Bit Set command is used to set the PPB Lock bit if it is cleared either at reset or if the Password Unlock command was successfully executed. There is no PPB Lock Bit Clear command. Once the PPB Lock Bit is set, it cannot be cleared unless the device is taken through a power-on clear or the Password Unlock command is executed. If the Password Mode Locking Bit is set, the PPB Lock Bit status is reflected as set, even after a power-on reset cycle. Exiting the PPB Lock Bit Set command is accomplished by writing the HiddenROM Exit command.

DPB Write(Erase) Command

The DPB Write command is used to set or clear a DPB for a given sector. The high order address bits (A_{22} to A_{12}) are issued at the same time as the code 01h or 00h on DQ_7 to DQ_0 . All other DQ data bus pins are ignored during the data write cycle. The DPBs are modifiable at any time, regardless of the state of the PPB or PPB Lock Bit. The DPBs are cleared at power-up or hardware reset. Exiting the DPB Write command is accomplished by writing the HiddenROM Exit command.

DPB verify command

DPB verify command is used to verify the status of a DPB for given sector. Scanning the sector addresses (SA) will produce a logical "1" at the device output DQ_0 for a protected sector. Otherwise the device will produce "0" at DQ_0 for the sector which is not protected. Writing the HiddenROM Exit Command returns the device back to normal operation.

PPB Lock Bit verify command

PPB Lock Bit verify command is used to verify the status of a PPB Lock Bit. A logical "1" at the device output DQ_1 indicates that the PPB Lock Bit is set. If PPB Lock Bit is not set, DQ_1 will output "0". Writing the HiddenROM Exit Command returns the device back to normal operation.

Password Unlock Command

The Password Unlock command is used to clear the PPB Lock Bit so that the PPBs can be unlocked for modification, thereby allowing the PPBs to become accessible for modification. The exact password must be entered in order for the unlocking function to occur. This command cannot be issued any faster than $2\ \mu\text{s}$ at a time to prevent a hacker from running through the all 64-bit combinations in an attempt to correctly match a password. If the command is issued before the $2\ \mu\text{s}$ execution window for each portion of the unlock, the command will be ignored.

The Password Unlock function is accomplished by writing Password Unlock command and data to the device to perform the clearing of the PPB Lock Bit. A_0 and A_1 are used to determine the 16 bit data quantity is used to match separated 16 bits. Writing the Password Unlock command is address order specific. In other words, the lowers address $A_1:A_0 = 00$, the next cycle command is to $A_1:A_0 = 01$, then to $A_1:A_0 = 10$, and finally to $A_1:A_0 = 11$. Writing out of sequence results in the Password Unlock not returning a match with the password and the PPB Lock Bit remains set.

Once the Password Unlock command is entered, the $\overline{\text{RY}}/\overline{\text{BY}}$ pin goes LOW indicating that the device is busy. Also, reading the Bank A results in the DQ_6 pin toggling, indicating that the Password Unlock function is in progress. Reading the other bank returns actual array data. Approximately $2\ \mu\text{s}$ is required for each portion of the unlock. Once the first portion of the password unlock completes ($\overline{\text{RY}}/\overline{\text{BY}}$ is not driven and DQ_6 does not toggle when read), the next cycle is issued, only this time with the next part of the password. Seven cycles Password Unlock commands are required to successfully clear the PPB Lock Bit. As with the first Password Unlock command, the $\overline{\text{RY}}/\overline{\text{BY}}$ signal goes LOW and reading the device results in the DQ_6 pin toggling on successive read operations until complete. It is the responsibility of the microprocessor to keep track of the number of Password Unlock cycles, the order, and when to read the PPB Lock bit to confirm successful password unlock. Writing the HiddenROM Exit Command returns the device back to normal operation.

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PPB Program Command

The PPB Program command is used to program, or set, a given PPB. Each PPB is individually programmed (but is bulk erased with the other PPBs). The specific sector address (A_{22} to A_{12}) are written at the same time as the program command 60h. If the PPB Lock Bit is set and the corresponding PPB is set for the sector, the PPB Program command will not execute and the command will time-out without programming the PPB. After issuing "SGA+WP/68h" at 4th bus cycle, the device requires approximately 150 μ s time out period for programming the PPB. Then by writing "SGA+WP/48h" at 5th bus cycle, the device outputs verify data at DQ0. If DQ0=1 then PPB is programmed. If not, then the user needs to repeat this program sequence from the 4th cycle of "SGA+WP/68h".

The PPB Program command does not follow the Embedded Program algorithm. Writing the HiddenROM Exit Command returns the device back to normal operation.

All PPB Erase Command

The All PPB Erase command is used to erase all PPBs in bulk. There is no means for individually erasing a specific PPB. Unlike the PPB program, no specific sector address is required. However, when the PPB erase command is written (60h), all Sector PPBs are erased in parallel. If the PPB Lock Bit is set the ALL PPB Erase command will not execute and the command will time-out without erasing the PPBs. After issuing "WPE/60h" at 4th bus cycle, the device requires approximately 1.5ms time out period for programming the PPB. Then by writing "WPE/40h" at 5th bus cycle, the device outputs verify data at DQ0. If DQ0=0 then PPB is successfully erased. If not, then the user needs to repeat this program sequence from the 4th cycle of "WPE/60h".

It is the responsibility of the user to preprogram all PPBs prior to issuing the All PPB Erase command. If the user attempts to erase a cleared PPB, over-erasure may occur making it difficult to program the PPB at a later time. Also note that the total number of PPB program/erase cycles is limited to 100 cycles. Cycling the PPBs beyond 100 cycles is not guaranteed. Writing the HiddenROM Exit Command returns the device back to normal operation.

WRITE OPERATION STATUS

Detailed in "Hardware Sequence Flags Table" are all the status flags which can determine the status of the bank for the current mode operation. The read operation from the bank which doesn't operate Embedded Algorithm returns data of memory cells. These bits offer a method for determining whether an Embedded Algorithm is properly completed. The information on DQ₂ is address-sensitive. This means that if an address from an erasing sector is consecutively read, the DQ₂ bit will toggle. However, DQ₂ will not toggle if an address from a non-erasing sector is consecutively read. This allows users to determine which sectors are in erase and which are not.

The status flag is not output from banks (non-busy banks) which do not execute Embedded Algorithms. For example, a bank (busy bank) is executing an Embedded Algorithm. When the read sequence is [1] < busy bank >, [2] < non-busy bank >, [3] < busy bank >, the DQ₆ toggles in the case of [1] and [3]. In case of [2], the data of memory cells are output. In the erase-suspend read mode with the same read sequence, DQ₆ will not be toggled in [1] and [3].

Hardware Sequence Flags Table

Status		DQ ₇	DQ ₆	DQ ₅	DQ ₃	DQ ₂	
In Progress	Embedded Program Algorithm	$\overline{DQ_7}$	Toggle	0	0	No Toggle* ³	
	Embedded Erase Algorithm	Erase Sector	0	Toggle	0	1	Toggle* ¹
		Non-Erase Sector					No Toggle* ³
	Erase Suspended Mode	Erase Suspend Read (Erase Suspended Sector)	1	No Toggle* ³	0	0	Toggle
		Erase Suspend Read (Non-Erase Suspended Sector)	Data	Data	Data	Data	Data
Erase Suspend Program (Non-Erase Suspended Sector)		$\overline{DQ_7}$	Toggle	0	0	No Toggle* ^{2,*3}	
Exceeded Time Limits	Embedded Program Algorithm	$\overline{DQ_7}$	Toggle	1	0	No Toggle* ³	
	Embedded Erase Algorithm	0	Toggle	1	1	N/A	
	Erase Suspended Mode	Erase Suspend Program (Non-Erase Suspended Sector)	$\overline{DQ_7}$	Toggle	1	0	N/A

*1: Successive reads from the erasing or erase-suspend sector will cause DQ₂ to toggle.

*2: Reading from non-erase suspend sector address will indicate logic “1” at the DQ₂ bit.

*3: When the device is set to Asynchronous mode, these status flags should be read by \overline{CE} toggle.

DQ₇

Data Polling

The device features \overline{Data} Polling as a method to indicate to the host that the Embedded Algorithms are in progress or completed. During the Embedded Program Algorithm, an attempt to read the device will produce a complement of data last written to DQ₇. Upon completion of the Embedded Program Algorithm, an attempt to read the device will produce true data last written to DQ₇. During the Embedded Erase Algorithm, an attempt to read the device will produce a “0” at the DQ₇ output. Upon completion of the Embedded Erase Algorithm, an attempt to read device will produce a “1” on DQ₇. The flowchart for \overline{Data} Polling (DQ₇) is shown in “Data Polling Algorithm” in “■ FLOW CHART”.

For programming, the \overline{Data} Polling is valid after the rising edge of the fourth write pulse in the four write pulse sequences.

For chip erase and sector erase, the \overline{Data} Polling is valid after the rising edge of the sixth write pulse in the six write pulse sequences. \overline{Data} Polling must be performed at sector addresses of sectors being erased, not protected sectors. Otherwise the status may become invalid.

If a program address falls within a protected sector, \overline{Data} Polling on DQ₇ is active for approximately 1 μs, then that bank returns to the read mode. After an erase command sequence is written, if all sectors selected for erasing are protected, \overline{Data} Polling on DQ₇ is active for approximately 400 μs, then the bank returns to read mode.

Once the Embedded Algorithm operation is close to being completed, the device data pins (DQ₇) may change asynchronously while the output enable (\overline{OE}) is asserted low. This means that device is driving status information on DQ₇ at one instant, and then that byte’s valid data at the next instant. Depending on when the system samples the DQ₇ output, it may read the status or valid data. Even if device has completed the Embedded Algorithm operation and DQ₇ has a valid data, data outputs on DQ₀ to DQ₆ may still be invalid. The valid data on DQ₀ to DQ₇ will be read on successive read attempts.

The \overline{Data} Polling feature is active only during the Embedded Programming Algorithm, Embedded Erase Algorithm or sector erase time-out. (See “Hardware Sequence Flags Table”.)

See “ \overline{Data} Polling Timings/Toggle Bit Timings (During Embedded Algorithm)” and “Synchronous \overline{Data} Polling Timings/Toggle Bit Timings” in “■ TIMING DIAGRAM” for the \overline{Data} Polling timing specifications and diagrams.

DQ₆

Toggle Bit I

The device also features the “Toggle Bit I” as a method to indicate to the host system that the Embedded Algorithms are in progress or completed.

During Embedded Program or Erase Algorithm cycle, successive attempts to read (\overline{CE} toggling) data from the busy bank will result in DQ₆ toggling between one and zero. Once the Embedded Program or Erase Algorithm cycle is completed, DQ₆ will stop toggling and valid data will be read on the next successive attempts. During programming, the Toggle Bit I is valid after the rising edge of the fourth write pulse in the four write pulse sequences. For chip erase and sector erase, the Toggle Bit I is valid after the rising edge of the sixth write pulse in the six write pulse sequences. The Toggle Bit I is active during the sector time out.

In programming, if the sector being written is protected, the toggle bit will toggle for about 1 μ s and then stop toggling with data unchanged. In erase, the device will erase all selected sectors except for protected ones. If all selected sectors are protected, the chip will toggle the toggle bit for about 400 μ s and then drop back into read mode, having data kept remained.

\overline{CE} toggling will cause DQ₆ to toggle. In addition, an Erase Suspend/Resume command will cause DQ₆ to toggle.

The system can use DQ₆ to determine whether a sector is actively erased or is erase-suspended. When a bank is actively erased (that is, the Embedded Erase Algorithm is in progress), DQ₆ toggles. When a bank enters the Erase Suspend mode, DQ₆ stops toggling. Successive read cycles during erase-suspend-program cause DQ₆ to toggle.

To operate toggle bit function properly, \overline{CE} must be high when bank address is changed.

See “Data Polling Timings/Toggle Bit Timings (During Embedded Algorithm)” and “Synchronous Data Polling Timings/Toggle Bit Timings” in “■ TIMING DIAGRAM” for the Toggle Bit I timing specifications and diagrams.

DQ₅

Exceeded Timing Limits

DQ₅ will indicate if the program or erase time has exceeded the specified limits (internal pulse count). Under these conditions DQ₅ will produce “1”. This is a failure condition indicating that the program or erase cycle was not successfully completed. Data Polling is only operating function of the device under this condition. The \overline{CE} circuit will partially power down device under these conditions (to approximately 2 mA). The \overline{OE} and \overline{WE} pins will control the output disable functions as described in “MBM29BS/FS12DH User Bus Operations Table” in “■ DEVICE BUS OPERATION”.

The DQ₅ failure condition may also appear if a user tries to program a non-blank location without pre-erase. In this case the device locks out and never completes the Embedded Algorithm operation. Hence, the system never reads valid data on DQ₇ bit and DQ₆ never stop toggling. Once the device has exceeded timing limits, the DQ₅ bit will indicate a “1”. Please note that this is not a device failure condition since the device was incorrectly used. If this occurs, reset device with the command sequence.

DQ₃

Sector Erase Timer

After completion of the initial sector erase command sequence, sector erase time-out begins. DQ₃ will remain low until the time-out is completed. Data Polling and Toggle Bit are valid after the initial sector erase command sequence.

If Data Polling or the Toggle Bit I indicates that a valid erase command has been written, DQ₃ may be used to determine whether the sector erase timer window is still open. If DQ₃ is high (“1”) the internally controlled erase cycle has begun. If DQ₃ is low (“0”), the device will accept additional sector erase commands. To insure the command has been accepted, the system software should check the status of DQ₃ prior to and following each subsequent Sector Erase command. If DQ₃ were high on the second status check, the command may not have been accepted.

See “Configuration Register Table” : Hardware Sequence Flags.

DQ₂

Toggle Bit II

This toggle bit II, along with DQ₆, can be used to determine whether the device is in the Embedded Erase Algorithm or in Erase Suspend.

Successive reads from the erasing sector will cause DQ₂ to toggle during the Embedded Erase Algorithm. If the device is in the erase-suspended-read mode, successive reads from the erase-suspended sector will cause DQ₂ to toggle. When the device is in the erase-suspended-program mode, successive reads from the non-erase suspended sector will indicate a logic "1" at the DQ₂ bit.

DQ₆ is different from DQ₂ in that DQ₆ toggles only when the standard program or Erase, or Erase Suspend Program operation is in progress. The behavior of these two status bits, along with that of DQ₇, is summarized as follows :

For example, DQ₂ and DQ₆ can be used together to determine if the erase-suspend-read mode is in progress. (DQ₂ toggles while DQ₆ does not.) See also "Hardware Sequence Flags Table".

Furthermore DQ₂ can also be used to determine which sector is being erased. At the erase mode, DQ₂ toggles if this bit is read from an erasing sector.

To operate toggle bit function properly, \overline{CE} or \overline{OE} must be high when bank address is changed.

Reading Toggle Bits DQ₆/DQ₂

Whenever the system initially begins reading toggle bit status, it must read DQ₇ to DQ₀ at least twice in a row to determine whether a toggle bit is toggling. Typically a system would note and store the value of the toggle bit after the first read. After the second read, the system would compare the new value of the toggle bit with the first. If the toggle bit is not toggling, the device has completed the program or erase operation. The system can read array data on DQ₇ to DQ₀ on the following read cycle.

However, if, after the initial two read cycles, the system determines that the toggle bit is still toggling, the system also should note whether the value of DQ₅ is high (see the section on DQ₅) . If it is, the system should then determine again whether the toggle bit is toggling, since the toggle bit may have stopped toggling just as DQ₅ went high. If the toggle bit is no longer toggling, the device has successfully completed the program or erase operation. If it is still toggling, the device did not complete the operation successfully, and the system must write the reset command to return to reading array data.

The remaining scenario is that the system initially determines that the toggle bit is toggling and DQ₅ has not gone high. The system may continue to monitor the toggle bit and DQ₅ through successive read cycles, determining the status as described in the previous paragraph. Alternatively, it may choose to perform other system tasks. In this case, the system must start at the beginning of the algorithm when it returns to determine the status of the operation. (Refer to "Toggle Bit Algorithm" in "■ FLOW CHART".)

RDY: Ready

The RDY is a dedicated output that, when the device is configured in the Synchronous mode, indicates (when at logic low) the system should wait 1 clock cycle before expecting the next word of data. Using the RDY Configuration Command Sequence, RDY can be set so that a logic low indicates the system should wait 2 clock cycles before expecting valid data.

In Synchronous mode RDY functions only data valid indicator. The RDY output to be low during the initial access in burst mode.

When the device is configured in Asynchronous mode, the RDY is an open-drain output which indicates whether an Embedded Algorithm is in progress or completed (RY/ \overline{BY}). If output is low, the device is busy with either a program or erase operation. If output is high (RY/ \overline{BY} should be pulled up), the device is ready to accept any read/write or erase operation. If the device is placed in an Erase Suspend mode, RDY output will be High-Z.

During programming at Asynchronous mode, the RDY pin is driven low after the rising edge of the fourth write pulse. During an erase operation, the RY/ \overline{BY} pin is driven low after the rising edge of the sixth write pulse. The RDY pin will indicate a busy condition during \overline{RESET} pulse.

Since this is an open-drain output at Asynchronous mode, RDY pins can be tied together in parallel with a pull-up resistor to V_{CCQ}.

Data Protection

The device is designed to offer protection against accidental erasure or programming caused by spurious system level signals that may exist during power transitions. During power up device automatically resets internal state machine to Read mode. Also, with its control register architecture, alteration of memory contents only occurs after successful completion of specific multi-bus cycle command sequence.

Device also incorporates several features to prevent inadvertent write cycles resulting from V_{CC} power-up and power-down transitions or system noise.

Write Pulse "Glitch" Protection

Noise pulses of less than 3 ns (typical) on \overline{OE} , \overline{CE} , or \overline{WE} will not initiate a write cycle.

Logical Inhibit

Write cycles are inhibited by holding any one of $\overline{OE} = V_{IL}$, $\overline{CE} = V_{IH}$ or $\overline{WE} = V_{IH}$. To initiate a write cycle, \overline{CE} and \overline{WE} must be a logical zero while \overline{OE} is a logical one.

Power-Up Write Inhibit

Power-up of the device with $\overline{WE} = \overline{CE} = V_{IL}$ and $\overline{OE} = V_{IH}$ will not accept commands on the rising edge of \overline{WE} . The internal state machine is automatically reset to read mode on power-up.

■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating		Unit
		Min	Max	
Storage Temperature	T _{stg}	-55	+125	°C
Ambient Temperature with Power Applied	T _A	-40	+85	°C
Voltage with Respect to Ground All inputs and I/Os pins except as noted below* ^{1,2}	V _{IN} , V _{OUT}	-0.5	V _{CCQ} +0.5	V
Power Supply Voltage* ¹	V _{CC}	-0.5	+2.5	V
I/O's Power Supply Voltage	V _{CCQ}	-0.5	+2.5	V
ACC* ^{1,3}	V _{ACC}	-0.5	+10.5	V

*1 : Voltage is defined on the basis of V_{SS} = GND = 0 V.

*2 : Minimum DC voltage on input or I/O pins is -0.5 V. During voltage transitions, input or I/O pins may undershoot V_{SS} to -2.0 V for periods of up to 20 ns. Maximum DC voltage on input or I/O pins is V_{CC} +0.5 V. During voltage transitions, input or I/O pins may overshoot to V_{CC} +2.0 V for periods of up to 20 ns.

*3 : Minimum DC input voltage on ACC pin is -0.5 V. During voltage transitions, ACC pin may undershoot V_{SS} to -2.0 V for periods of up to 20 ns. Voltage difference between input and supply voltage (V_{IN} - V_{CC}) does not exceed +8.0 V. Maximum DC input voltage on ACC pin is +10.5 V which may overshoot to +12.5 V for periods of up to 20 ns.

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Part No.	Value		Unit
			Min	Max	
Ambient Temperature	T _A	MBM29BS/FS12DH 12	-40	+85	°C
Power Supply Voltage*	V _{CC}	MBM29BS/FS12DH 12	+1.65	+1.95	V
V _{CCQ} Supply Voltage*	V _{CCQ}	MBM29BS/FS12DH 12	+1.65	+V _{CC}	V

* : Voltage is defined on the basis of V_{SS} = GND = 0 V.

Notes: Operating ranges define those limits between which the functionality of the device is guaranteed.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

■ MAXIMUM OVERSHOOT/MAXIMUM UNDERSHOOT

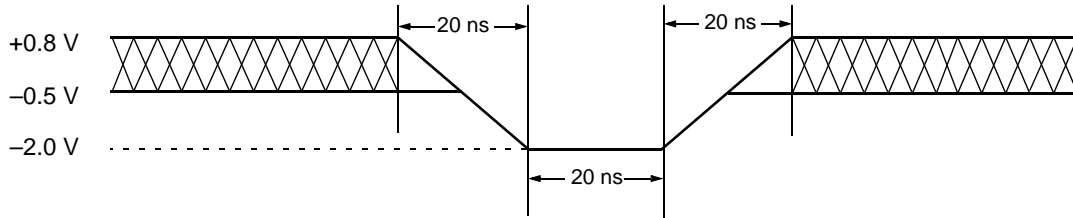


Figure 1 Maximum Undershoot Waveform

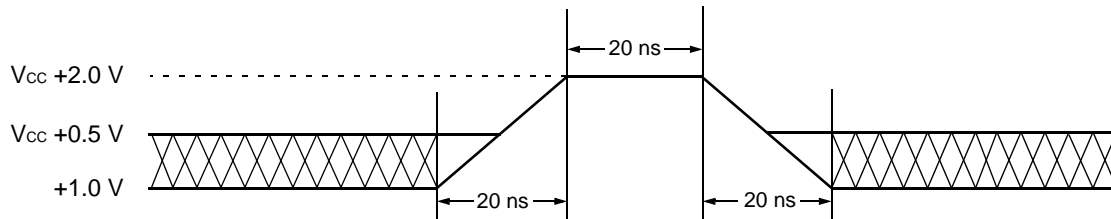


Figure 2 Maximum Overshoot Waveform 1

■ DC CHARACTERISTICS

- CMOS Compatible

Parameter	Symbol	Conditions	Value			Unit
			Min	Typ	Max	
Input Leakage Current	I_{LI}	$V_{IN} = V_{SS} \text{ to } V_{CC}, V_{CC} = V_{CC} \text{ Max}$	—	—	±1.0	μA
Output Leakage Current	I_{LO}	$V_{OUT} = V_{SS} \text{ to } V_{CC}, V_{CC} = V_{CC} \text{ Max}$	—	—	±1.0	μA
V _{CC} Active Burst Read Current	I_{CCB}	$\overline{CE} = V_{IL}, \overline{OE} = V_{IH}, \overline{WE} = V_{IH},$ 66 MHz	—	15	30	mA
V _{CC} Active Asynchronous Read Current* ¹	I_{CC1}	$\overline{CE} = V_{IL}, \overline{OE} = V_{IH},$ $\overline{WE} = V_{IH}$	—	10 MHz 20	30	mA
		5 MHz 10		15		
V _{CC} Active Current* ²	I_{CC2}	$\overline{CE} = V_{IL}, \overline{OE} = V_{IH}, V_{PP} = V_{IH}$	—	15	40	mA
V _{CC} Current (Standby)	I_{CC3}	$\overline{CE} = \overline{RESET} = V_{CC} \pm 0.2 \text{ V}$	—	0.2	50	μA
V _{CC} Current (Standby, Reset)* ³	I_{CC4}	$\overline{RESET} = V_{SSQ} \pm 0.2 \text{ V}, \text{ CLK} = V_{IL}$	—	0.2	50	μA
V _{CC} Current (Automatic Sleep Mode)	I_{CC5}	$V_{CC} = V_{CC} \text{ Max}, \overline{CE} = V_{SSQ} \pm 0.2 \text{ V},$ $\overline{RESET} = V_{CCQ} \pm 0.2 \text{ V}, V_{IN} = V_{CCQ}$ $\pm 0.2 \text{ V or } V_{SSQ} \pm 0.2 \text{ V}$	—	0.2	50	μA
V _{CC} Active Current (Read-While-Program)* ⁴	I_{CC6}	$\overline{CE} = V_{IL}, \overline{OE} = V_{IH}$	—	25	60	mA
V _{CC} Active Current (Read-While-Erase)* ⁴	I_{CC7}	$\overline{CE} = V_{IL}, \overline{OE} = V_{IH}$	—	25	60	mA
Input Low Level	V_{IL}	$V_{CCQ} = 1.8 \text{ V}$	-0.5	—	0.4	V
Input High Level	V_{IH}	$V_{CCQ} = 1.8 \text{ V}$	$V_{CCQ}-0.4$	—	$V_{CCQ}+0.4$	V
Output Low Voltage Level	V_{OL}	$I_{OL} = 100 \mu\text{A},$ $V_{CC} = V_{CC} \text{ Min} = V_{CCQ}$	—	—	0.1	V
Output High Voltage Level	V_{OH}	$I_{OH} = -100 \mu\text{A},$ $V_{CC} = V_{CC} \text{ Min} = V_{CCQ}$	$V_{CCQ}-0.1$	—	—	V
Voltage for ACC Program Acceleration* ⁵	V_{ACC}	—	11.5	—	12.5	V

*1: The I_{CC} current listed includes both the DC operating current and the frequency dependent component.

*2: I_{CC} active while Embedded Algorithm (Program or Erase) is in progress.

*3: Automatic sleep mode enables the low power mode when address remain stable for $t_{ACC} + 60 \text{ ns}$.

*4: Embedded Algorithm (Program or Erase) is in progress. (@5 MHz)

*5: Applicable for only V_{CC} .

MBM29BS/FS12DH₁₅

■ AC CHARACTERISTICS

- Synchronous/Burst Read

Parameter	Symbols	Value				Unit
		54 MHz		66 MHz		
	Standard	Min	Max	Min	Max	
Latency (Even Address in Handshake Mode)	t _{IACC}	—	69	—	56	ns
Latency—(Non-Handshake or Odd Address in Handshake mode)	t _{IACC}	—	87.5	—	71	ns
Burst Access Time Valid Clock to Output Delay	t _{BACC}	—	13.5	—	11	ns
Address Setup Time to CLK*	t _{ACS}	5	—	4	—	ns
Address Hold Time from CLK*	t _{ACH}	7	—	6	—	ns
Data Hold Time from Next Clock Cycle	t _{BDH}	4	—	3	—	ns
Chip Enable to RDY Valid	t _{CR}	—	13.5	—	11	ns
Output Enable to Output Valid	t _{OE}	—	13.5	—	11	ns
Chip Enable to High-Z	t _{CEZ}	—	10	—	8	ns
Output Enable to High-Z	t _{OEZ}	—	10	—	8	ns
$\overline{\text{CE}}$ Setup Time to CLK	t _{CES}	5	—	—	4	ns
Ready Access Time from CLK	t _{RACC}	—	13.5	—	11	ns
$\overline{\text{CE}}$ Setup Time to $\overline{\text{AVD}}$	t _{CAS}	0	—	0	—	ns
$\overline{\text{AVD}}$ Set Up Time to CLK	t _{AVSC}	5	—	4	—	ns
$\overline{\text{AVD}}$ Hold Time to CLK	t _{AVHC}	7	—	6	—	ns
Access Time	t _{ACC}	—	55	—	50	ns
CLK to access resume	t _{CKA}	—	13.5	—	11	ns
CLK to High-Z	t _{CKZ}	—	10	—	8	ns
Output Enable Setup Time	t _{OES}	5	—	4	—	ns
Read Cycle for Continuous suspend	t _{RCC}	—	1	—	1	ms
Read Cycle Time	t _{RC}	55	—	50	—	ns

*: Addresses are latched on the active edge of CLK.

Note : Test Conditions:

Output Load: $V_{CCQ} = 1.65 \text{ V to } 1.95 \text{ V} : 30 \text{ pF}$

Input rise and fall times: 5 ns

Input pulse levels: 0.0 V to V_{CCQ}

Timing measurement reference level

Input: $0.5 \times V_{CCQ}$

Output: $0.5 \times V_{CCQ}$

- Asynchronous Read

Parameter		Symbols		Value				Unit
				54 MHz		66 MHz		
		JEDEC	Standard	Min	Max	Min	Max	
Read Cycle Time		—	t _{RC}	55	—	50	—	ns
Access Time from $\overline{\text{CE}}$ Low		—	t _{CE}	—	55	—	50	ns
Asynchronous Access Time*		—	t _{ACC}	—	55	—	50	ns
Output Enable to Output Valid		—	t _{OE}	—	13.5	—	11	ns
Output Enable Hold Time	Read	—	t _{OEH}	0	—	0	—	ns
	Toggle and $\overline{\text{Data}}$ Polling			10	—	8	—	ns
Chip Enable to High-Z		—	t _{CEZ}	—	10	—	8	ns
$\overline{\text{CE}}$ High During Toggle Bit Polling		—	t _{CEPH}	20	—	20	—	ns
Output Enable to High-Z		—	t _{OEZ}	—	10	—	8	ns

* : Asynchronous Access Time is from the last of either stable addresses or the falling edge of $\overline{\text{AVD}}$.

- Hardware Reset ($\overline{\text{RESET}}$)

Parameter	Symbols		All Speed Options		Unit
	JEDEC	Standard			
$\overline{\text{RESET}}$ Pin Low (During Embedded Algorithms) to Read Mode	—	t _{READY}	—	20	μs
$\overline{\text{RESET}}$ Pulse Width	—	t _{RP}	500	—	ns
Reset High Time Before Read	—	t _{RH}	200	—	ns
Power On/Off Time	—	t _{PS}	0	—	ns

MBM29BS/FS12DH₁₅

• Write (Erase/Program) Operations

Parameter	Symbols		Value						Unit
			54 MHz			66 MHz			
	JEDEC	Standard	Min	Typ	Max	Min	Typ	Max	
Write Cycle Time	t _{AVAV}	t _{WC}	55	—	—	50	—	—	ns
Address Setup Time	t _{AVWL}	t _{AS}	0	—	—	0	—	—	ns
Address Hold Time	t _{WLAX}	t _{AH}	20	—	—	20	—	—	ns
$\overline{\text{AVD}}$ Low Time	—	t _{AVDP}	12	—	—	10	—	—	ns
$\overline{\text{CE}}$ Low to $\overline{\text{AVD}}$ High	—	t _{CLAH}	12	—	—	10	—	—	ns
Data Setup Time	t _{DVWH}	t _{DS}	45	—	—	20	—	—	ns
Data Hold Time	t _{WHDX}	t _{DH}	0	—	—	0	—	—	ns
Read Recovery Time Before Write	t _{GHWL}	t _{GHWL}	0	—	—	0	—	—	ns
$\overline{\text{CE}}$ Hold Time	t _{WHEH}	t _{CH}	0	—	—	0	—	—	ns
Write Pulse Width	t _{EHWH}	t _{WP}	30	—	—	20	—	—	ns
Write Pulse Width High	t _{WHWL}	t _{WPH}	20	—	—	20	—	—	ns
Latency Between Read and Write Operations	—	t _{SR/W}	0	—	—	0	—	—	ns
Programming Operation	t _{WHWH1}	t _{WHWH1}	—	6	—	—	6	—	μs
Sector Erase Operation*	t _{WHWH2}	t _{WHWH2}	—	0.5	—	—	0.5	—	s
V _{ACC} Rise and Fall Time	—	t _{VID}	500	—	—	500	—	—	ns
V _{ACC} Setup Time (During Accelerated Programming)	—	t _{VIDS}	1	—	—	1	—	—	μs
V _{CC} Setup Time	—	t _{VCS}	50	—	—	50	—	—	μs
$\overline{\text{CE}}$ Setup Time to $\overline{\text{WE}}$	t _{ELWL}	t _{CS}	0	—	—	0	—	—	ns
$\overline{\text{AVD}}$ Set Up Time to CLK	—	t _{AVSC}	5	—	—	4	—	—	ns
$\overline{\text{AVD}}$ Hold Time to CLK	—	t _{AVHC}	7	—	—	6	—	—	ns
$\overline{\text{AVD}}$ Setup Time to $\overline{\text{WE}}$	—	t _{AVSW}	5	—	—	4	—	—	ns
$\overline{\text{AVD}}$ Hold Time to $\overline{\text{WE}}$	—	t _{AVHW}	7	—	—	6	—	—	ns
Address Setup Time to CLK	—	t _{ACS}	5	—	—	4	—	—	ns
Address Hold Time to CLK	—	t _{ACh}	7	—	—	6	—	—	ns
Address Setup Time to $\overline{\text{AVD}}$	—	t _{AAS}	5	—	—	4	—	—	ns
Address Hold Time to $\overline{\text{AVD}}$	—	t _{AAH}	7	—	—	6	—	—	ns
$\overline{\text{WE}}$ Low to CLK	—	t _{WLc}	0	—	—	0	—	—	ns
$\overline{\text{AVD}}$ High to $\overline{\text{WE}}$ Low	—	t _{AHWL}	5	—	—	5	—	—	ns
CLK to $\overline{\text{WE}}$ Low	—	t _{cWL}	5	—	—	5	—	—	ns
Erase Time-out Time	—	t _{TOW}	50	—	—	50	—	—	μs

*: Does not include the preprogramming time.

Note : See the "Erase and Programming Performance" section for more information.1.

■ ERASE AND PROGRAMMING PERFORMANCE

Parameter	Limit			Unit	Comments
	Min	Typ	Max		
Sector Erase Time	—	0.5	2	s	Excludes programming prior to erasure
Word Programming Time	—	6.0	100	μs	Excludes system level overhead
Chip Programming Time	—	25.2	95	s	Excludes system level overhead
Erase/Program Cycle	100,000	—	—	cycle	

Note : Test conditions $T_A = +25^\circ\text{C}$,
 Typical Erase conditions $T_A = +25^\circ\text{C}$, $V_{CC} = 1.8\text{ V}$,
 Typical Program conditions $T_A = +25^\circ\text{C}$, $V_{CC} = 1.8\text{ V}$, Data = checker




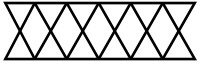
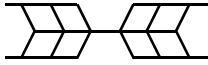
■ FBGA PIN CAPACITANCE

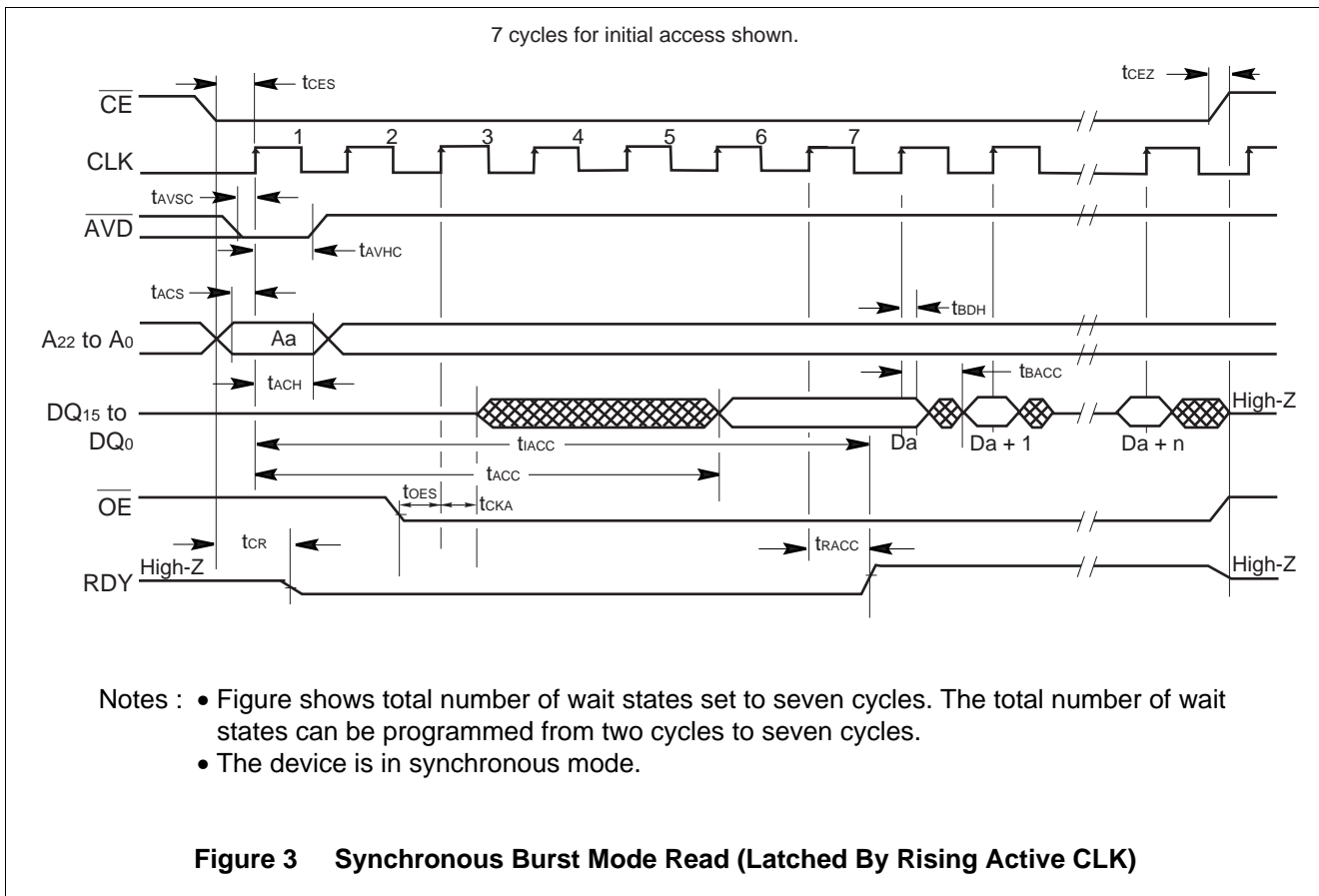
Parameter	Symbol	Test Setup	Typ	Max	Unit
Input Capacitance	C_{IN}	$V_{IN} = 0$	TBD	TBD	pF
Output Capacitance	C_{OUT}	$V_{OUT} = 0$	TBD	TBD	pF
Control Pin Capacitance	C_{IN2}	$V_{IN} = 0$	TBD	TBD	pF

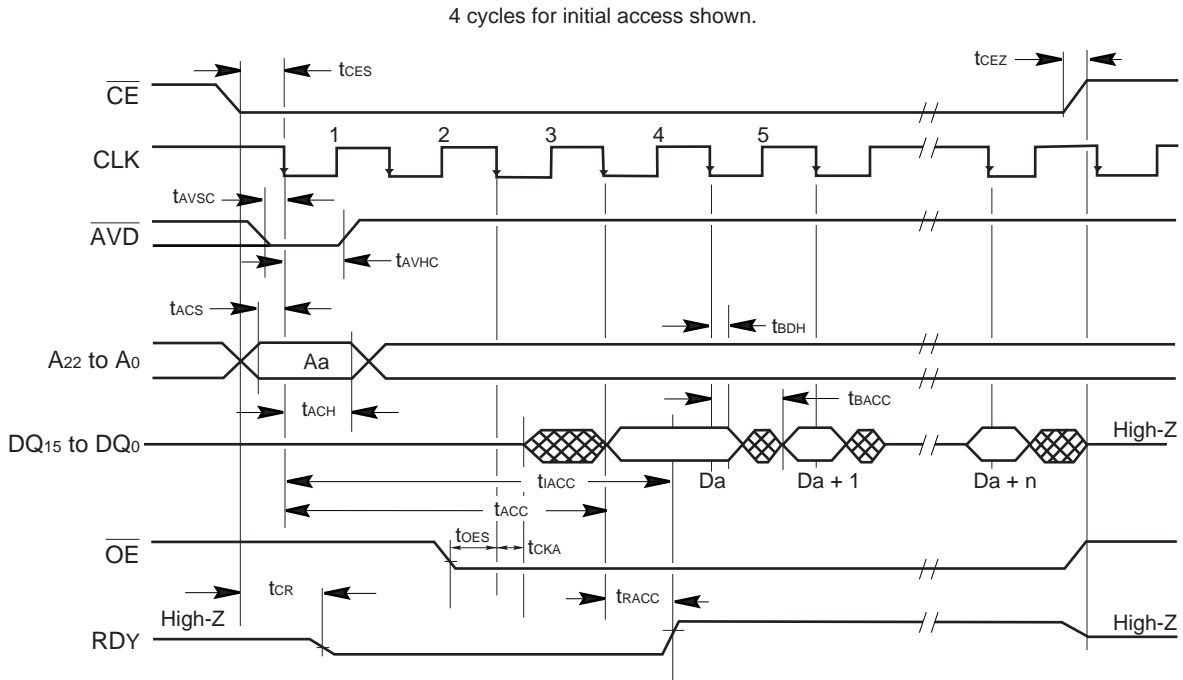
Note : Test conditions $T_A = +25^\circ\text{C}$, $f = 1.0\text{ MHz}$

TIMING DIAGRAM

- Key to Switching Wavwforms

WAVEFORM	INPUTS	OUTPUTS
	Steady	Steady
	Change from H to L	Change from H to L
	Change from L to H	Change from L to H
	Don't Care Any Change Permitted	Changing, State Unknown
	Does Not Apply	Center Line is High-Impedance State(High-Z)





- Notes :
- Figure shows total number of wait states set to four cycles. The total number of wait states can be programmed from two cycles to seven cycles. Clock is set for active falling edge.
 - The device is in synchronous mode.

Figure 4 Synchronous Burst Mode Read (Latched By Falling Active CLK)

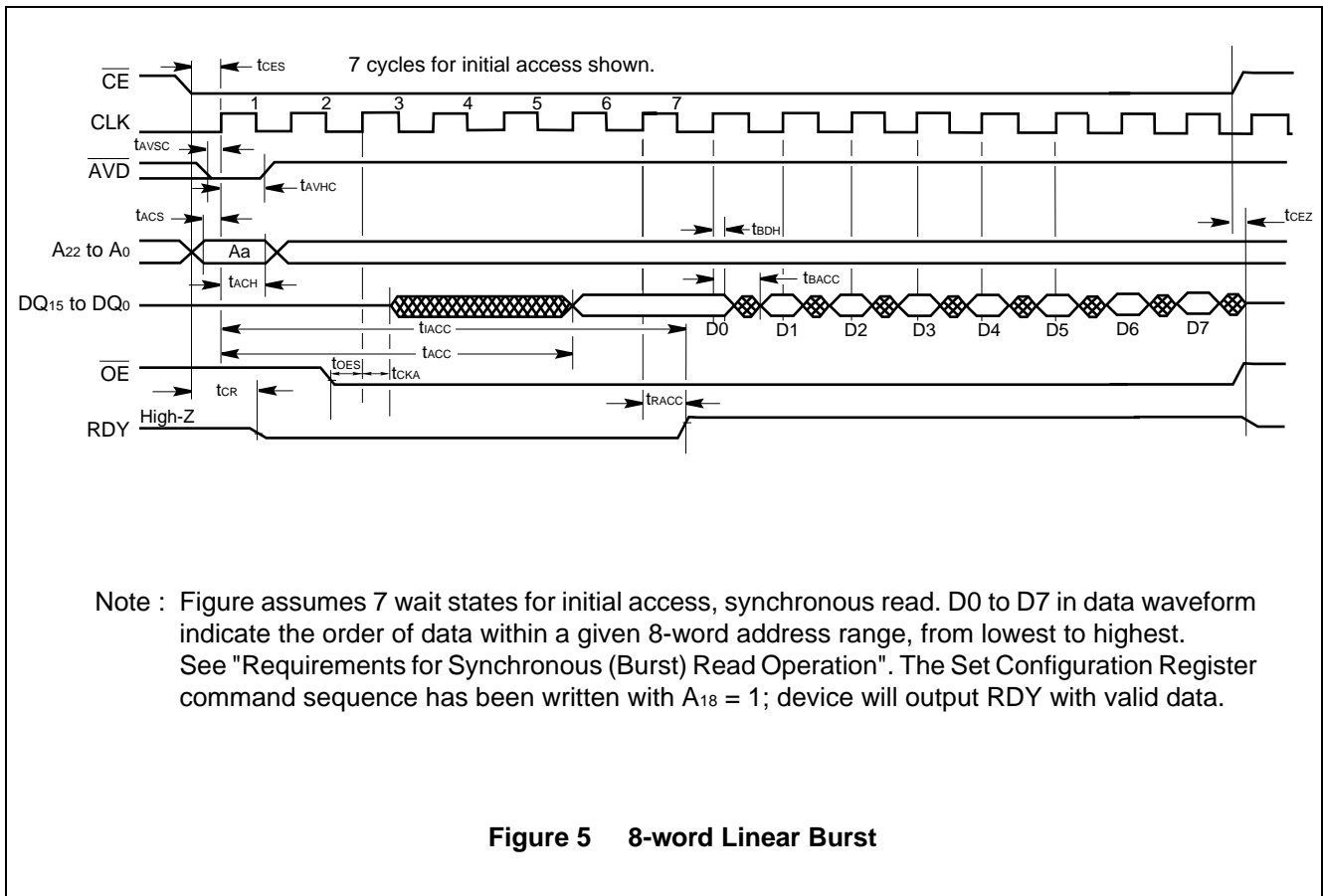
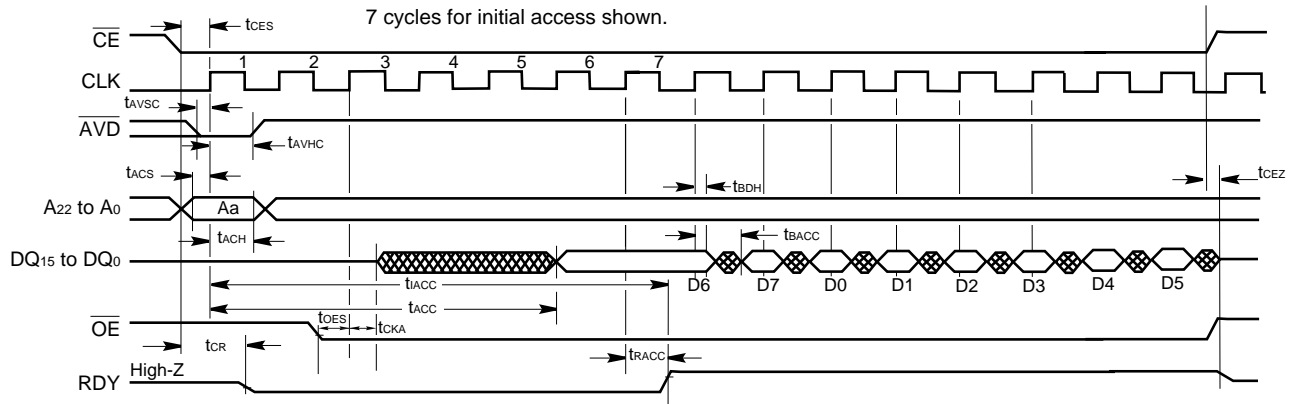


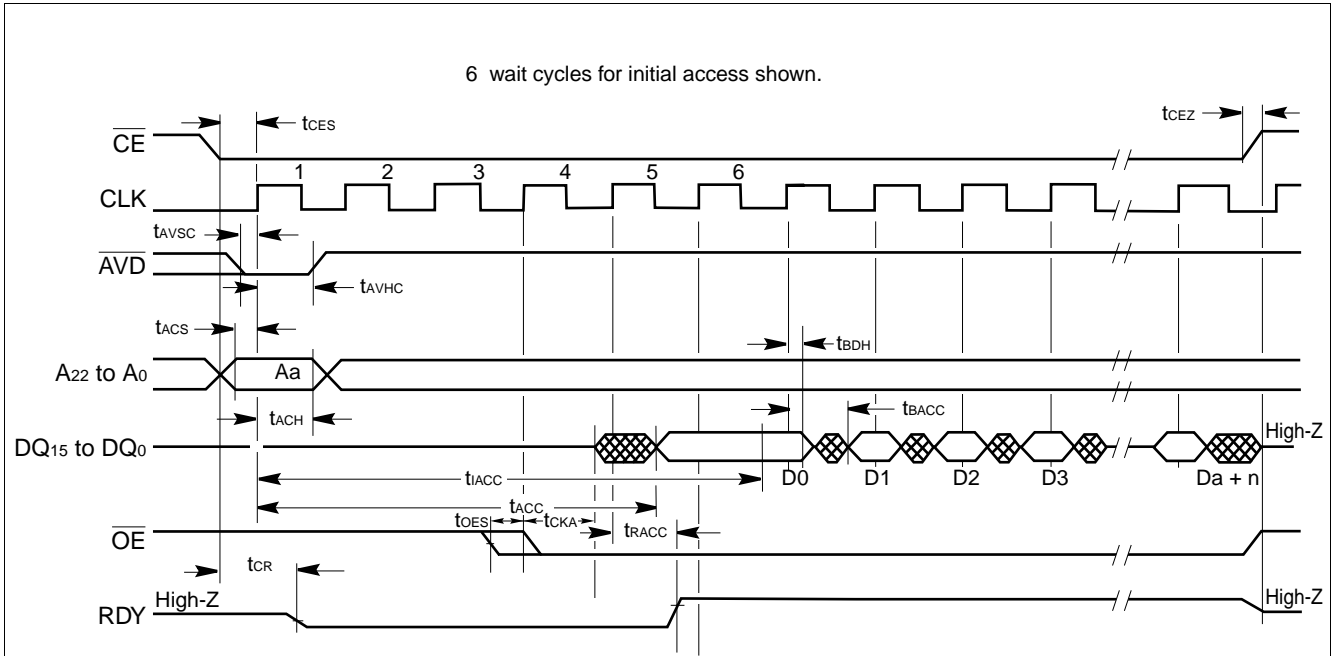
Figure 5 8-word Linear Burst



Note : Figure assumes 7 wait states for initial access, synchronous read. D0 to D7 in data waveform indicate the order of data within a given 8-word address range, from lowest to highest. Starting address in figure is the 7th address in range (A₆). See "Requirements for Synchronous (Burst) Read Operation". The Set Configuration Register command sequence has been written with A₁₈ = 1; device will output RDY with valid data.

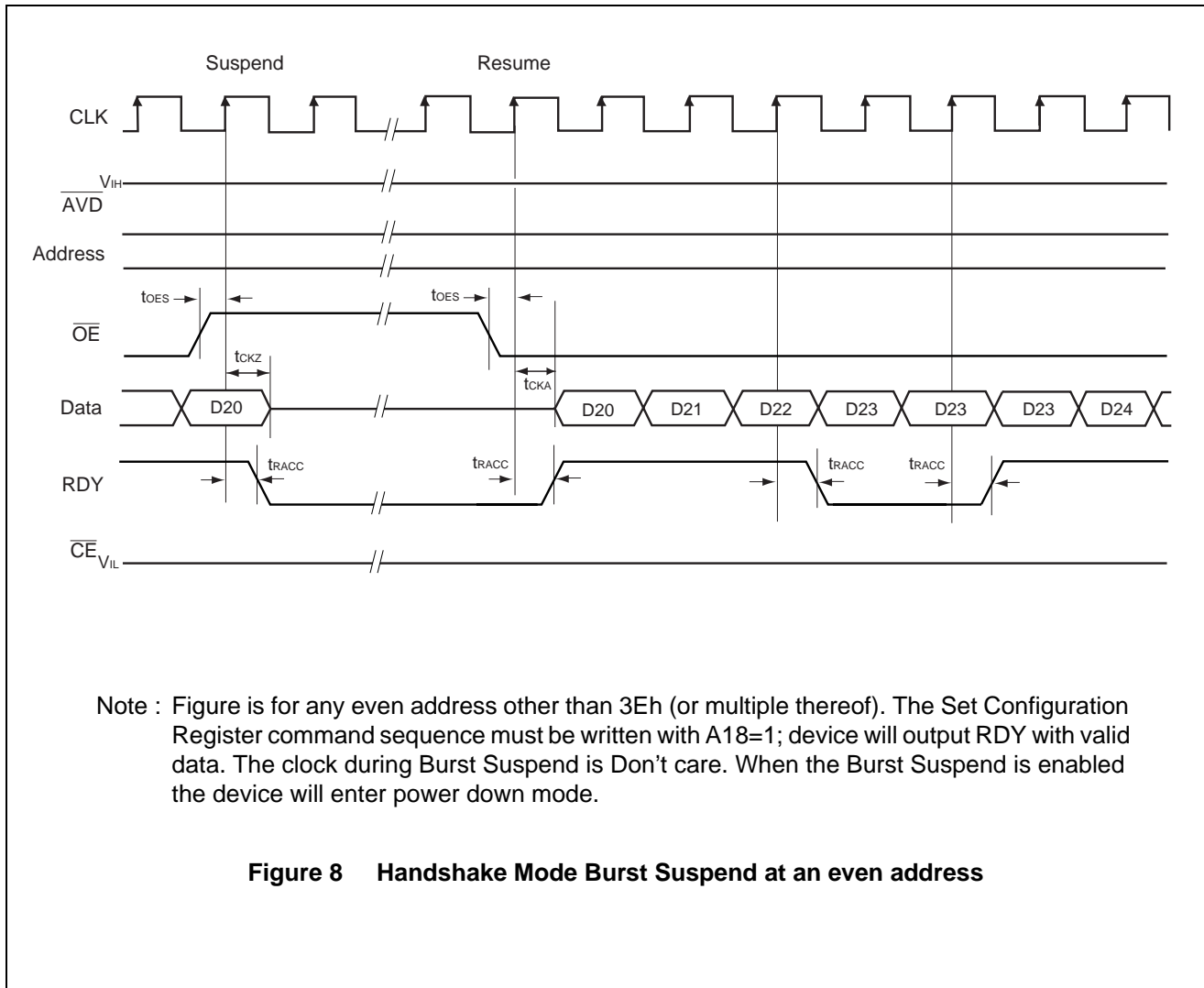
Figure 6 8-word Linear Burst with Wrap Around

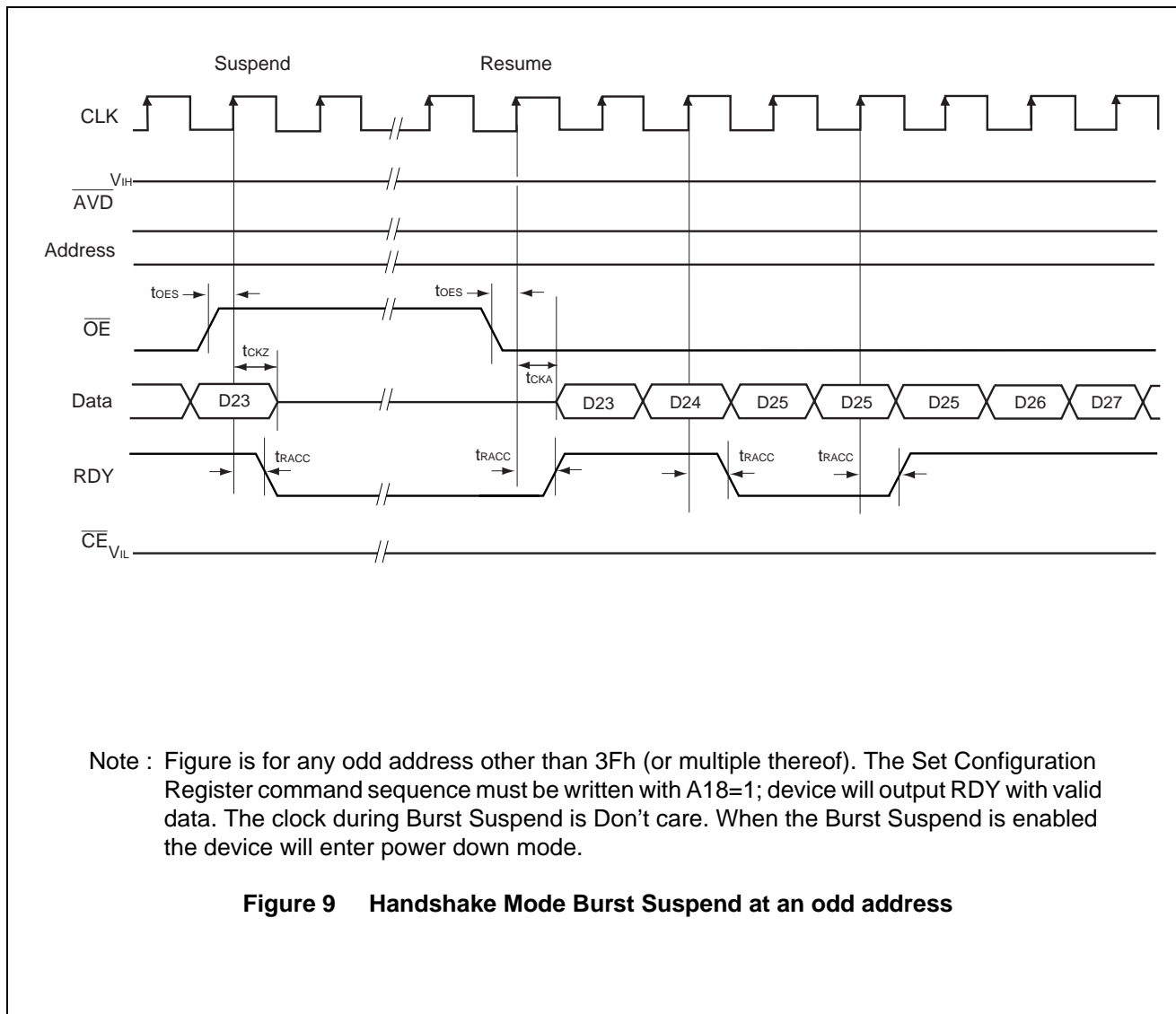
MBM29BS/FS12DH₁₅

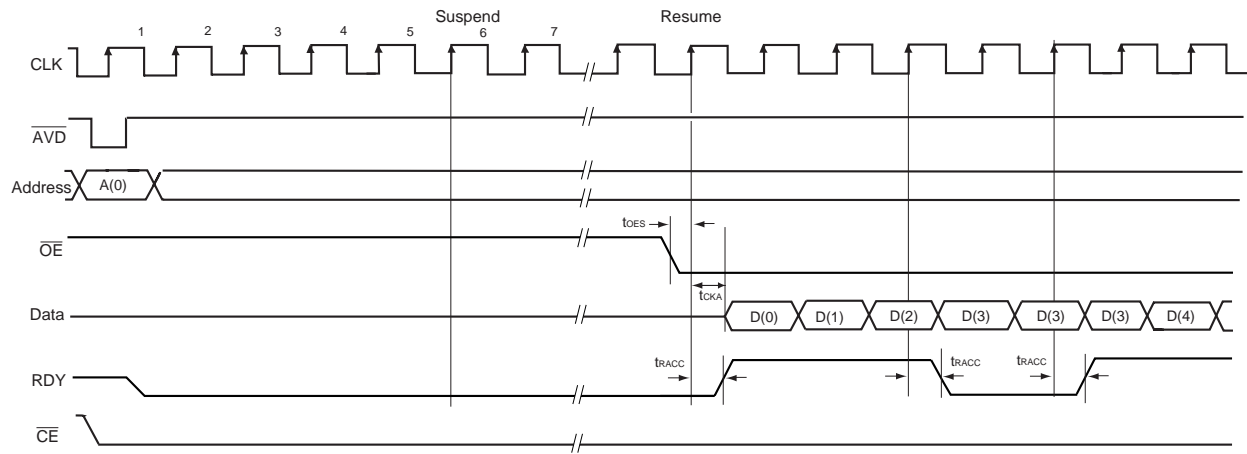


Note : Figure assumes 6 wait states for initial access, 66 MHz clock, and synchronous read.
 The Set Configuration Register command sequence has been written with $A_{18} = 0$; device will output RDY one cycle before valid data.

Figure 7 Linear Burst with RDY Set One Cycle Before Data

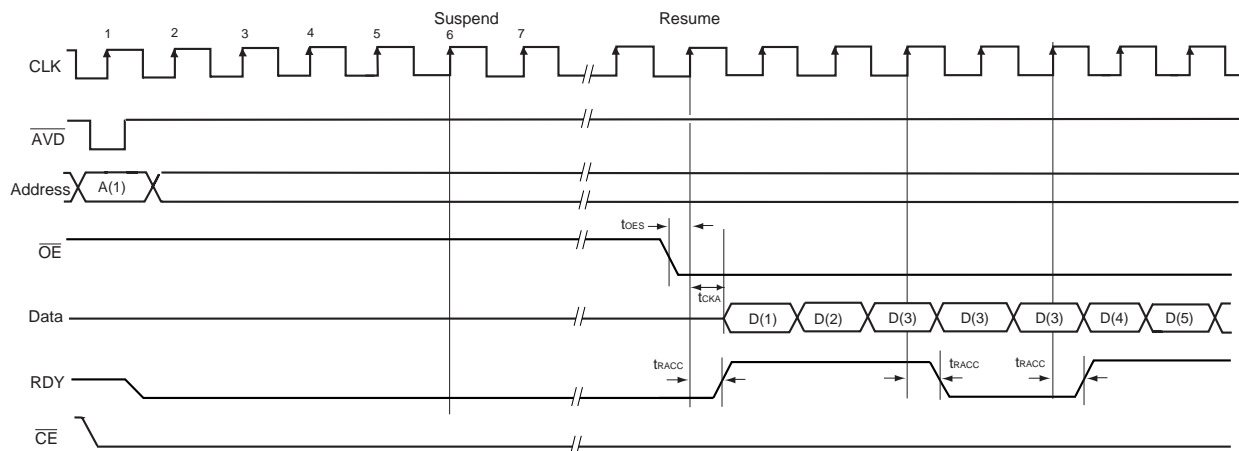






Note : Figure assumes 6 wait states for initial access and synchronous read. The starting address is Even. The Set Configuration Register command sequence must be written with A18=1; device will output RDY with valid data. The clock during Burst Suspend is Don't care. When the Burst Suspend is enabled the device will enter power down mode.

Figure 10 Handshake Mode Burst Suspend prior to Initial Access when the starting address is Even



Note : Figure assumes 6 wait states for initial access and synchronous read. The starting address is Odd. The Set Configuration Register command sequence must be written with A18=1; device will output RDY with valid data. The clock during Burst Suspend is Don't care. When the Burst Suspend is enabled the device will enter power down mode.

Figure 11 Handshake Mode Burst Suspend prior to Initial Access when the starting address is Odd

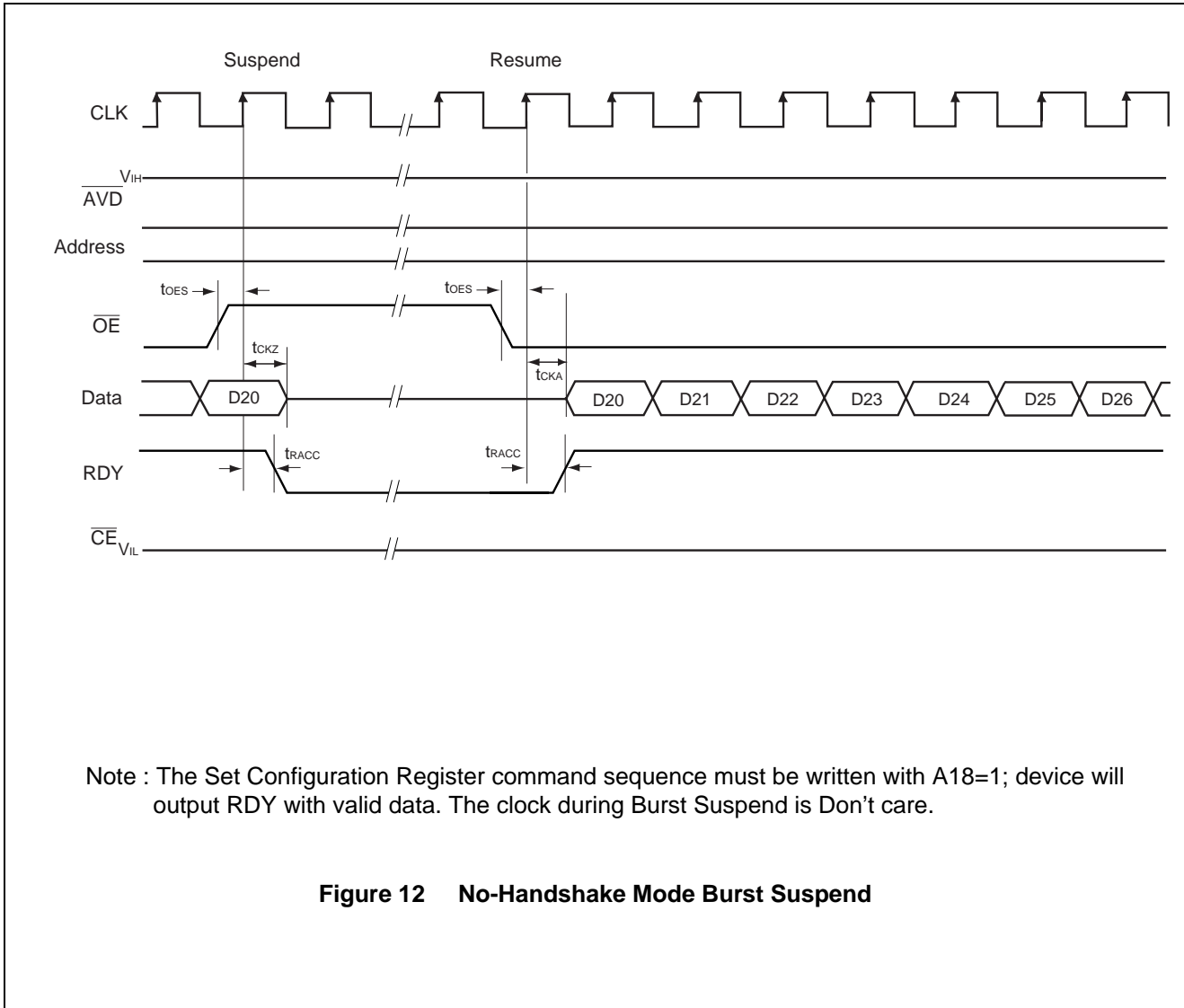
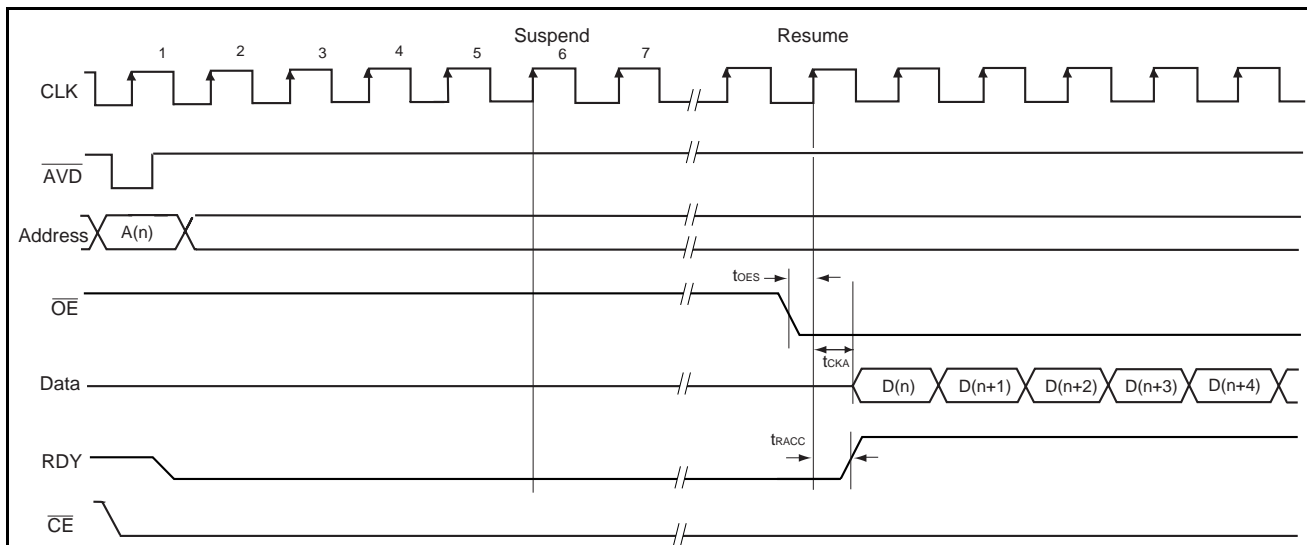
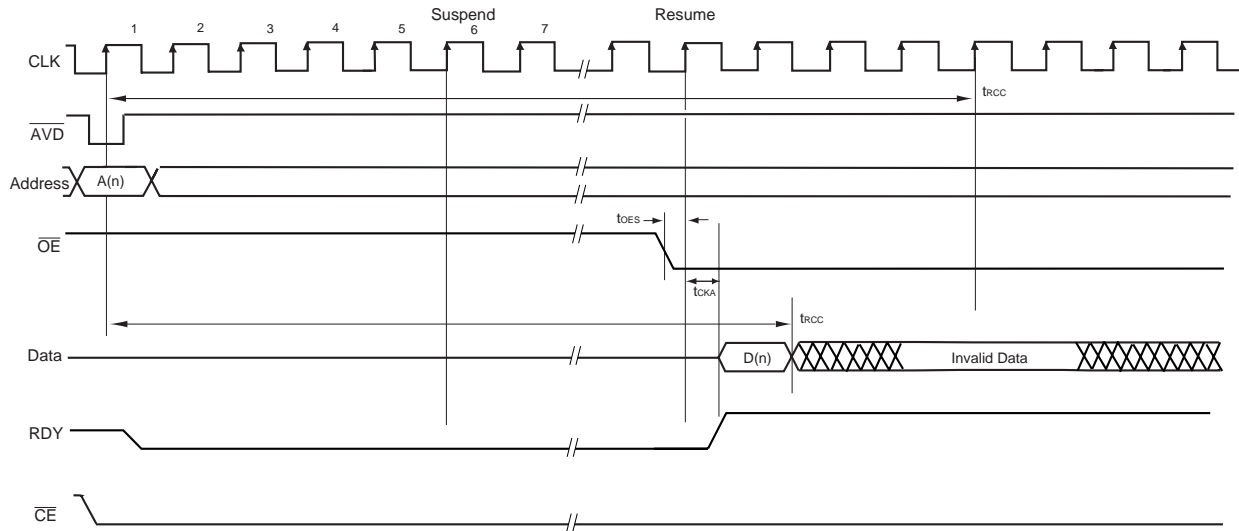


Figure 12 No-Handshake Mode Burst Suspend



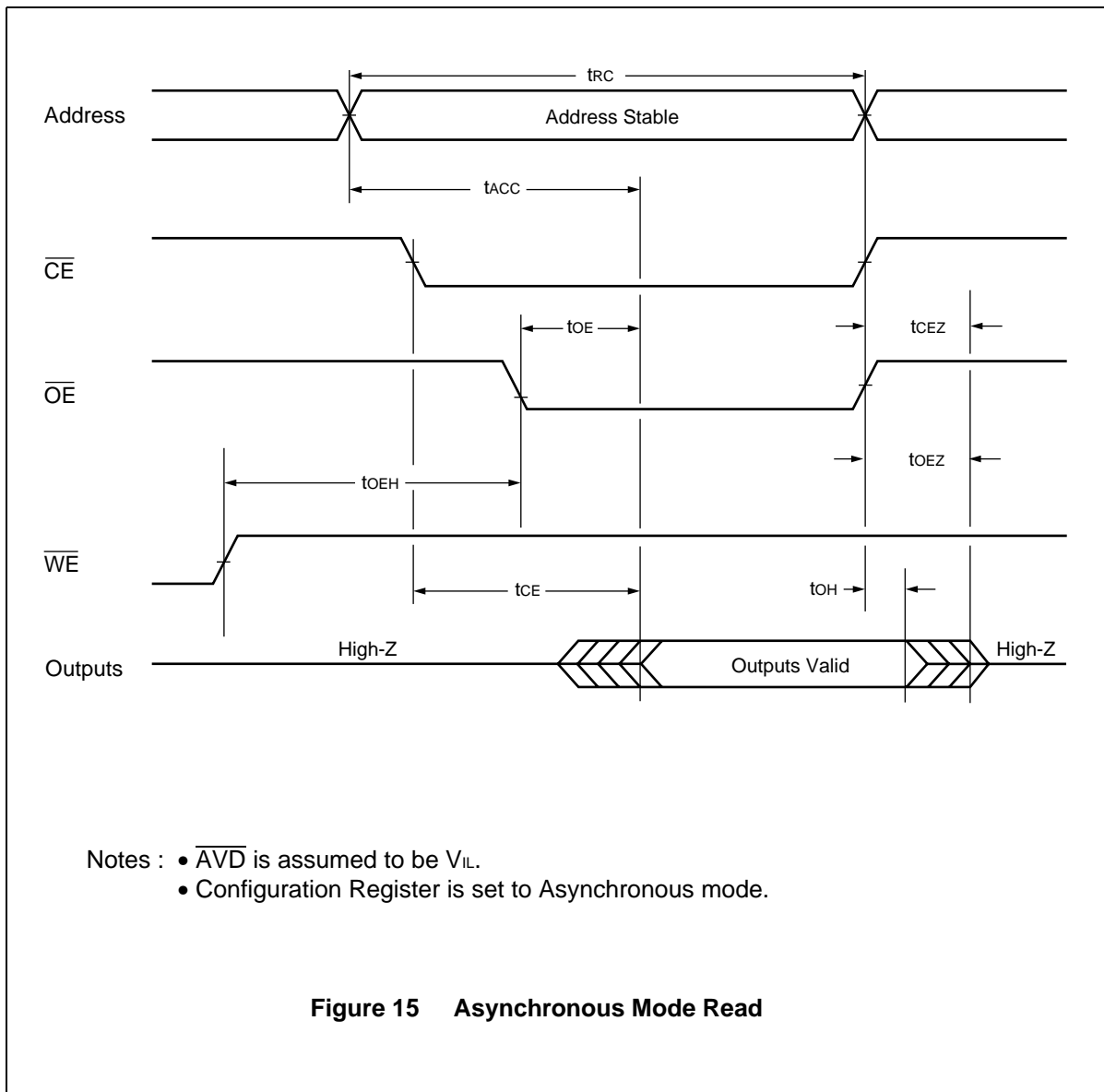
Note : Figure assumes 6 wait states for initial access and synchronous read. The Set Configuration Register command sequence must be written with A18=1; device will output RDY with valid data. The clock during Burst Suspend is Don't care.

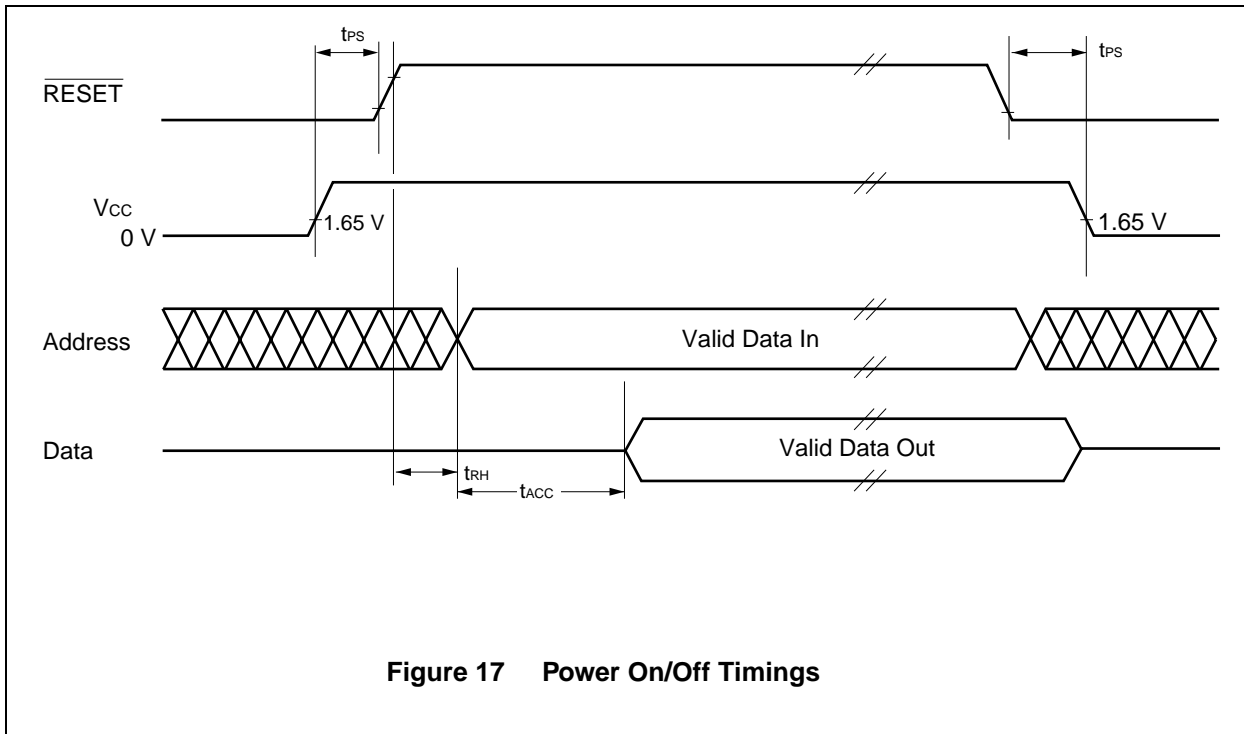
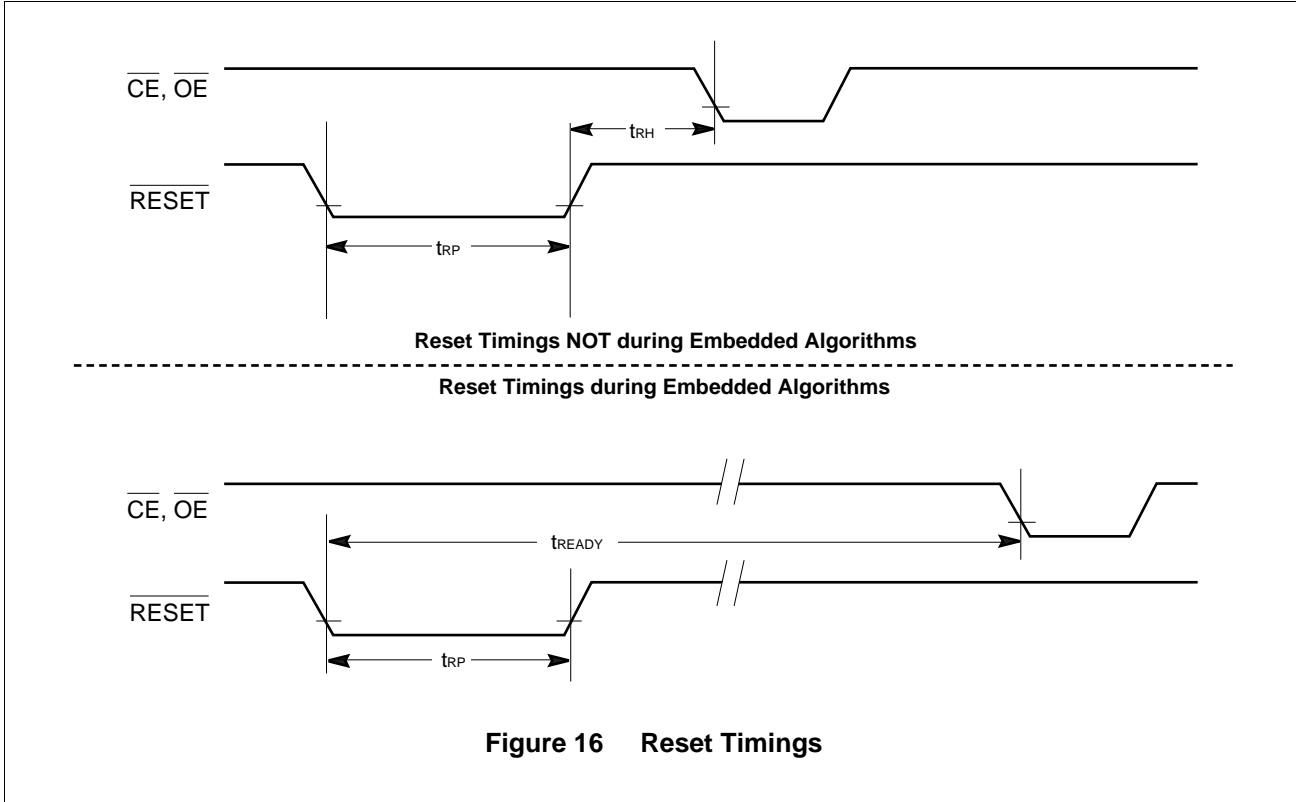
Figure 13 No-Handshake Mode Burst Suspend prior to Initial Access

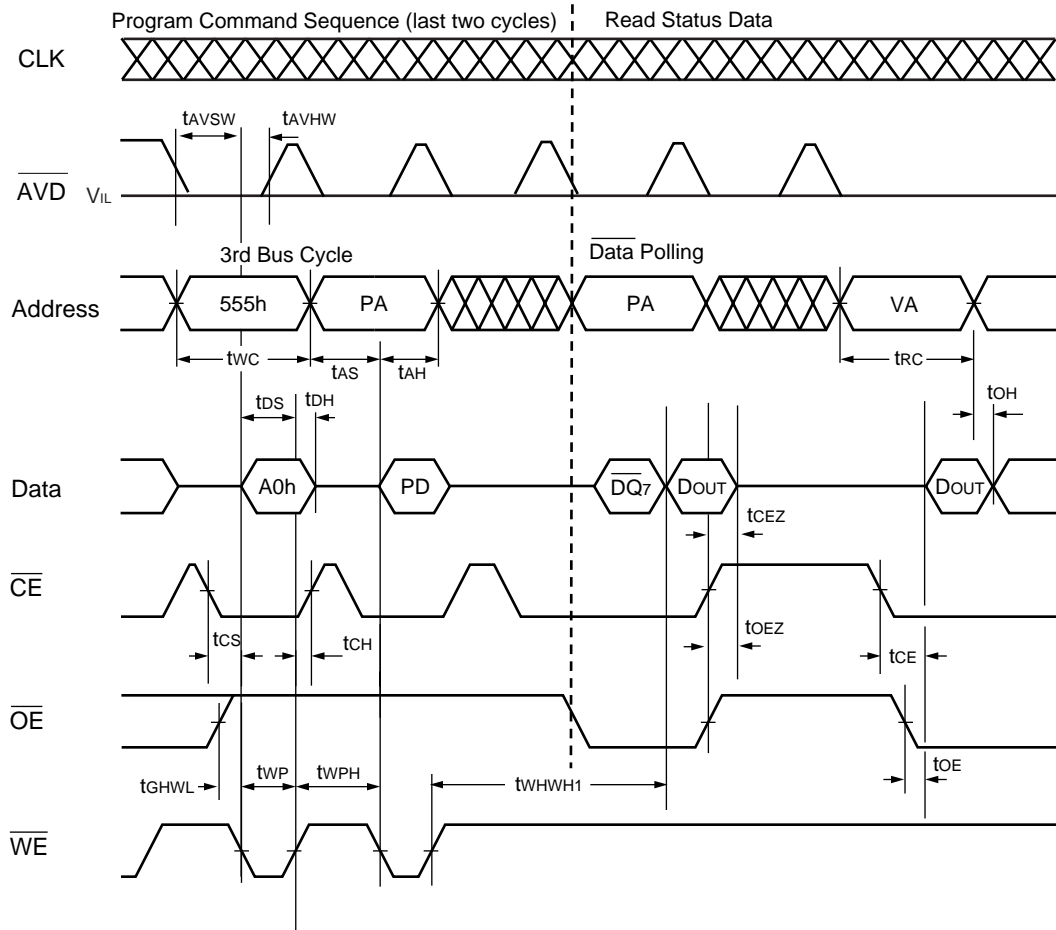


- Notes :
- Figure assumes 6 wait states for initial access and synchronous read. The Set Configuration Register command sequence must be written with A18=1; device will output RDY with valid data. The clock during Burst Suspend is Don't care.
 - Burst plus Burst Suspend should not last longer than t_{RCC} without relatching an address. After the period of t_{RCC} the device will output invalid data.

Figure 14 Read Cycle for No-Handshake Mode Continuous Suspend

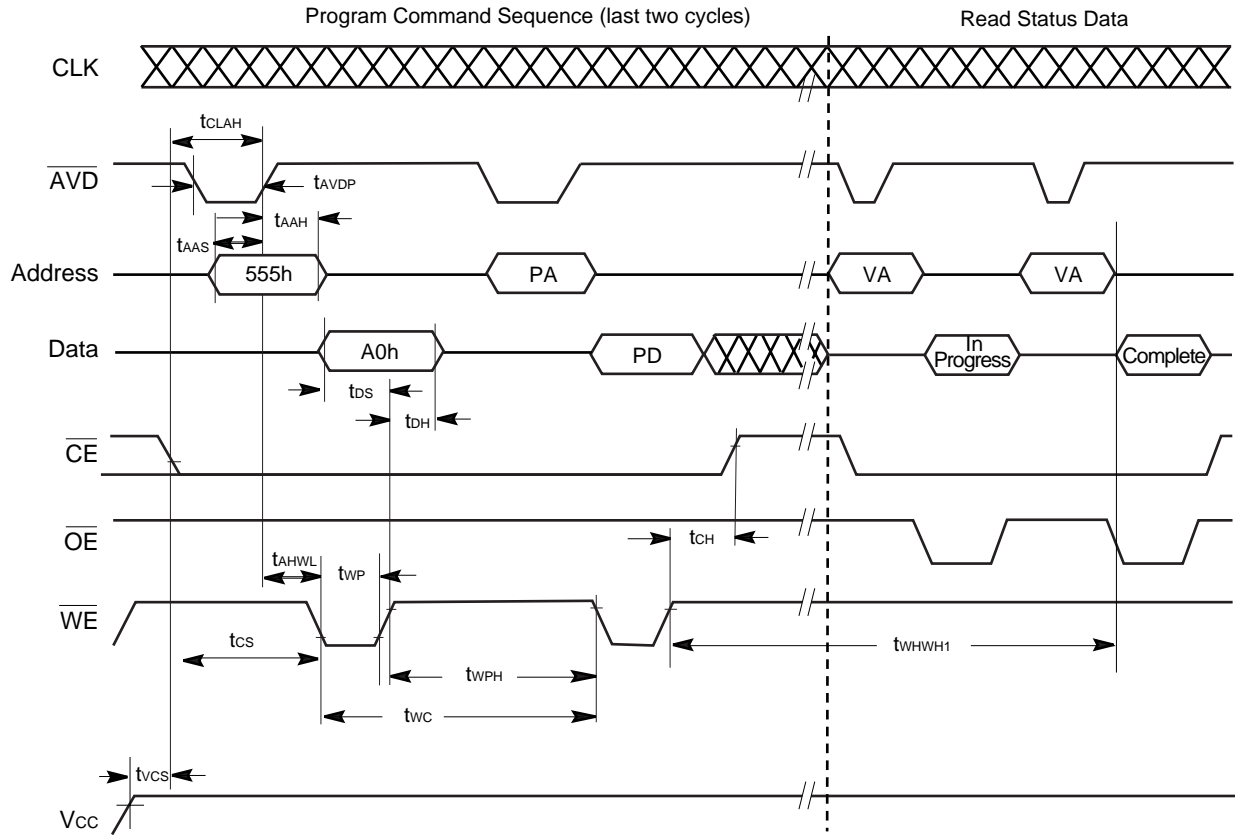






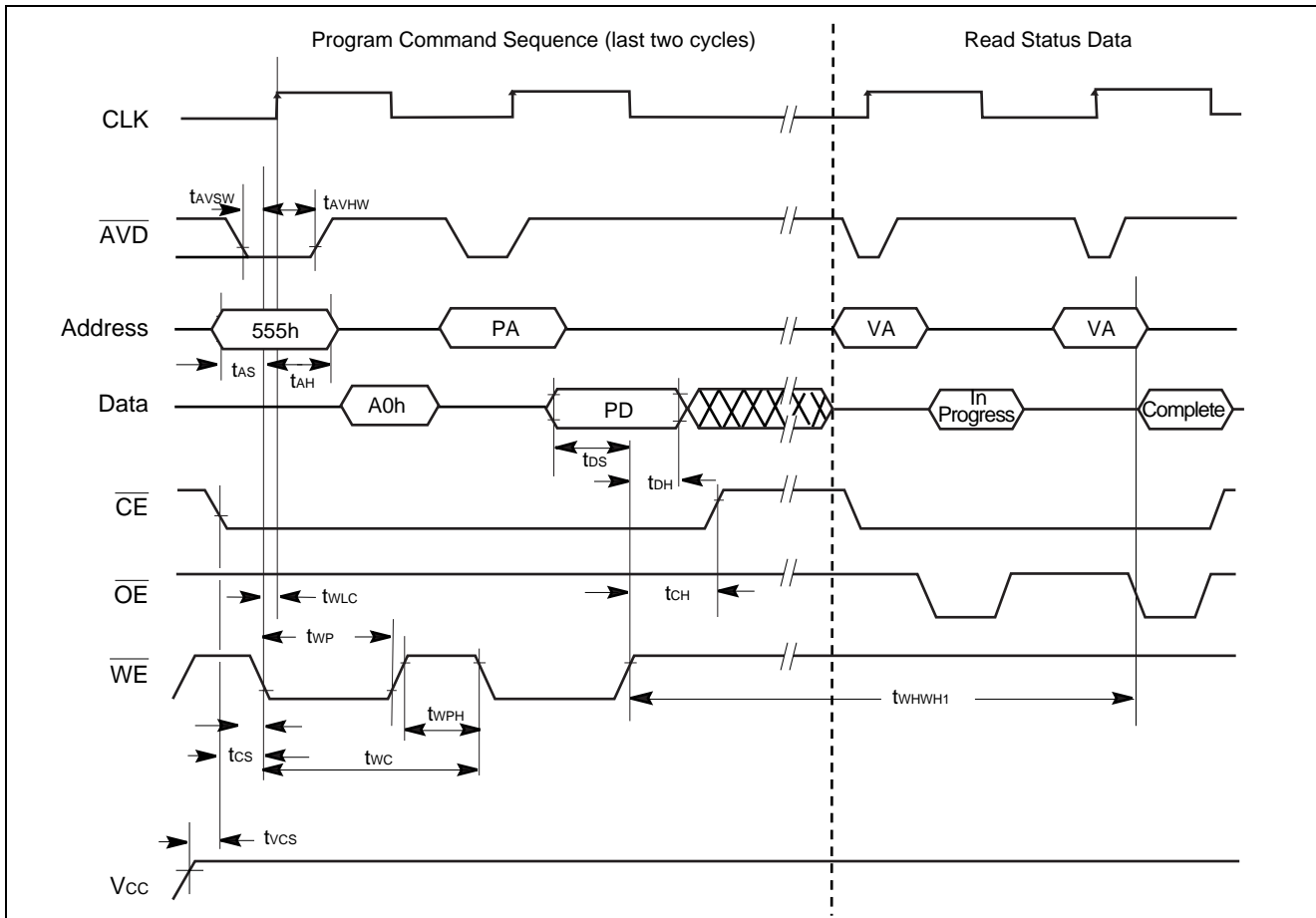
- Notes :
- PA = Program Address, PD = Program Data, VA = Valid Address for reading status bits.
 - "In progress" and "complete" refer to status of program operation.
 - A₂₂ to A₁₂ are don't care during command sequence unlock cycles.
 - CLK is Don't care.
 - Configuration Register is set to Asynchronous mode.

Figure 18 Program Operation Timings at Asynchronous Mode (\overline{WE} latch)



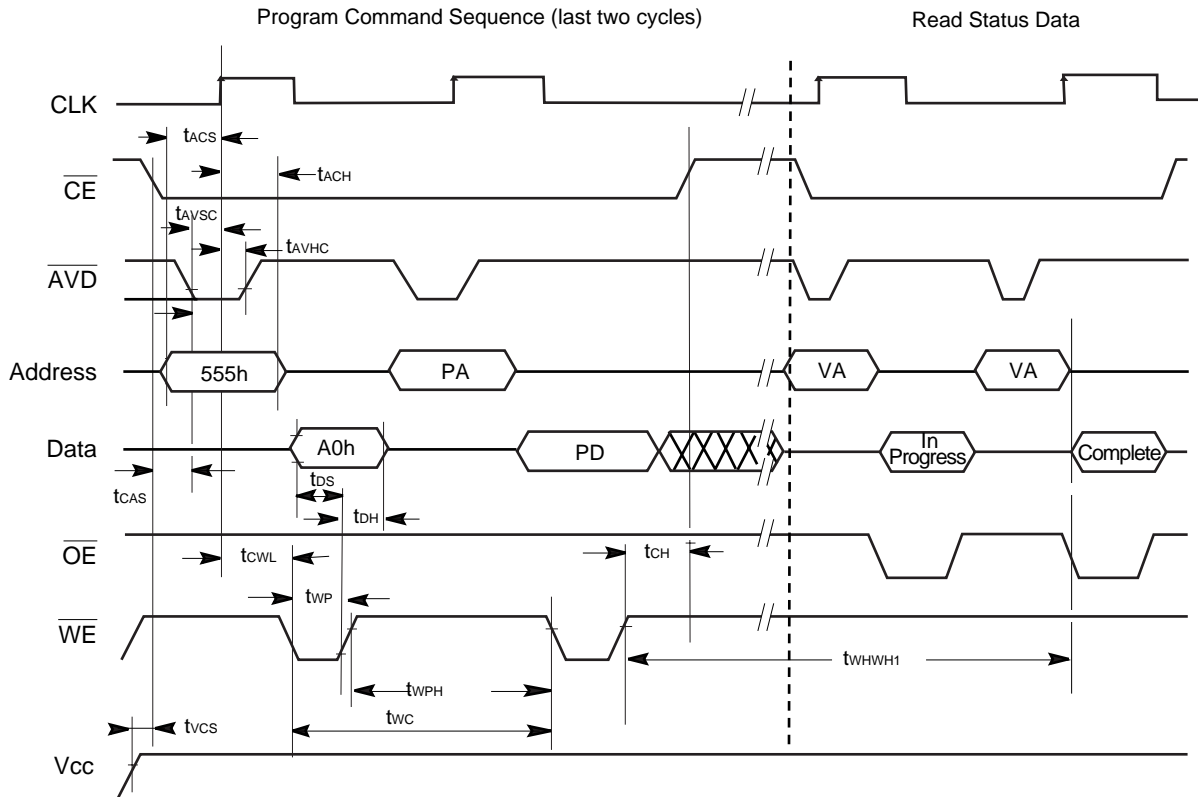
- Notes :
- PA = Program Address, PD = Program Data, VA = Valid Address for reading status bits.
 - "In progress" and "complete" refer to status of program operation.
 - A₂₂ to A₁₂ are don't care during command sequence unlock cycles.
 - CLK is Don't care.
 - Configuration Register is set to Asynchronous mode.
 - Addresses are latched on the rising edge of AVD.

Figure 19 Program Operation Timings at Asynchronous Mode (AVD latch)



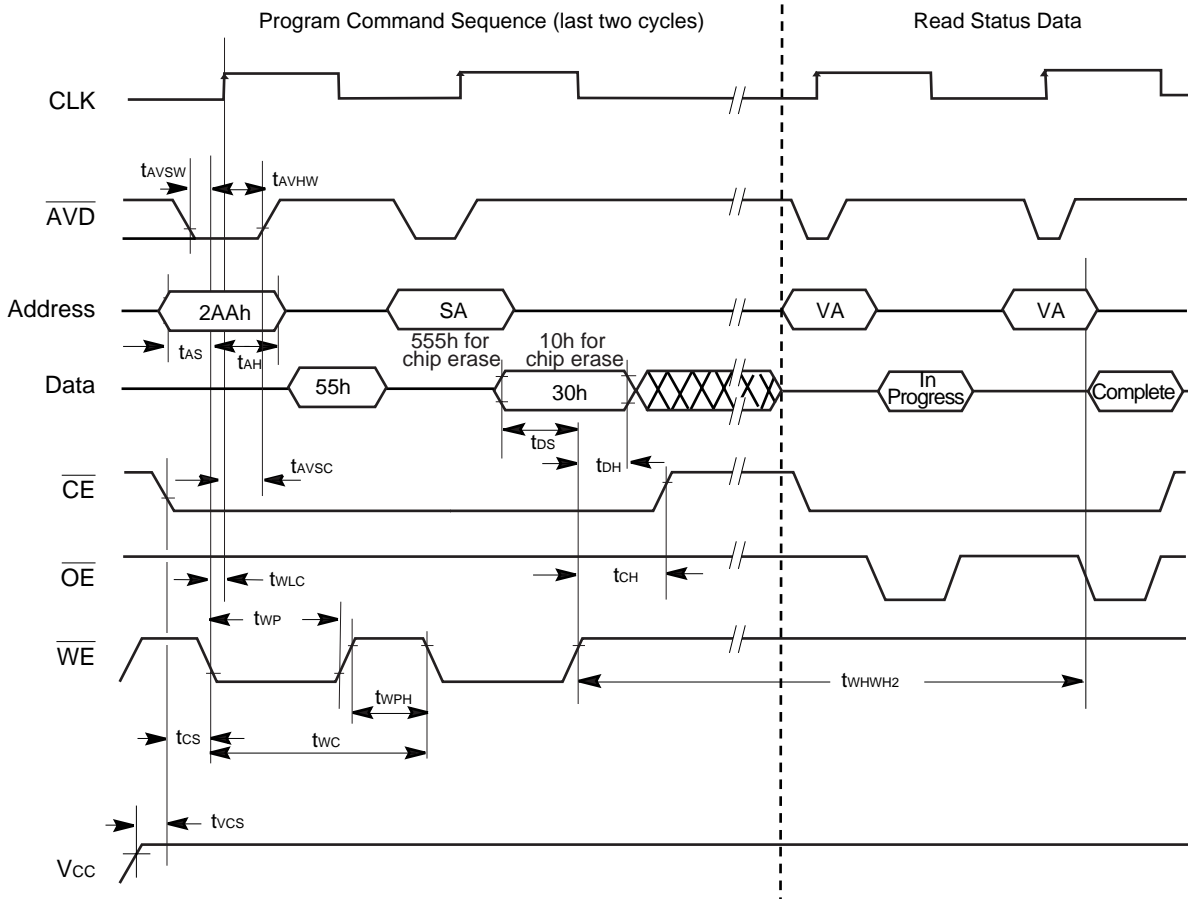
- Notes :
- PA = Program Address, PD = Program Data, VA = Valid Address for reading status bits.
 - "In progress" and "complete" refer to status of program operation.
 - A₂₂ to A₁₂ are don't care during command sequence unlock cycles.
 - Configuration Register is set to Synchronous mode.
 - Addresses are latched on the first of either the falling edge of \overline{WE} or active edge of CLK. When "twlc" is not met then \overline{AVD} /address set up and hold time to CLK will be required.

Figure 20 Program Operation Timings at Synchronous Mode (\overline{WE} latch)



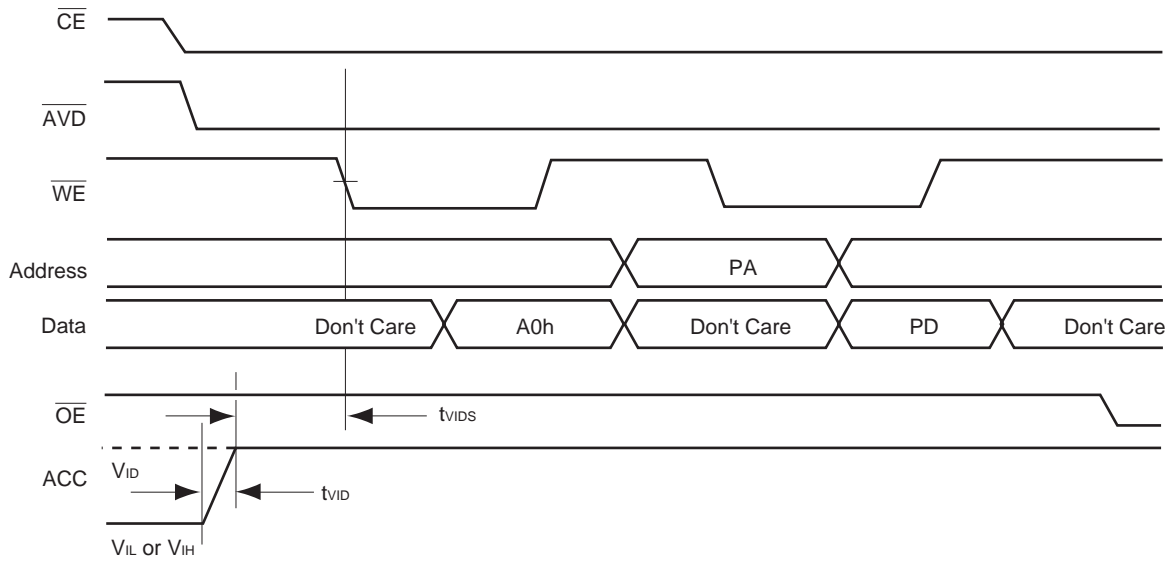
- Notes :
- PA = Program Address, PD = Program Data, VA = Valid Address for reading status bits.
 - "In progress" and "complete" refer to status of program operation.
 - A₂₂ to A₁₂ are don't care during command sequence unlock cycles.
 - Configuration Register is set to Synchronous mode.
 - Addresses are latched on the first of either the active edge of CLK or the rising edge of AVD.

Figure 21 Program Operation Timings at Synchronous Mode (CLK latch)



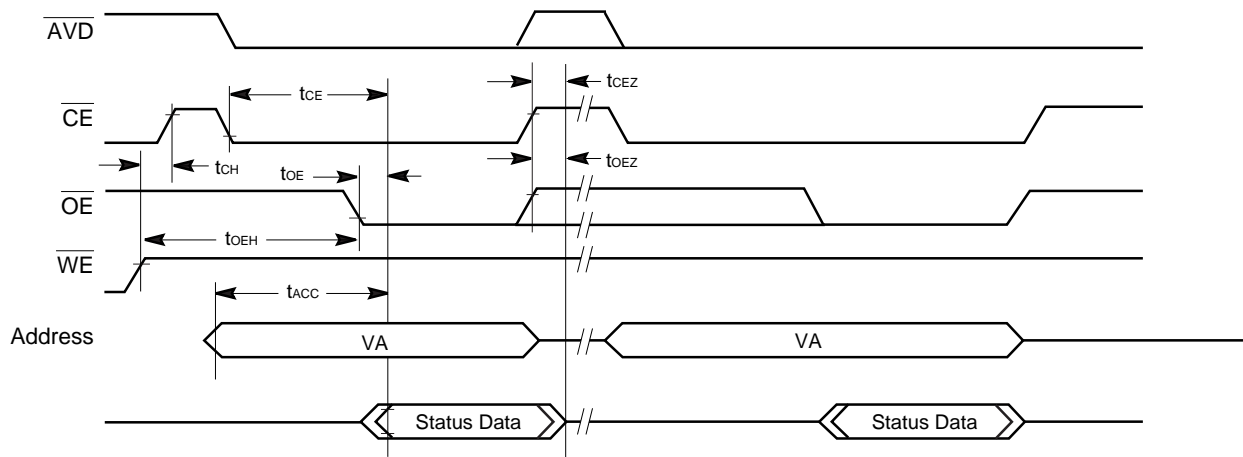
- Notes :
- SA is the sector address for Sector Erase.
 - Address bits A₂₂ to A₁₂ are don't cares during unlock cycles in the command sequence.
 - This timing is for Synchronous mode.

Figure 22 Chip/Sector Erase Command Sequence



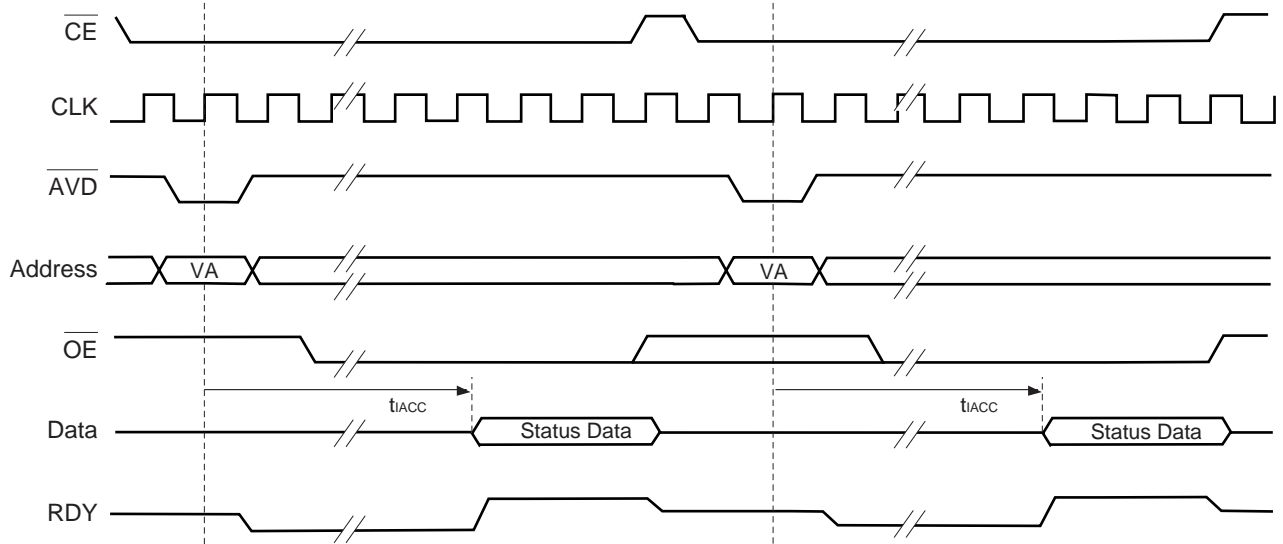
Note : Use setup and hold times from conventional program operation.

Figure 23 Accelerated Fast mode Programming Timing



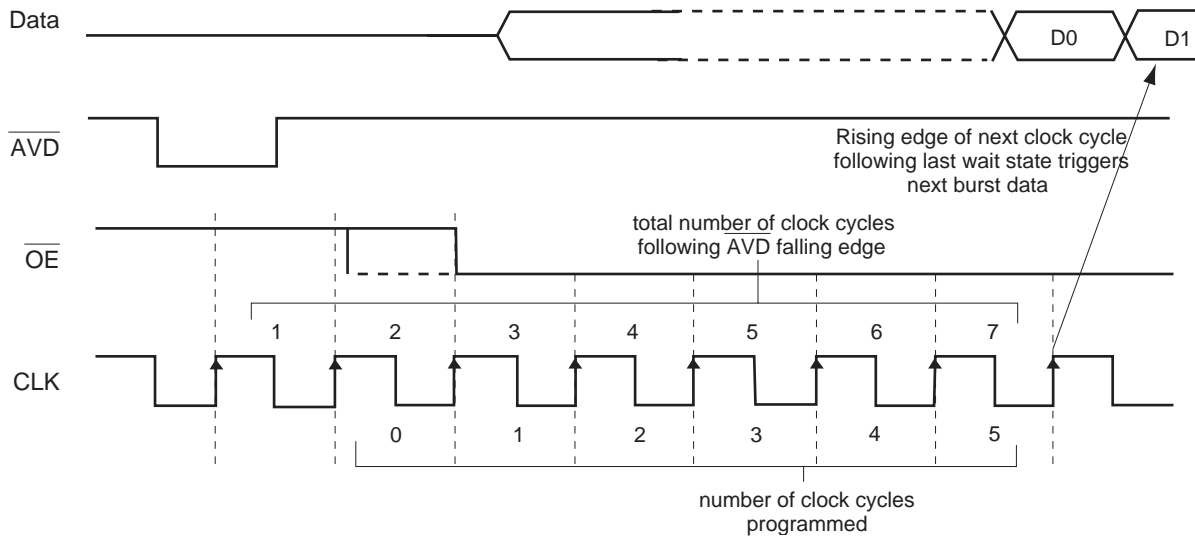
- Notes :
- Status reads in figure are shown as asynchronous mode.
 - VA = Valid Address. Two read cycles are required to determine status. When the Embedded Algorithm operation is complete, and \overline{Data} Polling will output true data and the toggle bits will stop toggling.

Figure 24 \overline{Data} Polling Timings/Toggle Bit Timings (During Embedded Algorithm)



- Notes :
- The timings are similar to synchronous read timings.
 - VA = Valid Address. Two read cycles are required to determine status. When the Embedded Algorithm operation is complete, the toggle bits will stop toggling.
 - RDY is active with data ($A_{18} = 0$ in the Burst Mode Configuration Register).
When $A_{18} = 1$ in the Burst Mode Configuration Register, RDY is active one clock cycle before data.

Figure 25 Synchronous Data Polling Timings/Toggle Bit Timings



Wait State Decoding Addresses:

A₁₄, A₁₃, A₁₂ = "101" ⇒ 5 programmed, 7 total

A₁₄, A₁₃, A₁₂ = "100" ⇒ 4 programmed, 6 total

A₁₄, A₁₃, A₁₂ = "011" ⇒ 3 programmed, 5 total

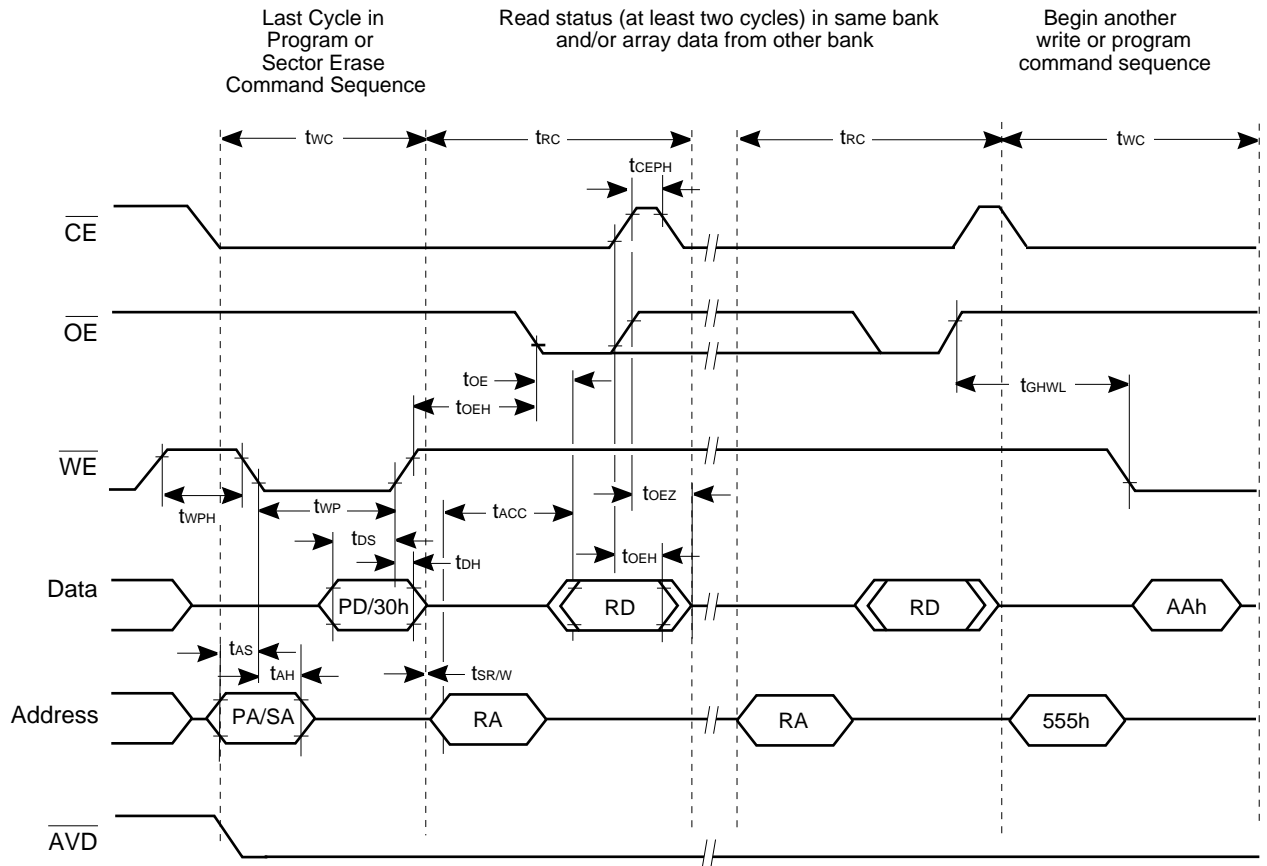
A₁₄, A₁₃, A₁₂ = "010" ⇒ 2 programmed, 4 total

A₁₄, A₁₃, A₁₂ = "001" ⇒ 1 programmed, 3 total

A₁₄, A₁₃, A₁₂ = "000" ⇒ 0 programmed, 2 total

Note : Figure assumes address D0 is not at an address boundary, active clock edge is rising, and wait state is set to "101".

Figure 26 Example of Wait States Insertion (Non-Handshaking Device)



Note : Breakpoints in waveforms indicate that system may alternately read array data from the "non-busy bank" while checking the status of the program or erase operation in the "busy" bank. The system should read status twice to ensure valid information.

Figure 27 Bank-to-Bank Read/Write Cycle Timings

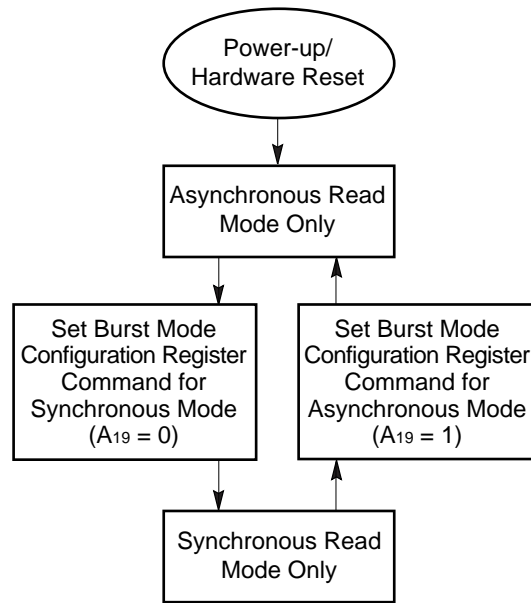
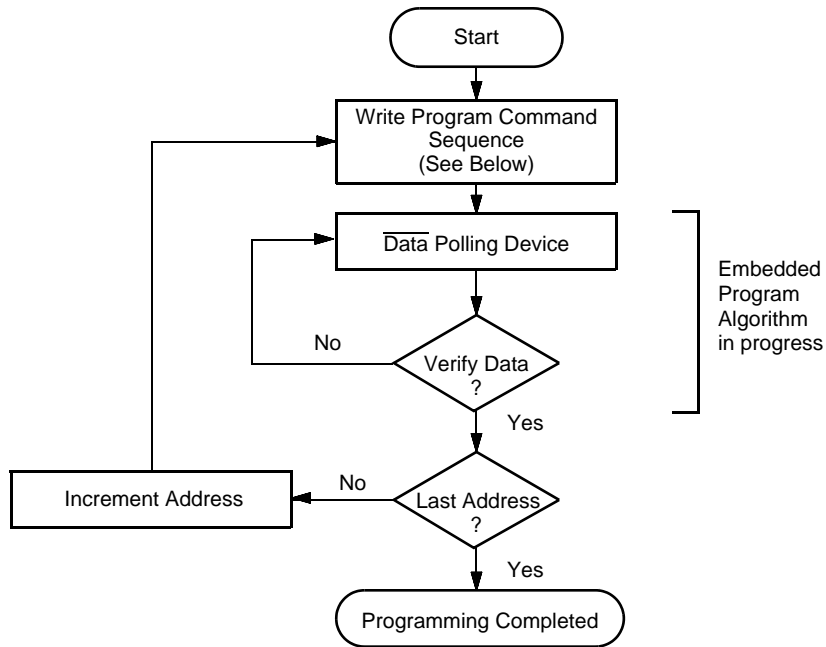


Figure 28 Synchronous/Asynchronous State Diagram

■ FLOW CHART

EMBEDDED ALGORITHM



Program Command Sequence (Address/Command):

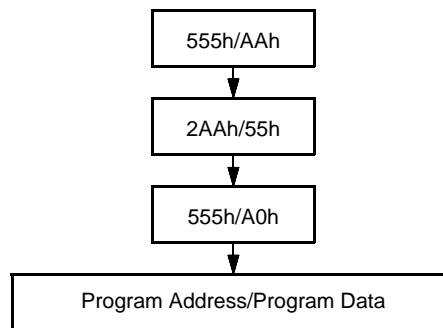
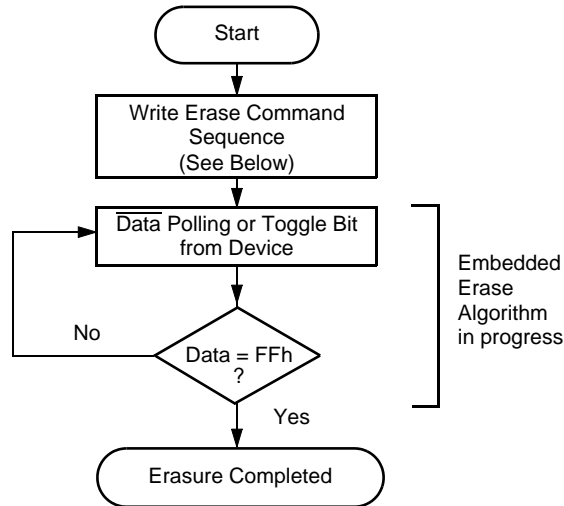
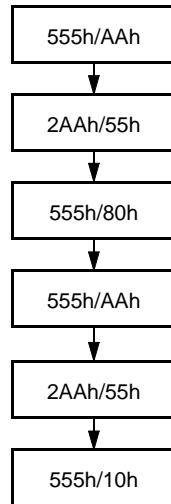


Figure 29 Embedded Program™ Algorithm

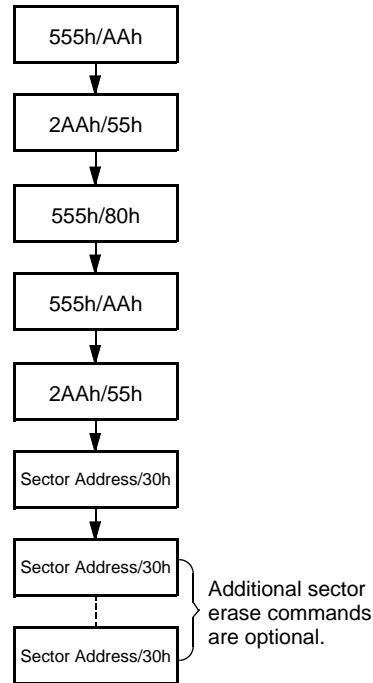
EMBEDDED ALGORITHM



Chip Erase Command Sequence (Address/Command):

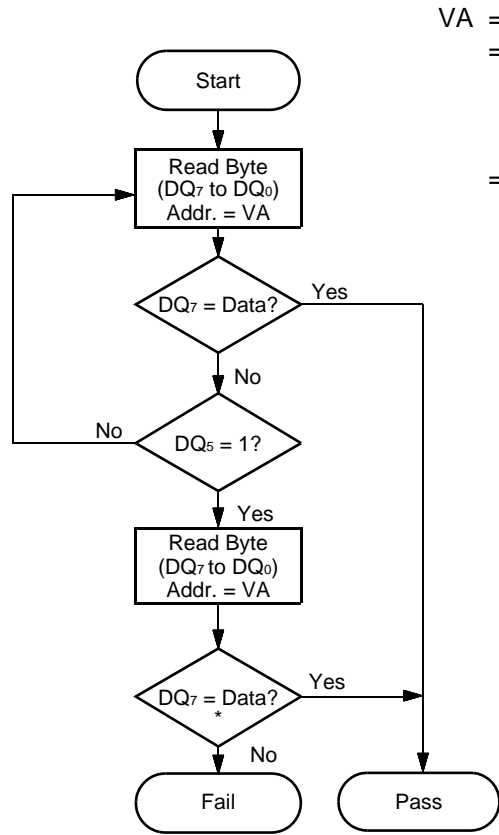


Individual Sector/Multiple Sector Erase Command Sequence (Address/Command):



- Notes :
- See “MBM29BS/FS12DH Command Definitions” in “■ DEVICE BUS OPERATION” for erase command sequence.
 - See the section on DQ₃ for information on the sector erase timer.

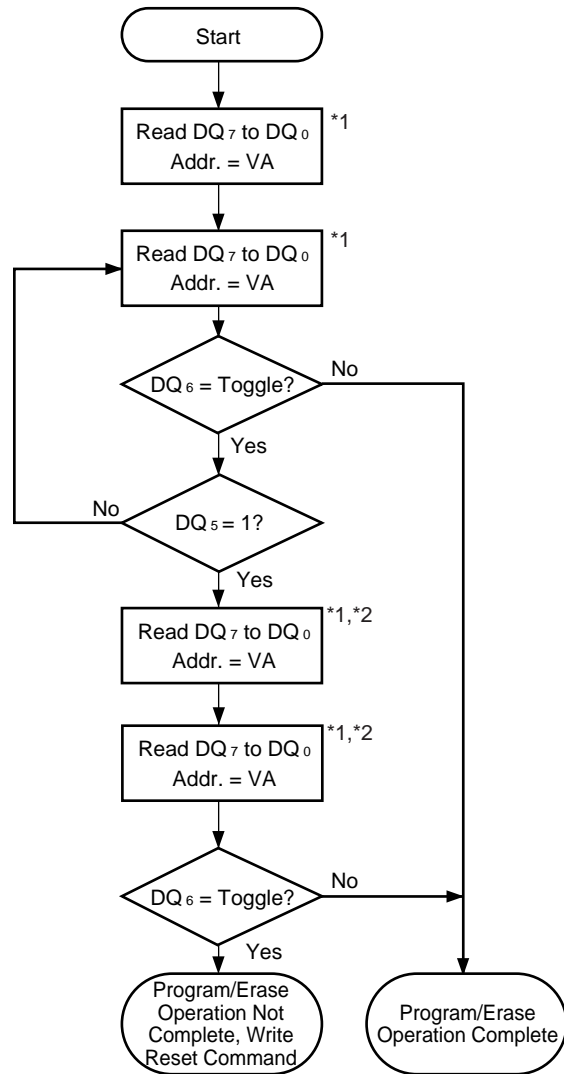
Figure 30 Embedded Erase™ Algorithm



VA = Address for programming
 = Any of the sector addresses within the sector being erased during sector erase or multiple erases operation.
 = Any of the sector addresses within the sector not being protected during sector erase or multiple sector erases operation.

* : DQ₇ is rechecked even if DQ₅ = "1" because DQ₇ may change simultaneously with DQ₅.

Figure 31 Data Polling Algorithm



VA = Bank address being executed
Embedded Algorithm

*1 : Read toggle bit twice to determine whether it is toggling.

*2 : Recheck toggle bit because it may stop toggling as DQ₅ changes to "1".

Figure 32 Toggle Bit Algorithm

FAST MODE ALGORITHM

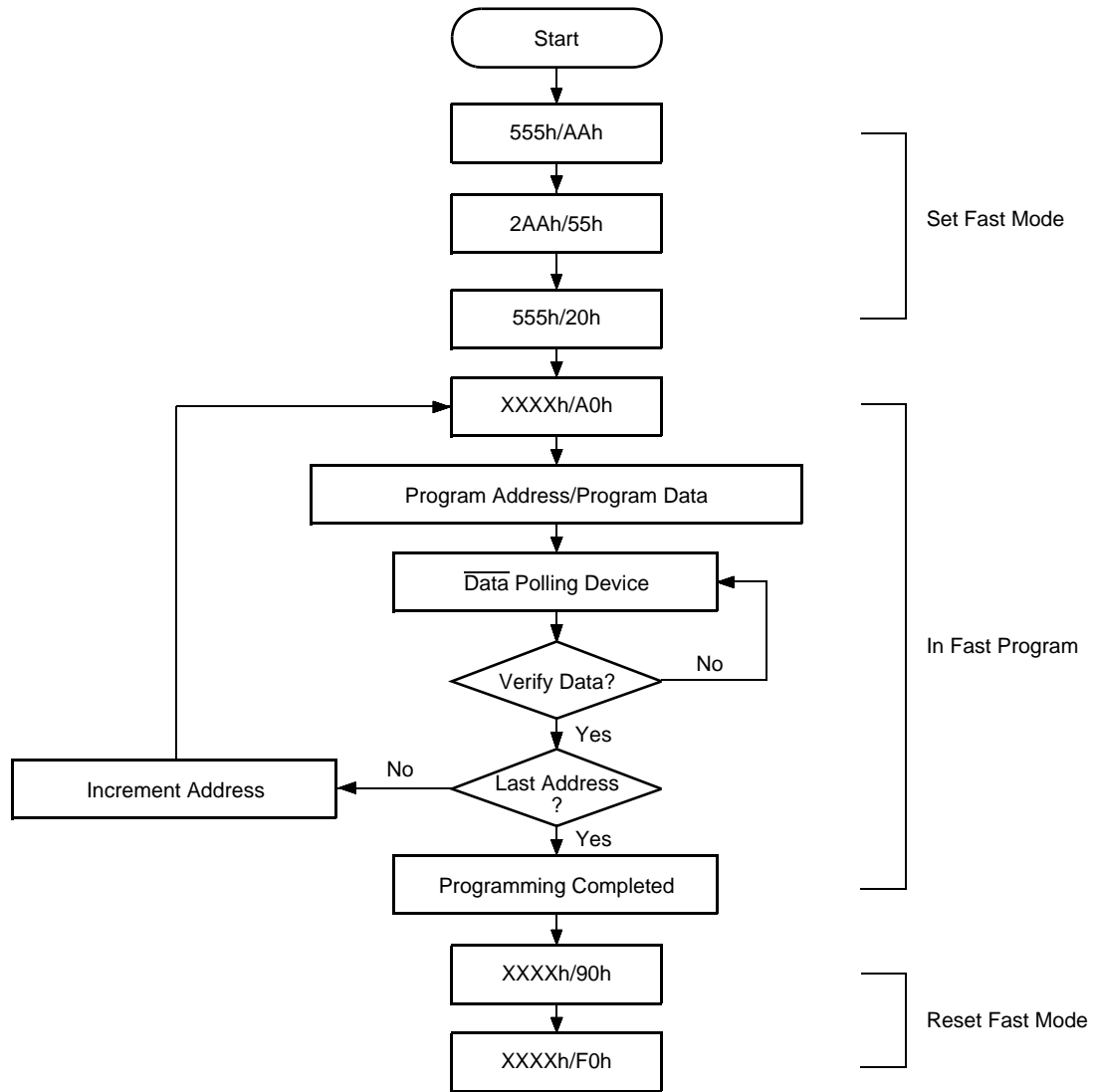
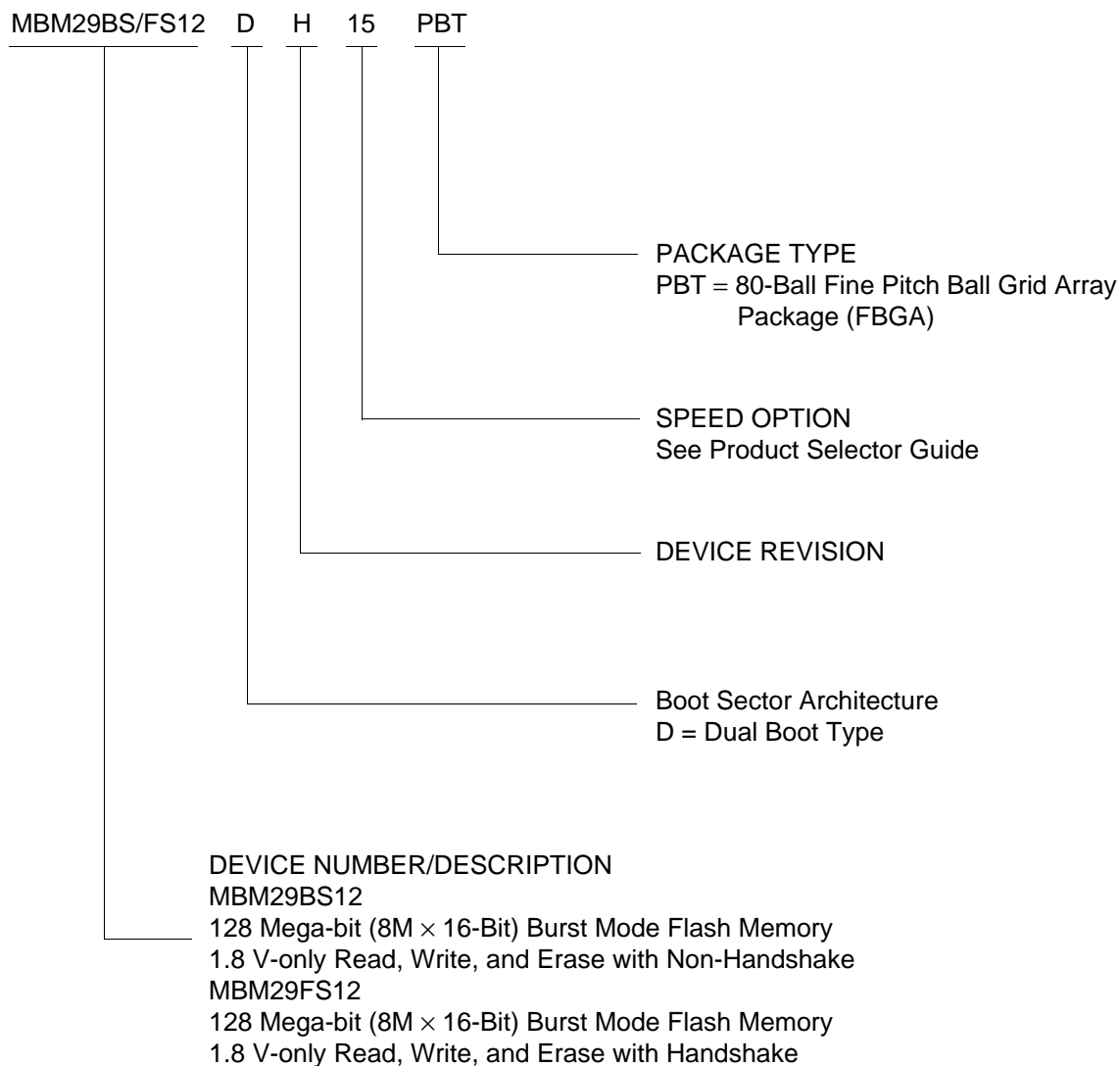


Figure 33 Embedded Programming Algorithm for Fast Mode

MBM29BS/FS12DH₁₅

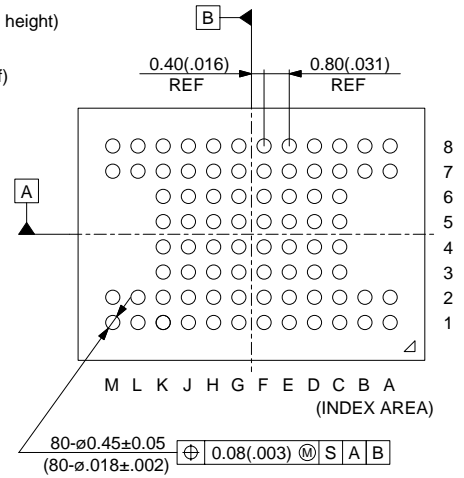
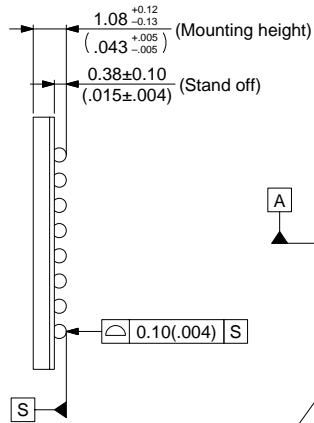
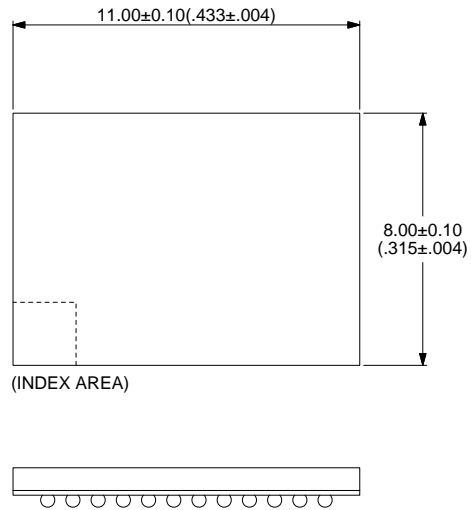
■ ORDERING INFORMATION

Part No.	Package	Access Time(ns)	Remarks
MBM29BS/FS12DH15PBT	80-ball plastic FBGA (BGA-80P-M04)	15	



■ PACKAGE DIMENSIONS

80-ball plastic FBGA
(BGA-80P-M04)



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Dimensions in mm (inches)

Note : The values in parentheses are reference values.

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